

Practitioner's Docket No. U 013399-2

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PATENT TRADEMARK OFFICE

CHAPTER II

**TRANSMITTAL LETTER
TO THE UNITED STATES ELECTED OFFICE (EO/US)**

(ENTRY INTO U.S. NATIONAL PHASE UNDER CHAPTER II)

PCT/IL99/00583 / 2 NOVEMBER 1999 ✓ 2 NOVEMBER 1998 ✓
INTERNATIONAL APPLICATION NO. INTERNATIONAL FILING DATE PRIORITY DATE CLAIMED
APPARATUS AND METHOD FOR FABRICATING FLAT WORKPIECES ✓
TITLE OF INVENTION
1. Doron EIDELMAN; 2. David FISCH; 3. Amir NOY; 4. Avi GROSS ✓
APPLICANT(S)

Box PCT
Assistant Commissioner for Patents
Washington D.C. 20231
ATTENTION: EO/US

NOTE: The completion of those filing requirements that can be made at a time later than 30 months from the priority date

CERTIFICATION UNDER 37 C.F.R. 1.10*
(Express Mail label number is **mandatory**.)
(Express Mail certification is optional.)

I hereby certify that this correspondence and the documents referred to as attached therein are being deposited with the United States Postal Service on this date APRIL 16, 2001, in an envelope as "Express Mail Post Office to Addressee," Mailing Label Number EL728212313US, addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231.

JENNIFER RASHKIN

(type or print name of person mailing paper)

Jennifer Rashkin
Signature of person mailing paper

WARNING: Certificate of mailing (first class) or facsimile transmission procedures of 37 C.F.R. 1.8 cannot be used to obtain a date of mailing or transmission for this correspondence.

***WARNING:** Each paper or fee filed by "Express Mail" **must** have the number of the "Express Mail" mailing label placed thereon prior to mailing. 37 C.F.R. 1.10(b).
"Since the filing of correspondence under § 1.10 without the Express Mail mailing label thereon is an oversight that can be avoided by the exercise of reasonable care, requests for waiver of this requirement will **not** be granted on petition." Notice of Oct. 24, 1996, 60 Fed. Reg. 56,439, at 56,442.

(Transmittal Letter to the United States Elected Office (EO/US)—page 1 of 8) **13-18**

EL728212313US

results from the Commissioner exercising his judgment under the authority granted under 35 USC 371(d). The filing receipt will show the actual date of receipt of the last item completing the entry into the national phase. See 37 C.F.R. §1.491 which states: "An international application enters the national state when the applicant has filed the documents and fees required by 35 USC 371(c) within the periods set forth in § 1.494 and § 1.495."

WARNING:

Where the items are those which can be submitted to complete the entry of the international application into the national phase are subsequent to 30 months from the priority date the application is still considered to be in the international state and if mailing procedures are utilized to obtain a date the express mail procedure of 37 C.F.R. §1.10 must be used (since international application papers are not covered by an ordinary certificate of mailing - See 37 C.F.R. §1.8.

NOTE: Documents and fees must be clearly identified as a submission to enter the national state under 35 USC 371 otherwise the submission will be considered as being made under 35 USC 111. 37 C.F.R. § 1.494(f).

1. Applicant herewith submits to the United States Elected Office (EO/US) the following items under 35 U.S.C. 371:
 - a. ☒ This express request to immediately begin national examination procedures (35 U.S.C. 371(f)).
 - b. ☒ The U.S. National Fee (35 U.S.C. 371(c)(1)) and other fees (37 C.F.R. § 1.492) as indicated below:

2.Fees

CLAIMS FEE	(1) FOR	(2) NUMBER FILED	(3) NUMBER EXTRA	(4) RATE	(5) CALCULATIONS
[X]*	TOTAL CLAIMS	39- 20 =	19	x \$ 18.00 =	\$ 342.00
	INDEPENDENT CLAIMS	3- 3 =		x \$ 80.00 =	
	MULTIPLE DEPENDENT CLAIM(S) (if applicable) + \$270.00				
BASIC FEE**	<input type="checkbox"/> U.S. PTO WAS INTERNATIONAL PRELIMINARY EXAMINATION AUTHORITY Where an International preliminary examination fee as set forth in § 1.482 has been paid on the international application to the U.S. PTO: <input type="checkbox"/> and the international preliminary examination report states that the criteria of novelty, inventive step (non-obviousness) and industrial activity, as defined in PCT Article 33(2) to (4) have been satisfied for all the claims presented in the application entering the national stage (37 CFR 1.492(a)(4)) \$100.00 <input type="checkbox"/> and the above requirements are not met (37 CFR 1.492(a)(1)) \$690.00				
	<input checked="" type="checkbox"/> U.S. PTO WAS NOT INTERNATIONAL PRELIMINARY EXAMINATION AUTHORITY Where no international preliminary examination fee as set forth in § 1.482 has been paid to the U.S. PTO, and payment of an international search fee as set forth in § 1.445(a)(2) to the U.S. PTO: <input type="checkbox"/> has been paid (37 CFR 1.492(a)(2)) \$710.00 <input type="checkbox"/> has not been paid (37 CFR 1.492(a)(3)) \$1,000.00 <input checked="" type="checkbox"/> where a search report on the international application has been prepared by the European Patent Office or the Japanese Patent Office (37 CFR 1.492(a)(5)) \$860.00				
SMALL ENTITY	Total of above Calculations				=1202.00
	Reduction by ½ for filing by small entity, if applicable. Affidavit must be filed. (note 37 CFR 1.9, 1.27, 1.28)				-
	Subtotal				\$1202.00
	Total National Fee				\$1202.00
	Fee for recording the enclosed assignment document \$40.00 (37 CFR 1.21(h)). (See Item 13 below). See attached "ASSIGNMENT COVER SHEET".				
TOTAL	Total Fees enclosed				\$1202.00

*See attached Preliminary Amendment Reducing the Number of Claims.

- i. ☒ A check in the amount of \$1202.00 to cover the above fees is enclosed.
 ii. ☐ Please charge Account No. _____ in the amount of \$ _____.
 A duplicate copy of this sheet is enclosed.

****WARNING:** "To avoid abandonment of the application the applicant shall furnish to the United States Patent and Trademark Office not later than the expiration of 30 months from the priority date: * * * (2) the basic national fee (see § 1.492(a)). The 30-month time limit may not be extended." 37 C.F.R. § 1.495(b).

WARNING: If the translation of the international application and/or the oath or declaration have not been submitted by the applicant within thirty (30) months from the priority date, such requirements may be met within a time period set by the Office. 37 C.F.R. § 1.495(b)(2). The payment of the surcharge set forth in § 1.492(e) is required as a condition for accepting the oath or declaration later than thirty (30) months after the priority date. The payment of the processing fee set forth in § 1.492(f) is required for acceptance of an English translation later than thirty (30) months after the priority date. Failure to comply with these requirements will result in abandonment of the application. The provisions of § 1.136 apply to the period which is set. Notice of Jan. 3, 1993, 1147 O.G. 29 to 40.

3. ☒ A copy of the International application as filed (35 U.S.C. 371(c)(2)):

NOTE: Section 1.495 (b) was amended to require that the basic national fee and a copy of the international application must be filed with the Office by 30 months from the priority date to avoid abandonment "The International Bureau normally provides the copy of the international application to the Office in accordance with PCT Article 20. At the same time, the International Bureau notifies applicant of the communication to the Office. In accordance with PCT Rule 47.1, that notice shall be accepted by all designated offices as conclusive evidence that the communication has duly taken place. Thus, if the applicant desires to enter the national stage, the applicant normally need only check to be sure the notice from the International Bureau has been received and then pay the basic national fee by 30 months from the priority date." Notice of Jan. 7, 1993, 1147 O.G. 29 to 40, at 35-36. See item 14c below.

- a. ☐ is transmitted herewith.
 b. ☐ is not required, as the application was filed with the United States Receiving Office.
 c. ☒ has been transmitted
 i. ☒ by the International Bureau.
 Date of mailing of the application (from form PCT/IB/308): _____.
 ii. ☐ by applicant on _____ Date

4. ☒ A translation of the International application into the English language (35 U.S.C. 371(c)(2)):
 a. ☐ is transmitted herewith.
 b. ☒ is not required as the application was filed in English.
 c. ☐ was previously transmitted by applicant on _____ Date
 d. ☐ will follow.

5. ☒ Amendments to the claims of the International application under PCT Article 19 (35 U.S.C. 371(c)(3)):

NOTE: The Notice of January 7, 1993 points out that 37 C.F.R. § 1.495(a) was amended to clarify the existing and continuing practice that PCT Article 19 amendments must be submitted by 30 months from the priority date and this deadline may not be extended. The Notice further advises that: "The failure to do so will not result in loss of the subject matter of the PCT Article 19 amendments. Applicant may submit that subject matter in a preliminary amendment filed under section 1.121. In many cases, filing an amendment under section 1.121 is preferable since grammatical or idiomatic errors may be corrected." 1147 O.G. 29-40, at 36.

- a. ☐ are transmitted herewith.
b. ☐ have been transmitted
i. ☐ by the International Bureau.
Date of mailing of the amendment (from form PCT/IB/308): _____.
ii. ☐ by applicant on _____.
Date
c. ☒ have not been transmitted as
i. ☒ applicant chose not to make amendments under PCT Article 19.
Date of mailing of Search Report (from form PCT/ISA/210): June 5, 2000.
ii. ☐ the time limit for the submission of amendments has not yet expired.
The amendments or a statement that amendments have not been made will be transmitted before the expiration of the time limit under PCT Rule 46.1.

6. ☒ A translation of the amendments to the claims under PCT Article 19 (38 U.S.C. 371(c)(3)):

- a. ☐ is transmitted herewith.
b. ☐ is not required as the amendments were made in the English language.
c. ☒ has not been transmitted for reasons indicated at point 5(c) above.

7. ☒ A copy of the international examination report (PCT/IPEA/409)

- ☒ is transmitted herewith.
☐ is not required as the application was filed with the United States Receiving Office.

8. ☐ Annex(es) to the international preliminary examination report

- a. ☐ is/are transmitted herewith.
b. ☐ is/are not required as the application was filed with the United States Receiving Office.

9. ☐ A translation of the annexes to the international preliminary examination report

- a. ☐ is transmitted herewith.
b. ☐ is not required as the annexes are in the English language.

10. ☒ An oath or declaration of the inventor (35 U.S.C. 371(c)(4)) complying with 35 U.S.C. 115
- a. ☐ was previously submitted by applicant on _____.
Date
- b. ☐ is submitted herewith, and such oath or declaration
- i. ☐ is attached to the application.
- ii. ☐ identifies the application and any amendments under PCT Article 19 that were transmitted as stated in points 3(b) or 3(c) and 5(b); and states that they were reviewed by the inventor as required by 37 C.F.R. 1.70.
- c. ☒ will follow.

Other document(s) or information included:

11. ☒ An International Search Report (PCT/ISA/210) or Declaration under PCT Article 17(2)(a):
- a. ☒ is transmitted herewith.
- b. ☐ has been transmitted by the International Bureau.
Date of mailing (from form PCT/IB/308): _____.
- c. ☐ is not required, as the application was searched by the United States International Searching Authority.
- d. ☐ will be transmitted promptly upon request.
- e. ☐ has been submitted by applicant on _____.
Date
12. ☒ An Information Disclosure Statement under 37 C.F.R. 1.97 and 1.98:
- a. ☐ is transmitted herewith.
Also transmitted herewith is/are:
☐ Form PTO-1449 (PTO/SB/08A and 08B).
☐ Copies of citations listed.
- b. ☒ will be transmitted within THREE MONTHS of the date of submission of requirements under 35 U.S.C. 371(c).
- c. ☐ was previously submitted by applicant on _____.
Date
13. ☐ An assignment document is transmitted herewith for recording.

A separate ☐ "COVER SHEET FOR ASSIGNMENT (DOCUMENT) ACCOMPANYING NEW PATENT APPLICATION" or ☐ FORM PTO 1595 is also attached.

14. ☒ Additional documents:
- a. ☐ Copy of request (PCT/RO/101)
 - b. ☒ International Publication No. WO 00/26645
 - i. ☒ Specification, claims and drawing
 - ii. ☐ Front page only
 - c. ☒ Preliminary amendment (37 C.F.R. § 1.121)
 - d. ☐ Other
- _____
- _____
- _____
15. ☒ The above checked items are being transmitted
- a. ☒ before 30 months from any claimed priority date.
 - b. ☐ after 30 months.
16. ☐ Certain requirements under 35 U.S.C. 371 were previously submitted by the applicant on _____, namely:
- _____
- _____
- _____

AUTHORIZATION TO CHARGE ADDITIONAL FEES

WARNING: *Accurately count claims, especially multiple dependent claims, to avoid unexpected high charges if extra claims are authorized.*

NOTE: *"A written request may be submitted in an application that is an authorization to treat any concurrent or future reply, requiring a petition for an extension of time under this paragraph for its timely submission, as incorporating a petition for extension of time for the appropriate length of time. An authorization to charge all required fees, fees under § 1.17, or all required extension of time fees will be treated as a constructive petition for an extension of time in any concurrent or future reply requiring a petition for an extension of time under this paragraph for its timely submission. Submission of the fee set forth in § 1.17(a) will also be treated as a constructive petition for an extension of time in any concurrent reply requiring a petition for an extension of time under this paragraph for its timely submission." 37 C.F.R. § 1.136(a)(3).*

NOTE: *"Amounts of twenty-five dollars or less will not be returned unless specifically requested within a reasonable time, nor will the payer be notified of such amounts; amounts over twenty-five dollars may be returned by check or, if requested, by credit to a deposit account." 37 C.F.R. § 1.26(a).*

☒ The Commissioner is hereby authorized to charge the following additional fees that may be required by this paper and during the entire pendency of this application to Account No. 12-0425.

☒ 37 C.F.R. 1.492(a)(1), (2), (3), and (4) (filing fees)

WARNING: *Because failure to pay the national fee within 30 months without extension (37 C.F.R. § 1.495(b)(2)) results in abandonment of the application, it would be best to always check the above box.*

☐ 37 C.F.R. 1.492(b), (c) and (d) (presentation of extra claims)

NOTE: *Because additional fees for excess or multiple dependent claims not paid on filing or on later presentation must*

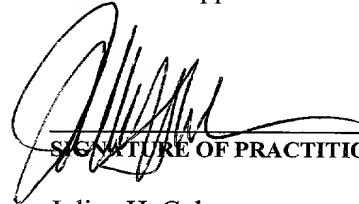
only be paid or these claims cancelled by amendment prior to the expiration of the time period set for response by the PTO in any notice of fee deficiency (37 C.F.R. § 1.492(d)), it might be best not to authorize the PTO to charge additional claim fees, except possible when dealing with amendments after final action.

- ☒ 37 C.F.R. 1.17 (application processing fees)
☒ 37 C.F.R. 1.17(a)(1)-(5)(extension fees pursuant to § 1.136(a).
☒ 37 C.F.R. 1.18 (issue fee at or before mailing of Notice of Allowance, pursuant to 37 C.F.R. 1.311(b))

NOTE: Where an authorization to charge the issue fee to a deposit account has been filed before the mailing of a Notice of Allowance, the issue fee will be automatically charged to the deposit account at the time of mailing the notice of allowance. 37 C.F.R. § 1.311(b).

NOTE: 37 C.F.R. 1.28(b) requires "Notification of any change in loss of entitlement to small entity status must be filed in the application . . . prior to paying, or at the time of paying . . . issue fee." From the wording of 37 C.F.R. § 1.28(b): (a) notification of change of status must be made even if the fee is paid as "other than a small entity" and (b) no notification is required if the change is to another small entity.

- ☐ 37 C.F.R. § 1.492(e) and (f) (surcharge fees for filing the declaration and/or filing an English translation of an International Application later than 30 months after the priority date).



SIGNATURE OF PRACTITIONER

Julian H. Cohen
(type or print name of practitioner)

Reg. No.: 20,302

Tel. No.: (212) 708-1887

P.O. Address

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c/o Ladas & Parry
26 West 61st Street
New York, N.Y. 10023

Practitioner's Docket No. U 013399-2**CHAPTER II****IN THE UNITED STATES ELECTED OFFICE (EO/US)**

PCT/IL99/00583	2 NOVEMBER 1999	2 NOVEMBER 1998
INTERNATIONAL APPLICATION NO.	INTERNATIONAL FILING DATE	PRIORITY DATE CLAIMED
APPARATUS AND METHOD FOR FABRICATING FLAT WORKPIECES		
TITLE OF INVENTION		
1. Doron EIDELMAN; 2. David FISCH; 3. Amir NOY; 4. Avi GROSS		
APPLICANT(S)		

Box PCT
Assistant Commissioner for Patents
Washington, D.C. 20231
ATTENTION: EO/US

PRELIMINARY AMENDMENT

Please amend the above identified application as follows:

IN THE CLAIMS :

Please cancel claims 14-15, 32-34, 40-41, and 43-69.

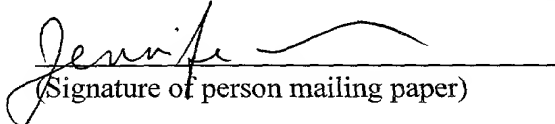
Please amend claims 2-5, 7, 9, 21, 24-25, 27-30, 35, 42, and 72 as follows:

CERTIFICATE UNDER 37 1.10

I hereby certify that this paper is being deposited with the United States Postal Service on this date APRIL 16, 2001 in an envelope as "EXPRESS MAIL POST OFFICE TO ADDRESSEE" Mailing Label Number EL728212313US addressed to the: Assistant Commissioner for Patents, Washington, D.C. 20231

JENNIFER RASHKIN

(Type or print name of person mailing paper)


(Signature of person mailing paper)

NOTE: Each paper or fee referred to as enclosed herein has the number of the "EXPRESS MAIL" mailing label place thereon prior to mailing 37 CFR 1.16(b).

2. (Amended) A system for manufacture of flat panel displays according to claim 1 and wherein the first controlled environment is an airborne particle controlled environment having a first level of controlled airborne particulate contamination, and the second controlled environment is an airborne particle controlled environment having a second level of controlled airborne particulate contamination that is less than the first level of controlled airborne particulate contamination.

3. (Amended) A system for manufacture of flat panel displays according to claim 1 and wherein said plurality of optical inspection devices are operative in coordination with said plurality of manufacturing devices for inspecting said substrates prior to transfer thereof out of said second controlled airborne particle contamination environment.

4. (Amended) A system for manufacture of flat panel displays according to claim 1 and wherein at least some of said plurality of optical inspection devices comprise non-scanning sensors.

5. (Amended) A system for manufacture of flat panel displays according to claim 4 and wherein said plurality of optical inspection devices are operative to identify fabrication process defects occurring during production of flat panel display substrates.

7. (Amended) A system for manufacture of flat panel displays according to claim 1 and wherein each of said plurality of optical inspection devices includes at least one non-scanning sensor which views substantially all of the surface of said substrate.

9. (Amended) A system for manufacture of flat panel displays according to claim 1 and wherein each of said plurality of optical inspection devices comprises an illuminating array operative to provide various combinations of illumination.

21. (Amended) An inspection system according to claim 17 and also comprising a

spatially positionable stage to support the flat panel display substrate, wherein the stage spatially positions the substrate at various angles relative to the illumination subsystem.

24. (Amended) An inspection system according to claim 22 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the flat panel display substrate such that a zero'th order of diffraction impinges on the non-scanning optical array.

25. (Amended) An inspection according to claim 22 and wherein the optical array the illumination subsystem and the stage are configured and arranged to additionally enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

27. (Amended) An inspection system according to claim 21 and also comprising an image analyzer receiving an output from said non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

28. (Amended) An inspection system according to claim 17 and wherein said optical array views substantially all of a surface of said substrate.

29. (Amended) An inspection system according to claim 17 and wherein said optical array views only part of a surface of said substrate.

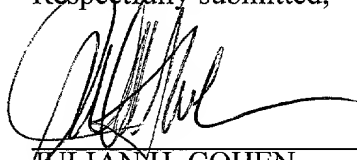
30. (Amended) An inspection system according to claim 17 and wherein said optical array acquires at least one image of said substrate for each of a plurality of different illuminations.

35. (Amended) An inspection system according to claim 17 and also comprising a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

42. (Amended) An inspection system according to claim 17 and comprising an adjustable mounting assembly for selectable determining at least one of relative inclination, spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said substrate.

72. (Amended) Apparatus for optically inspecting the surface of an article according to claim 70, wherein the image analysis subsystem is operative to identify anomalies that are substantially at least as large as the resolution of the camera.

Respectfully submitted,



JULIAN H. COHEN
LADAS & PARRY
26 WEST 61ST STREET
NEW YORK, NEW YORK 10023
REG.NO.20,302 (212)708-1887

2. (Amended) A system for manufacture of flat panel displays ~~comprising according to claim 1 and~~ wherein the first controlled environment is an airborne particle controlled environment having a first level of controlled airborne particulate contamination, and the second controlled environment is an airborne particle controlled environment having a second level of controlled airborne particulate contamination that is less than the first level of controlled airborne particulate contamination.

3. (Amended) A system for manufacture of flat panel displays according to claim 1 ~~or claim 2~~ and wherein said plurality of optical inspection devices are operative in coordination with said plurality of manufacturing devices for inspecting said substrates prior to transfer thereof out of said second controlled airborne particle contamination environment.

4. (Amended) A system for manufacture of flat panel displays according to ~~either of the preceding claims 1~~ and wherein at least some of said plurality of optical inspection devices comprise non-scanning sensors.

5. (Amended) A system for manufacture of flat panel displays according to ~~any of the preceding claims 4~~ and wherein said plurality of optical inspection devices are operative to identify fabrication process defects occurring during production of flat panel display substrates.

7. (Amended) A system for manufacture of flat panel displays according to ~~any of the preceding claims 1~~ and wherein each of said plurality of optical inspection devices includes at least one non-scanning sensor which views substantially all of the surface of said substrate.

9. (Amended) A system for manufacture of flat panel displays according to ~~any of the preceding claims 1~~ and wherein each of said plurality of optical inspection devices comprises an illuminating array operative to provide various combinations of illumination.

21. (Amended) An inspection system according to ~~any of claims 17-20~~ and also comprising a spatially positionable stage to support the flat panel display substrate, wherein the stage

spatially positions the substrate at various angles relative to the illumination subsystem.

24. (Amended) An inspection system according to either of claims 22 and 23 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the flat panel display substrate such that a zero'th order of diffraction impinges on the non-scanning optical array.

25. (Amended) An inspection according to any of claims 22-24 and wherein the optical array the illumination subsystem and the stage are configured and arranged to additionally enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

27. (Amended) An inspection system according to any of claims 21-26 21 and also comprising an image analyzer receiving an output from said non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

28. (Amended) An inspection system according to any of claims 17-18 and wherein said optical array views substantially all of a surface of said substrate.

29. (Amended) An inspection system according to any of claims 17-18 and wherein said optical array views only part of a surface of said substrate.

30. (Amended) An inspection system according to any of claims 17-29 and wherein said optical array acquires at least one image of said substrate for each of a plurality of different illuminations.

35. (Amended) An inspection system according to any of claims 17-21 and also comprising a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

42. (Amended) An inspection system according to any of claims 17-41 and comprising an adjustable mounting assembly for selectable determining at least one of relative inclination, spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said substrate.

72. (Amended) Apparatus for optically inspecting the surface of an article according to any of claims 70-73, wherein the image analysis subsystem is operative to identify anomalies that are substantially at least as large as the resolution of the camera.

13 Rec'd PCT/PTO 16 JUL 2001

09/807680

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Doron EIDELMAN, et al.

Serial No.: 09/807,680

Group No.: --

Filed: April 16, 2001

Examiner: Alvarado

For: APPARATUS AND METHOD FOR FABRICATING
FLAT WORKPIECES

Attorney Docket No.: U 013399-2

Assistant Commissioner of Patents
Washington, D.C. 20231

Sir:

FACSIMILE NO.: 703-305-3230

NO. OF PAGES: 3

ATTN: Examiner Alvarado

SUPPLEMENTAL PRELIMINARY AMENDMENT

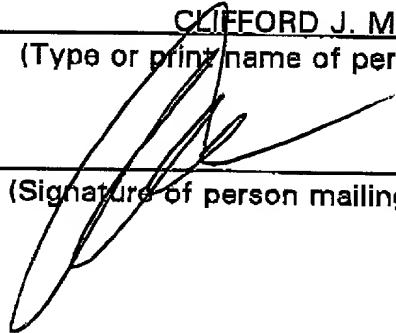
Supplemental to the Preliminary Amendment dated April 16, 2001, please
further amend the application as follows:

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being
attached, enclosed or transmitted) is being facsimile transmitted to the Patent
and Trademark Office on the date shown below:

Date: July 16, 2001

CLIFFORD J. MASS
(Type or print name of person mailing paper)


(Signature of person mailing paper)

13 Rec'd PCT/PTO 16 JUL 2001

09/807680

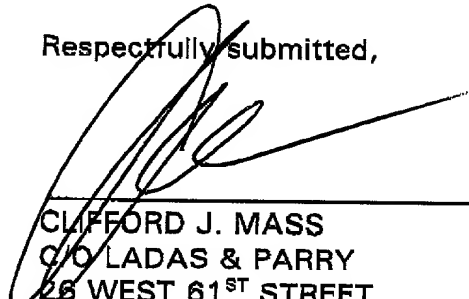
IN THE CLAIMS

Please cancel claims 73-179.

REMARKS

The courtesy of Examiner Alvarado in discussing this case with the undersigned on July 16, 2001, is gratefully acknowledged. The above amendatory action removes the need to pay any excess claim fees whereby Applicants have fully responded to the Notification of Missing Requirements mailed 18 May 2001.

Respectfully submitted,


CLIFFORD J. MASS
C/O LADAS & PARRY
26 WEST 61ST STREET
NEW YORK, N.Y. 10023
REG. NO. 30086 - 212-708-1890

APPARATUS AND METHOD
FOR FABRICATING FLAT WORKPIECES

Field of Invention

5 The present invention relates to the fabrication and inspection of flat workpieces in general and more particularly to the fabrication and inspection of flat articles such as flat panel display screens (FPDs) for computers, television and other suitable applications.

Background of the Invention

10 Flat panel visual displays such as liquid crystal displays (LCDs) are becoming increasingly popular for use in computer and television screens. However their cost remains high, in part, due to relatively low manufacturing yields.

15 There exist various well known techniques for FPD fabrication. Most of these techniques comprise a multi-step photolithographic process in which various thin films and photo-sensitive protective photoresist coatings are applied in turn to a glass substrate. The thin films may be metallic, non-metallic dielectric or the like depending on the particular process step. The photoresist coatings are selectively exposed, typically to UV light, developed and selectively washed away from the substrate. The thin films are etched to selectively remove regions not protected by residual photoresist. Repetition of this process deposits on the substrate a multi-layered matrix structure of metal connectors, thin film
20 transistors, optical filters such as polarizers, and individually controllable liquid crystal cells.

25 Various steps in the FPD fabrication process are highly sensitive to airborne and other impurities as well as to process defects. Unfiltered air typically contains many millions of airborne particles, such as dust, per cubic meter. Conventional FPD fabrication techniques require that the maximum level of airborne particulate concentration range between 10 - 100 particles per cubic meter, depending on the sensitivity of the given process step. Consequently, FPDs are typically fabricated in environments containing highly filtered air thus providing reduced contamination by airborne particles.

 FPD fabrication facilities are typically situated in so-called "clean rooms" in which the ambient air is filtered to maintain a level of airborne particulate contamination which is at the

upper end of the above-mentioned concentration range, typically at a concentration level of less than 100 airborne particles per cubic meter. This level of particulate contamination is insufficiently low for some fabrication steps. However, it is generally impracticable, because of cost and limitations on human access, to maintain large volumes of air in a clean room at the low levels of airborne particulate concentration required for such extremely contamination-sensitive fabrication steps. Consequently, FPD fabrication equipment performing steps requiring an even lower level of airborne particulate concentration typically includes a self-contained ultra clean micro-environment in which a required low level of airborne particulate concentration is maintained. Other types of FPD fabrication equipment define a micro-environment which may not differ from those of the clean room in terms of its airborne particulate concentration, but which differs in other characteristics.

In a typical FPD fabrication facility, human attendants are permitted into the clean room facilities having maximum concentration levels as low as 100 particles per cubic meter, however the attendants must be suitably dressed in protective clothing. Human attendants, even in suitable dress, typically can not access self-contained micro environments of fabrication equipment during operation thereof. Consequently, fabrication equipment operating is typically fully automated and is operational without human intervention.

It is well known to inspect FPD substrates during and following fabrication. Conventional automated inspection techniques are directed to ascertaining the uniformity of a matrix structure deposited on a glass substrate, determining whether dust has been trapped in intermediate matrix layers on the FPD, and ascertaining the performance of completed FPD panels. In addition non-automated human inspection is used to determine the existence of large scale process defects, generally visible to the human eye, such as chemical residues that have not been fully washed away, streaks, scratches and uneven exposure of the photoresist. The present invention relates to inspections of this latter type, namely large scale process defects.

Conventionally, all inspection of FPD substrates is performed in a clean room but outside the self-contained ultra-clean micro environments of the FPD fabrication equipment. A batch of substrates is typically inspected only after a series of process steps is completed. There is often a considerable time delay between the completion of a fabrication process and inspection. In the event of recurring contamination or recurring process flaws, many

conventional automated system for inspecting FPD substrates during fabrication for ascertaining the uniformity of the matrix structure deposited on the glass substrate and determining whether dust has been trapped in intermediate matrix layers thereof, is commercially available from the present assignee, Orbotech Ltd. of Israel, and is designated
5 by catalogue no. LC 3090. Part of this system is described and claimed in U.S. Patent

The existing Orbotech system described above is not normally used for identifying many typical fabrication large scale process defects on FPD substrates because it collects data relating to a matrix structure having dimensions that are orders of magnitude smaller than those of typical process defects. Moreover, because the system scans the substrates, it is
10 physically relatively large, expensive and complex to operate.

Human inspection for process defects is conventionally performed by an operator situated inside the clean room who positions a substrate under a light source to inspect it for undesired residues, streaks, scratches and other relatively large scale anomalies on the substrate. While such inspection can be useful to detect certain large scale fabrication process
15 defects, it takes place outside the self-contained micro environment of contamination-sensitive process equipment and it suffers from the typical high cost and non-standardization associated with non-automated human inspection methods.

Other types of inspection, typified by the disclosure of U.S. Patent 5,771,068, assigned to the present assignee and incorporated herein by reference, are conventionally used to inspect FPDs that are sufficiently completed to enable selective activation of pixels.
20 According to an embodiment described in U.S. Patent 5,771,068, various combinations of pixels are illuminated and a relatively low resolution staring array sensor images the entire substrate as the various combinations are illuminated. The images are analyzed for variations in intensities. This type of inspection is clearly not suitable for inspection FPD substrates in
25 intermediate stages of fabrication.

Additional publications that are believed to be relevant to the art of inspecting for large scale defects and non-conformities on surfaces of articles include U.S. Patent 5,640,237 and Japan Patent Application 11-94753.

Summary of Invention

The present invention seeks to overcome drawbacks of conventional FPD inspection systems and to provide an improved system and method for automated inspection of FPDs and other flat surfaces.

5 The present invention further seeks to provide an FPD manufacturing system having increased yield.

The present invention still further seeks to provide an automated system for inspecting FPDs which is less expensive and more compact in size than conventional automated scanning FPD inspection systems.

10 Additionally the present invention seeks to provide a system operative to inspect FPD substrates inside the self-contained ultra-clean micro environment of equipment performing contamination-sensitive FPD fabrication processes.

One aspect of a preferred embodiment of the invention relates to a system and method for the manufacture of FPDs using contamination-sensitive fabrication equipment
15 having a self-contained micro environment typically, but not necessarily, characterized by an airborne particulate concentration that is substantially lower than that of its surroundings. Automated inspection apparatus is provided inside the self-contained micro environment of the process equipment and FPD substrates are inspected inside the micro environment of the fabrication equipment before transportation to other fabrication equipment to perform a
20 downstream fabrication process.

Another aspect of a preferred embodiment of the invention relates to the inspection of FPD substrates that is performed inside fabrication equipment immediately following the completion of a series of fabrication process steps and before the substrate is transferred to other fabrication equipment to perform a subsequent series of steps. A
25 determination of whether there exist any process defects on the substrate is made in order that the operation of the process equipment that is performing defective steps can be interrupted and corrected before a recurring defect affects subsequent substrates.

Another aspect of a preferred embodiment of the present invention relates to a system and method for FPD fabrication in which FPD substrates are inspected for typical
30 fabrication process defects by an automated system. Preferably, the inspection is performed without comparison to an external reference. Preferably, inspection is provided to detect

typical fabrication process defects including scratches, process residues, uneven exposure of photoresist, uneven deposition of films and contamination by particles embedded in the substrate.

Another aspect of a preferred embodiment of the present invention relates to a system to automatically inspect substantially flat surfaces of industrial articles, such as FPD substrates, for the existence and absence of relatively large scale process defects such as are generally visible to the human eye. Relatively large scale process defects include, by way of example only, in the context of FPD substrate inspection: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

Preferably, various configurations of illumination are applied to a surface under inspection. and for each configuration of illumination an image of an illuminated region on the surface is acquired using a sensor, preferably a staring array CCD sensor.

The types and configurations of illumination used in the context of preferred embodiments of the present invention generally include: Bright Field Illumination, in which a specular reflection of light from the source of illumination impinges on a lens associated with a sensor viewing the object; and Dark Field Illumination in which a specular reflection of light from the source of illumination does not impinge on a lens associated with a sensor viewing the object. Additionally the bright field and dark field illumination respectively may be diffuse or focused.

Thus for example, diffuse substantially bright field illumination or diffuse dark field illumination may be applied. Diffuse substantially bright field illumination refers to illumination in which a diffuse illumination source is used, and the mutual orientation of the surface under inspection, the illumination source and a lens associated with the sensor is such that the specular reflection of at least some of the light from the diffuse source impinges on a lens associated with the sensor. Diffuse dark field illumination refers to illumination in which a diffuse illumination source is used, and the mutual orientation of the surface under inspection, the illumination and a lens associated with the sensor is such that a specular reflection of light from diffuse source does not impinge directly on a lens associated with the sensor.

Additionally, focussed bright field illumination or focussed dark field illumination may be applied. Focussed bright field illumination refers to illumination in which the illumination is focussed to form a beam which is intersected by the surface under inspection, wherein orientation of the surface under inspection, the illumination and the sensor is such that a specular reflection of light from the focussed source impinges on a lens associated with the sensor. Focussed dark field illumination refers to illumination in which illumination is focussed to form a beam which is intersected by the surface under inspection, wherein orientation of the surface under inspection, the illumination and the sensor is such that a specular reflection of light from the focussed source does not impinge on a lens associated with the sensor.

It is appreciated that the surfaces of some articles inspected, for example FPDs, may include a periodic spatial feature that forms a diffraction grating. In the context of inspecting surfaces having such a periodic spatial feature, focussed dark field illumination is further categorized into on-axis and off-axis focussed dark field illumination. Focussed on-axis dark field illumination refers to focussed dark field illumination in which the illumination source, the surface under inspection and the sensor are oriented such that the zero'th, or central, order of diffraction does not impinge on a lens associated with the sensor, however some other non-zero'th order of diffraction impinges on a lens associated with the sensor. Focussed off-axis dark field illumination refers to focussed dark field illumination in which the illumination source, the surface under inspection and the sensor are oriented such that no orders of diffraction impinge on a lens associated with the sensor, preferably because mutual axes along which diffraction orders converge are all outside the lens associated with the sensor.

Another aspect of a preferred embodiment of the present invention relates to a system to inspect coatings applied to substantially flat surfaces of industrial objects, in which the coatings are applied, and subsequently inspected in using the apparatus and methods of the present invention.

There is thus provided in accordance with a preferred embodiment of the present invention a system for manufacture of flat panel displays including a plurality of manufacturing devices located in a first controlled environment, at least some of the plurality of manufacturing devices each including an enclosure defining a second controlled

environment different from the first controlled environment, and a plurality of optical inspection devices operative to inspect flat panel display substrates at various stages of the production thereof by the plurality of manufacturing devices, at least some of the plurality of optical inspection devices being located within the enclosures defining the second controlled environments.

Preferably the first controlled environment is an airborne particle controlled environment having a first level of controlled airborne particulate contamination, and the second controlled environment is an airborne particle controlled environment having a second level of controlled airborne particulate contamination that is less than the first level of controlled airborne particulate contamination.

Further in accordance with a preferred embodiment of the present invention the plurality of optical inspection devices are operative in coordination with the plurality of manufacturing devices for inspecting the substrates prior to transfer thereof out of the second controlled airborne particle contamination environment.

Still further in accordance with a preferred embodiment of the present invention the at least some of the plurality of optical inspection devices include non-scanning sensors.

Additionally in accordance with a preferred embodiment of the present invention the plurality of optical inspection devices are operative to identify fabrication process defects occurring during production of flat panel display substrates.

Moreover in accordance with a preferred embodiment of the present invention the process defects include at least one of the following: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

Further in accordance with a preferred embodiment of the present invention the each of the plurality of optical inspection devices includes at least one non-scanning sensor which views substantially all of the surface of the substrate.

Still further in accordance with a preferred embodiment of the present invention the at least one non-scanning sensor includes a plurality of non-scanning sensors, each sensor viewing a portion of the substrate and together the plurality of sensors viewing

substantially the entire surface of the substrate.

Additionally in accordance with a preferred embodiment of the present invention each of the plurality of optical inspection devices includes an illuminating array operative to provide various combinations of illumination.

5 Moreover in accordance with a preferred embodiment of the present invention the combinations include at least dark field and substantially bright field illumination.

Further in accordance with a preferred embodiment of the present invention the non-scanning sensor acquires at least one image of the substrate for each combination.

10 Still further in accordance with a preferred embodiment of the present invention the system also includes an image analyzer for identifying process defects by computer analysis of a plurality of images of the substrate taken under various ones of the combinations of illumination.

Additionally in accordance with a preferred embodiment of the present invention, the image analyzer is operative without comparison to an external reference.

15 Moreover in accordance with a preferred embodiment of the present invention, the enclosure contains a first plurality of illuminators mounted on a first wall of the enclosure and a second plurality of illuminators mounted on a second wall of the enclosure, orthogonal to the first wall.

20 Further in accordance with a preferred embodiment of the present invention, the system also includes directionally adjustable illuminators..

25 Still further in accordance with another preferred embodiment of the present invention there is provided an inspection system for use in inspecting flat panel displays including a non-scanning optical array for viewing a flat panel display substrate, and an illumination subsystem sequentially providing dark field and bright field illumination of the flat panel display substrate when the optical array views the flat panel display substrate.

Additionally the illumination subsystem provides various combinations of dark field and bright field illumination of the flat panel display substrate when the optical array views the flat panel display substrate. The dark field and said bright field illumination may be diffuse or focussed.

30 Moreover, the flat panel display substrate may have a surface that includes a periodic spatial feature that is operative to diffract said dark field and said bright field

illumination.

Further in accordance with a preferred embodiment of the present invention, the system includes a spatially positionable stage to support the flat panel display substrate, and the stage spatially positions the substrate at various angles relative to the illumination subsystem.

Still further in accordance with a preferred embodiment of the present invention, the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the flat panel display substrate such that a non-zero'th order of diffraction impinges on the non-scanning optical array. Preferably, a multiplicity of the non-zero'th orders of diffraction of a similar order impinge on the non-scanning optical array.

Additionally, the optical array, the illumination subsystem and the stage are preferably configured and arranged to enable selectively viewing the flat panel display substrate such that a zero'th order of diffraction impinges on the non-scanning optical array.

Moreover, the optical array, the illumination subsystem and the stage are preferably additionally configured and arranged to enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

Preferably, the optical array, the stage and the illumination subsystem are configured and arranged to sequentially view the flat panel display substrate such that in one view a selected non-zero'th order of diffraction impinges on the optical array, and in other each sequential views at least one of the following orders of diffraction impinges on the optical array: a zero'th order of diffraction, an additional selected non-zero'th order of diffraction, no order of diffraction, the same non-zero'th order of diffraction of a different region of the article.

Additionally, in accordance with a preferred embodiment of the present invention the system also includes an image analyzer receiving an output from the non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

Further in accordance with a preferred embodiment of the present invention the

optical array views substantially all of a surface of the substrate. Alternatively, the optical array views only part of the surface of the substrate

Still further in accordance with a preferred embodiment of the present invention the optical array acquires at least one image of the substrate for each of a plurality
5 of different illuminations.

Additionally in accordance with a preferred embodiment of the present invention the image analyzer identifies the defects by computer analysis of a plurality of images of the substrate taken under differing illumination.

Moreover in accordance with a preferred embodiment of the present invention
10 the system also includes an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

Further in accordance with a preferred embodiment of the present invention the system also includes a third illuminator mounted on a third wall of the enclosure.

Still further in accordance with a preferred embodiment of the present
15 invention the system also includes a diffuser associated with the illumination subsystem.

Moreover in accordance with a preferred embodiment of the present invention the system includes a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

Preferably, the reflector has two points of focus, and wherein a projector is
20 situated at a first of points of focus, and the second point of focus is situated away from the flat panel display substrate. The reflector is preferably a section of an ellipsoid.

Alternatively, the reflector is flat and is operatively associated with a lens, which is preferably a fresnel lens attached to the reflector.

Moreover, in accordance with an additional alternative, the system includes
25 light source, preferably a projector, and a lens operative to provide concentrated light from the light source to at least part of said flat panel display substrate. Preferably, the projector is situated at a first focus of the lens, and a second focus of the lens is situated away from the flat panel display substrate.

Additionally in accordance with a preferred embodiment of the present
30 invention the system includes an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and axial orientation of at least two of the

optical array, the illumination subsystem and the substrate.

There is also provided in accordance with a preferred embodiment of the present invention an inspection system for use in inspecting objects including a non-scanning optical array for viewing an object, and an illumination subsystem sequentially providing dark field and bright field illumination of the flat panel display substrate when the optical array
5 views the object.

Further in accordance with a preferred embodiment of the present invention the illumination subsystem provides various combinations of dark field and bright field illumination of the object when the optical array views the surface. Preferably, the dark field
10 and said bright field illumination are diffuse or focussed.

Moreover, the surface may include a periodic spatial feature that operative to diffract light impinging thereon.

Additionally, the system preferably includes a spatially positionable stage to support the article, wherein the stage spatially positions the article at various angles relative to
15 the illumination subsystem, and the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the surface such that a non-zero'th order of diffraction impinges on the non-scanning optical array.

Additionally, the system is preferably arranged so that multiplicity of non-zero'th orders of diffraction of substantially the same order impinge on the non-scanning
20 optical array. Preferably, the optical array, the illumination subsystem and the stage are configured and arranged such that the surface may be selectively viewed while a zero'th order of diffraction reflected from the surface impinges on the non-scanning optical array, or while no orders of diffraction impinge on the non-scanning optical array.

Preferably, the optical array, the illumination subsystem and the stage are
25 configured and arranged to sequentially view the article so that one view of the article a selected non-zero order of diffraction impinges on the optical array, and in other sequential views at least one of the following orders of diffraction impinges on the optical array: a zero'th order of diffraction, an additional non-zero'th order of diffraction, the same non-zero'th order of diffraction of a different region of the surface of the article, and no order of
30 diffraction.

Still further in accordance with a preferred embodiment of the present

invention the system also includes an image analyzer receiving an output from the non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, particles.

5 Additionally in accordance with a preferred embodiment of the present invention the optical array views substantially all of a surface of the substrate. Alternatively, the optical array views only part of the surface of the substrate.

 Moreover in accordance with a preferred embodiment of the present invention the optical array acquires at least one image of the substrate for each of a plurality of different
10 illuminations.

 Further in accordance with a preferred embodiment of the present invention the image analyzer identifies the defects by computer analysis of a plurality of images of the substrate taken under differing illumination.

 Still further in accordance with a preferred embodiment of the present
15 invention the system also includes an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

 Additionally in accordance with a preferred embodiment of the present invention the system also includes a third illuminator mounted on a third wall of the
20 enclosure.

 Moreover in accordance with a preferred embodiment of the present invention the system also includes a diffuser associated with the illumination subsystem.

 Additionally in accordance with a preferred embodiment of the present invention, the system includes a light source and a reflector operative to provide concentrated
25 light from the light source to at least part of said surface. Preferably, the reflector has two points of focus. A projector preferably is situated at a first focus, and a second focus is situated not on the surface.

 Further, in accordance with a preferred embodiment of the present invention, the reflector is a section of an ellipsoid. Alternatively, the reflector is flat and is operatively
30 associated with a lens, which is preferably a fresnel lens attached to the reflector.

 Alternatively, the system includes a light source, preferably a projector, and a

lens operative to provide concentrated light from the light source to at least part of the flat panel display substrate. Preferably, the projector is situated at a first focus of the lens, and a second focus of the lens is situated not on the flat panel display substrate.

Further in accordance with a preferred embodiment of the present invention the system includes an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and axial orientation of at least two of the optical array, the illumination subsystem and the substrate.

There is also provided in accordance with a preferred embodiment of the present invention apparatus for optically inspecting the surface of an article having a substantially planar surface, including an inspection region, an illuminator operative to selectably illuminate the surface of an article located in the inspection region with at least two predetermined configurations of illumination, an image acquisition sub-system including at least one non-scanning camera for acquiring images of the surface of the article when illuminated by at least one predetermined configuration of illumination, and an image analysis subsystem for computer analyzing the images and detecting anomalies in the surface as a function of variations in reflected intensities of illumination. Based on the results of analysis of the surface, the article may be discarded, or subjected to further processing. Further processing may include correction of anomalies.

There is additionally provided a spatially positionable stage for supporting the article in the inspection region in selectable orientation relative to the illumination apparatus.

Moreover, in accordance with a preferred embodiment of the invention the image analysis subsystem is operative to identify anomalies that are substantially the same size as the resolution of the camera.

There is additionally provided in accordance with a preferred embodiment of the present invention apparatus for coating an article having a substantially planar surface, including a coating generator operative to generate a coating on a surface of the article, an illuminator for selectably illuminating the surface bearing the coating with at least two predetermined configurations of illumination, an image acquisition sub-system including at least one non-scanning sensor for acquiring images of the surface of the article for each combination of illumination, and an image analysis subsystem for analyzing the images and detecting anomalies in the surface on the basis of variations in reflected intensities of

illumination.

There is also provided in accordance with a preferred embodiment of the present invention apparatus for inspecting an article in a clean room, including an inspection device situated in the clean room and including an inspection stage selectably positionable by remote control, at least one non-scanning sensor viewing the substantially the entire inspection stage, an array of illuminators illuminating the inspection stage, automated feed apparatus, a control station situated outside the clean room, the control station including a viewer for viewing articles placed in the inspection device and a controller for positioning the stage and providing selected configurations of illumination to illuminate the article.

There is also provided in accordance with a preferred embodiment of the present invention a method for manufacture of flat panel displays including providing a plurality of manufacturing devices located in a first controlled environment, at least some of the plurality of manufacturing devices each including an enclosure defining a second controlled environment different from the first controlled environment, and inspecting flat panel display substrates at various stages of the production thereof by the plurality of manufacturing devices at a location within the enclosures defining a second controlled environment.

Further in accordance with a preferred embodiment of the present invention the inspecting step includes inspecting the substrates prior to transfer thereof out of the second controlled airborne particle contamination environment.

Still further in accordance with a preferred embodiment of the present invention the inspecting step includes inspecting using non-scanning sensors.

Additionally in accordance with a preferred embodiment of the present invention the method further includes identifying fabrication process defects occurring during production of flat panel display substrates.

Moreover in accordance with a preferred embodiment of the present invention the identifying step includes identifying process defects including at least one of the following: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

Further in accordance with a preferred embodiment of the present invention the

inspecting step includes inspecting using at least one non-scanning sensor which views substantially all of the surface of the substrate.

Still further in accordance with a preferred embodiment of the present invention the inspecting step includes inspecting using a plurality of non-scanning sensors, each sensor viewing a portion of the substrate and together the plurality of sensors viewing substantially the entire surface of the substrate.

Additionally in accordance with a preferred embodiment of the present invention the inspecting step includes illuminating the substrate with an illuminating array operative to provide various combinations of illumination.

Moreover in accordance with a preferred embodiment of the present invention the combinations include at least dark field and substantially bright field illumination.

Further in accordance with a preferred embodiment of the present invention the inspecting step includes acquiring at least one image of the substrate for each combination using the non-scanning sensor.

Still further in accordance with a preferred embodiment of the present invention the method also includes performing computer analysis of a plurality of images of the substrate taken under various ones of the combinations of illumination to detect process defects.

Additionally in accordance with a preferred embodiment of the present invention the image analysis step is performed without comparison to an external reference.

Moreover in accordance with a preferred embodiment of the present invention the providing step includes further mounting a first plurality of illuminators on a first wall of the enclosure and mounting a second plurality of illuminators on a second wall of the enclosure, orthogonal to the first wall.

Further in accordance with a preferred embodiment of the present invention the mounting step includes further providing directionally adjustable illuminators.

There is also provided in accordance with a preferred embodiment of the present invention a method for inspecting a flat panel display substrate including viewing a flat panel display substrate using a non-scanning optical array, and sequentially illuminating the flat panel display substrate with dark field and bright field illumination while the optical array views the flat panel display substrate.

Further in accordance with a preferred embodiment of the present invention the sequentially illuminating step illuminates using various combinations of dark field and bright field illumination of the flat panel display substrate when the optical array views the flat panel display substrate.

5 Still further in accordance with a preferred embodiment of the present invention the method also includes receiving an output from the non-scanning optical array, and detecting process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

10 Additionally in accordance with a preferred embodiment of the present invention the viewing step includes viewing substantially all of a surface of said substrate.

Moreover in accordance with a preferred embodiment of the present invention the viewing step includes acquiring at least one image of the substrate for each of a plurality of different illuminations.

15 Further in accordance with a preferred embodiment of the present invention the detecting step includes identifying the defects by computer analysis of a plurality of images of the substrate taken under differing configurations of illumination.

20 Still further in accordance with a preferred embodiment of the present invention the method also includes providing an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

Additionally in accordance with a preferred embodiment of the present invention the providing step also includes providing a third illuminator mounted on a third wall of the enclosure.

25 Moreover in accordance with a preferred embodiment of the present invention the method also includes providing a diffuser associated with the illumination subsystem.

30 Further in accordance with a preferred embodiment of the present invention the method also includes providing an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and axial orientation of at least two of the optical array, the illumination subsystem and the substrate.

There is also provided in accordance with a preferred embodiment of the

present invention a method for inspecting objects including viewing an object using a non-scanning optical array, and sequentially illuminating the object with dark field and bright field illumination while the optical array views the object.

5 Further in accordance with a preferred embodiment of the present invention the sequentially illuminating step illuminates using various combinations of dark field and bright field illumination of the object while the optical array views the object.

Still further in accordance with a preferred embodiment of the present invention the method also includes receiving an output from the non-scanning optical array, and detecting process defects including at least one of: uneven deposition of coatings, uneven
10 removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

Additionally in accordance with a preferred embodiment of the present invention the viewing step includes viewing substantially all of a surface of the object.

Moreover in accordance with a preferred embodiment of the present invention
15 the viewing step includes acquiring at least one image of the object for each of a plurality of different illuminations.

Further in accordance with a preferred embodiment of the present invention the detecting step includes identifying the defects by computer analysis of a plurality of images of the object taken under differing configurations of illumination.

20 Still further in accordance with a preferred embodiment of the present invention the method also includes providing an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

25 Additionally in accordance with a preferred embodiment of the present invention the providing step also includes providing a third illuminator mounted on a third wall of the enclosure.

Moreover in accordance with a preferred embodiment of the present invention the method also includes providing a diffuser associated with the illumination subsystem.

30 Further in accordance with a preferred embodiment of the present invention the method also includes providing an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and rotational orientation of at least two

of the optical array, the illumination subsystem and the object.

There is also provided in accordance with a preferred embodiment of the present invention a method for optically inspecting the surface of an article having a substantially planar surface, including defining an inspection region, selectably illuminating the surface of an article located in the inspection region with at least two predetermined configurations of illumination, for each predetermined configuration of illumination acquiring an image of the surface of the article using at least one non-scanning camera, and analyzing the image and detecting anomalies in the surface as a function of variations in reflected intensities of illumination.

There is additionally provided in accordance with a preferred embodiment of the present invention a method for coating an article having a substantially planar surface, including generating a coating on a surface of the article, selectably illuminating the surface bearing the coating with at least two predetermined configurations of illumination, for each configuration of illumination acquiring an image of the surface of the article using at least one non-scanning sensor, and analyzing the images and detecting anomalies in the surface on the basis of variations in reflected intensities.

There is also provided in accordance with a preferred embodiment of the present invention a method for inspecting an article in a clean room, including situating an inspection device in the clean room, selectably positioning an inspection stage of the inspection device by remote control, viewing substantially the entire inspection stage using at least one non-scanning sensor of the inspection device, illuminating the inspection stage using an array of illuminators of the inspection device, placing articles in the inspection device using automated feed apparatus of the inspection device, and situating a control station outside the clean room, the control station including a viewer for viewing articles placed in the inspection device and a controller for remotely positioning the stage and providing selected combinations of illumination.

There is additionally provided in accordance with a preferred embodiment of the present invention a method for inspecting the surface of an article, including the steps of placing the article in an inspection region defined by a stage, illuminating a portion of the surface of the article with at least one configuration of dark field illumination, acquiring an image of substantially the entire surface for the at least one configuration of dark field

illumination, illuminating the surface with at least one configuration of substantially bright field illumination, acquiring an image of substantially the entire surface for the at least one configuration of substantially bright field illumination, and providing computer analysis of the images to determine non uniformities in reflected intensities.

5 Further in accordance with a preferred embodiment of the present invention the at least one configuration of dark field illumination includes a plurality of dark field illumination configurations, and a separate image is acquired for each configuration.

Still further in accordance with a preferred embodiment of the present invention the at least one configuration of substantially bright illumination includes a plurality
10 of bright field illumination configurations, and a separate image is acquired for each configuration.

Additionally in accordance with a preferred embodiment of the present invention each predetermined combination of illumination is provided by selecting a predetermined inclination and rotational orientation of the substrate, and separate images of
15 the surface are acquired for each inclination and rotational orientation.

Moreover in accordance with a preferred embodiment of the present invention there is provided an additional step of optically treating the illumination prior to acquiring an image.

Further in accordance with a preferred embodiment of the present invention the
20 treatment is provided by optical filters.

Still further in accordance with a preferred embodiment of the present invention the filters filter for selected wavelengths.

Additionally in accordance with a preferred embodiment of the present invention the filters filter for selected polarization.

25 Moreover in accordance with a preferred embodiment of the present invention the surface is illuminated with a selected combination of broad spectrum illumination and imaged through an optical filter operative to transmit light in a first predetermined spectral range, and subsequently imaged through and optical filter operative to transmit light in a second predetermined spectral range.

30 Further in accordance with a preferred embodiment of the present invention the surface is illuminated with a first combination of illumination through an optical filter

operative to transmit light predetermined spectral range and imaged, and subsequently illuminated with a second combination of illumination through an optical filter operative to transmit light in a second predetermined spectral range and imaged.

5 Still further in accordance with a preferred embodiment of the present invention the surface is illuminated with a selected combination of broad spectrum illumination and imaged through and optical filter operative to transmit light having a first polarization state, and subsequently imaged with through a second optical filter operative to transmit light having a second predetermined polarization state.

10 Additionally in accordance with a preferred embodiment of the present invention the surface is illuminated with a first combination of optically filtered illumination having a first predetermined polarization state and imaged, and subsequently illuminated with a second combination of optically filtered illumination having a second predetermined polarization state and imaged.

15 Moreover in accordance with a preferred embodiment of the present invention there is provided an additional step of blurring the image during acquisition.

Further in accordance with a preferred embodiment of the present invention an image is blurred by introducing, during image acquisition, relative movement between at least two of the following: the surface, the camera, and an optical element between the surface and the camera.

20 Still further in accordance with a preferred embodiment of the present invention there is provided a further step of analyzing the non-uniformities in reflective intensity with a computer to determine the presence of defects in coatings on the substrate.

Additionally in accordance with a preferred embodiment of the present invention the article is a flat display panel substrate.

25 There is also provided in accordance with a preferred embodiment of the present invention a method for coating the surface of an article, including the steps of depositing a coating on at least part of a surface of the article, placing the article in an inspection region, illuminating a portion of the coated surface of the article with dark field illumination and acquiring an image of the illuminated surface, illuminating the surface with
30 substantially bright field illumination and acquiring an image of the illuminated surface, and analyzing each image with a computer to determine non uniformities in reflected intensity.

There is also provided in accordance with a preferred embodiment of the present invention apparatus for the automatic optical inspection of a generally flat article having at least one generally periodic spatial feature, comprising a light beam generator providing an illuminating beam of light along an illuminating light beam axis onto a generally flat article having at least one at least generally periodic spatial feature; and a sensor viewing the article along a light receiving axis disposed at an angle with respect to the illumination light beam axis whereby a generally non-zero'th order of diffracted light reflected from the said article impinges on the sensor.

Further in accordance with a preferred embodiment of the present invention, there is provided a selectably orientable support supporting the generally flat article, and a positioner for changing the angular inclination of the generally flat article with respect to the illumination light beam axis and said light receiving axis during viewing by the sensor. Preferably, the positioner is operative to selectably orient the generally flat article so that it lies in a plane that is not always perpendicular to the plane defined by the illuminating light beam axis and the light receiving axis.

Still further in accordance with a preferred embodiment of the present invention, there is provided a light absorbing housing enclosing at least said light beam generator and the sensor for generally preventing diffuse illumination from impinging on said sensor is also provided.

There is also provided in accordance with a preferred embodiment of the present invention a method for manufacturing flat panel displays including the steps of providing a first controlled environment in which an airborne particle controlled environment having a first level of controlled airborne particulate contamination, and a second controlled environment in which an airborne particle controlled environment having a second level of controlled airborne particulate contamination is less than the first level of controlled airborne particulate contamination.

Further in accordance with a preferred embodiment of the present invention the method of inspecting a flat panel display includes illuminating the dark field and the bright field illumination are diffuse. Preferably, the dark field and the bright field illumination are focussed.

Additionally in accordance with a preferred embodiment of the present

invention the flat panel display substrate has a surface that includes a periodic spatial feature, and the dark field and the bright field illumination are diffracted by the spatial feature.

Still further in accordance with a preferred the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the flat panel display substrate such that a non-zero'th order of diffraction impinges on the non-scanning optical array. Additionally a multiplicity of the non-zero'th orders of diffraction of a similar order impinge on said non-scanning optical array.

Still further in accordance with a preferred embodiment of the present invention, the method for inspecting the flat panel display includes configuring and arranging the optical array, the illumination subsystem and the stage to additionally enable selectively viewing the flat panel display substrate such that a zero'th order of diffraction impinges on the non-scanning optical array. Additonally, the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

Furthermore, the optical array and the illumination subsystem are configured and arranged to sequentially view the flat panel display substrate and wherein in one view a selected non-zero'th order of diffraction impinges on the optical array, and in other each sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional selected non-zero'th order of diffraction, no order of diffraction, the same non-zero'th order of diffraction of a different region of the article.

The method for inspecting a flat panel display includes providing a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate. Additionally the reflector has two points of focus, and wherein a projector is situated at a first of points of focus, and the second point of focus is situated away from the flat panel display substrate. The reflector may be a section of an ellipsoid. Alternatively, the reflector may be flat and operatively associated with a lens, and the lens may include a fresnel lens attached to the reflector.

Furthermore the method for inspecting a flat display panel may include providing a light source and a lens operative to provide concentrated light from the light source to at least part of the flat panel display substrate. Addtioanlly the projector is situated

at a first focus of the lens, and a second focus of the lens is situated away from the flat panel display substrate.

In a method for inspecting a flat display panel the dark field and the bright field illumination may be diffuse. Additionally, the dark field and the bright field illumination may be focussed, and the surface includes a periodic spatial feature operative to diffract light impinging thereon.

The method also includes providing a spatially positionable stage to support the article, wherein the stage spatially positions the article at various angles relative to the illumination subsystem. Additionally, the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the surface such that a non-zero'th order of diffraction impinges on the non-scanning optical array, and the multiplicity of non-zero'th orders of diffraction of substantially the same order impinge on the non-scanning optical array. Furthermore, the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing of the surface such that a zero'th order of diffraction impinges on the non-scanning optical array. Furthermore, the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the object such that substantially no orders of diffraction impinge on the non-scanning optical array. The optical array, the illumination subsystem and the stage are also configured and arranged to sequentially view the object and wherein in one view a selected non-zero order of diffraction impinges on the optical array, and in other sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional non-zero'th order of diffraction, the same non-zero'th order of diffraction of a different region of the surface of the article, and no order of diffraction.

Additionally the optical array views only a part of a surface of the substrate.

The method for inspecting a flat panel display also includes providing a light source and a reflector operative to provide concentrated light from the light source to at least part of said surface wherein the reflector has two points of focus, and wherein a projector is situated at a first focus, and a second focus is situated not on the surface.

The reflector is a section of an ellipsoid or alternatively the reflector may be flat and is operatively associated with a lens. The lens may be a fresnel lens attached to the

reflector.

The method for inspecting a flat panel display also includes providing a light source and a lens operative to provide concentrated light from the light source to at least part of the flat panel display substrate, and a projector which is situated at a first focus of the lens, and a second focus of the lens is situated not on the flat panel display substrate.

Brief Description of the Drawings

The present invention will be more fully appreciated from the following detailed description taken in conjunction with the accompanying drawings, in which:

Fig. 1 is a simplified pictorial illustration of a clean room for FPD fabrication having located therein a system for inspecting FPD substrates constructed and operative according to a preferred embodiment of the present invention;

Fig. 2A - 2E are simplified illustrations of a typical FPD substrate and various typical fabrication process flaws which may occur during fabrication thereof;

Fig. 3 is a simplified pictorial illustration of an inspection system constructed and operative in accordance with a preferred embodiment of the present invention;

Fig. 4 is a simplified pictorial illustration of an illumination unit useful in a preferred embodiment of the invention;

Fig. 5 is a simplified pictorial illustration of an inspection system having a stage which is movable about multiple axes in accordance with a preferred embodiment of the invention;

Fig. 6 is a simplified side view illustration of the geometry of diffuse bright field illumination employed in a preferred embodiment of the invention;

Fig. 7 is a simplified side view illustration of the geometry of one type of diffuse dark field illumination employed in a preferred embodiment of the invention;

Fig. 8 is a simplified side view illustration of the geometry of another form of diffuse dark field illumination employed in a preferred embodiment of the invention;

Fig. 9 is a simplified pictorial illustration of the structure and operation of an optical head of a preferred embodiment of the invention;

Fig. 10 is a simplified flow chart illustrating operation of a system for generating a patterned coating on a surface of a planar substrate and inspecting the surface in accordance with a preferred embodiment of the invention;

Fig. 11 is a simplified pictorial illustration of various structures for illumination and

image acquisition which may be incorporated in an inspection system constructed and operative in accordance with additional preferred embodiments of the present invention;

Fig. 12 is a simplified pictorial illustration of an illumination and image acquisition subsystem of an inspection system constructed and operative in accordance with an additional preferred embodiment of the present invention;

Fig. 13 is a side view of the illumination and image acquisition subsystem shown in Fig. 12:

Fig. 14 is a simplified pictorial illustration of an illumination and image acquisition subsystem configured and arranged in accordance with a preferred embodiment of the present invention to provide focussed bright field and focussed dark field illumination showing axes of inclination and rotation of a stage therein;

Figs. 15A - 15E are simplified side view illustrations of an illumination and acquisition subsystem constructed and arranged in accordance with a preferred embodiment of the present invention showing the effect of changing the angle of inclination of a stage;

Figs. 16A and 16B are simplified pictorial illustrations of an illumination and image acquisition subsystem constructed and arranged in accordance with a preferred embodiment of the present invention showing on-axis focussed dark-field and off-axis focussed dark field illumination, respectively.

Figs. 17A and 17B are simplified side view illustrations of an illumination and image acquisition system constructed and arranged in accordance with a preferred embodiment of the present invention illustrating diffraction when focussed and diffuse illumination are provided:

Fig. 18 is a simplified pictorial illustration of an illumination and image acquisition subsystem of an inspection system constructed and operative in accordance with still another preferred embodiment of the present invention, employing a fresnel lens and reflector assembly;

Fig. 19 is a simplified pictorial illustration of an illumination and image acquisition subsystem of an inspection system constructed and operative in accordance with yet another preferred embodiment of the present invention, employing a transmissive fresnel lens; and

Fig. 20 is a simplified pictorial illustration of an additional preferred embodiment of an inspection system constructed and operative in accordance with the present invention.

Detailed Description of Preferred Embodiments

Reference is made to Fig. 1, which illustrates part of an FPD fabrication facility 10 comprising a number of units of fabrication equipment 12, at least some of which include an inspection system 14 constructed and operative in accordance with the present invention.

FPD fabrication is extremely sensitive to contamination by airborne particles. FPD fabrication is therefore conducted in so-called "clean areas", having a controlled environment of highly filtered air. Various processes require different tolerances of air purity. A typical clean area used for FPD fabrication, such as a clean room, may have a concentration of airborne particulate impurities, such as dust, of between 10 - 100 particles per cubic meter of air. In order to maintain such low concentrations of airborne particles, FPD fabrication operations are preferably highly mechanized and run without human intervention.

Fabrication equipment 12 is generally highly automated and self-contained. Each unit of equipment 12 is situated in a clean room 15 and performs a predetermined series of fabrication process steps. Automated trolleys 16 running on pathways 18 in the clean room 15 are used to transport cassettes 20 of in-fabrication FPD substrates to and from the automated fabrication equipment 12 during the fabrication process. To minimize contamination, only a few human attendants 22 are permitted into the clean room 15. Moreover, attendants 22 in the clean room 15 are required to wear specially designed attire to further reduce contamination.

FPD structures and fabrication processes are well known and are described in detail, for example in Castellano, J. et. Al., "Liquid Crystal Displays", Stanford Resources, Inc., 1995. The particulars of any given fabrication process are not part of this invention. A generalized description of FPD structure and fabrication, is now provided by way of example only in order that the description of the present invention may be more readily understood.

A typical FPD substrate, shown in Fig. 2A, comprises a glass substrate 24 having a multi-layered matrix structure, typically comprising a periodic spatial array of features, such as individually controllable liquid crystal cells 25, uniformly deposited thereon. The size of each cell is typically in the order of 90 x 270 microns. The cells 25 are interconnected by connectors (not shown) having a typical line width of the order of 7 microns. A typical substrate measures between 405 x 505mm and 650 x 830mm and contains a plurality of

multi-layered matrices 26, of which four are shown. It is readily appreciated that a dense structure of cells and connectors typically forms a two dimensional diffraction grating when appropriately illuminated.

The matrix structure is preferably obtained by a repetitive multi-step process generally including the deposition of a metallic or non-metallic thin film on the substrate 24; coating the film with a radiation sensitive photoresist; exposing the photoresist to radiation according to a predetermined pattern; developing the photoresist and selectively washing away those parts of the photoresist that are exposed (or in some processes, not exposed); etching away those parts of the thin film not protected by residual photoresist, to thereby form the predetermined pattern in the thin film; and stripping away residual photoresist that overlays the resulting pattern. Each of these steps may be performed by various alternative techniques, the particulars of which are not of importance for the current invention. As the result of multiple repetitions of the foregoing steps, multi-layered matrices 26 are generated.

Typically each unit of fabrication equipment 12 handles a number of associated steps in the fabrication process. For example, some fabrication equipment deposits thin metallic film layers on the glass substrate 24. Other fabrication equipment coats the resulting metallic film with photoresist, exposes the photoresist according to a pattern, develops the photoresist and selectively removes exposed or unexposed photoresist. Still other fabrication equipment etches the metallic layer to remove those parts of the metal film that are not protected by residual photoresist. Still further fabrication equipment strips residual photoresist overlying the resultant pattern.

A typical clean room comprises an area of hundreds of square meters. Because human attendants cannot be excluded from such clean rooms and because of the extremely high cost of maintaining clean rooms at the lower end of the permitted range of contamination, the large clean rooms typically have a concentration level of airborne particles per cubic meter that is maintained at the upper end of the permitted range, approximately 100 airborne particles per cubic meter.

In order to meet the environmental demands required by some of the fabrication steps within the clean room 15, for example low airborne particulate concentration, various critical units of fabrication equipment 12 are each provided with an enclosure defining a second controlled self-contained environment that meets the required environmental demands. This

second self-contained environment is typically maintained at a lower level of airborne contamination than that of the clean room 15. For typical fabrication equipment, the self-contained environment is maintained preferably at about 10 airborne particles per cubic meter.

Inside the second self-contained controlled environment, in-fabrication FPD substrates are typically handled by robots (not shown). FPDs are typically fabricated in batches, with each batch being carried in cassettes 20 between various second self-contained environments situated at different locations in the clean room.

Processes that are performed in fabrication equipment 12 are potentially subject to process flaws. Referring now to Figs. 2B - 2E, illustrative examples of typical detectable large scale process flaws are shown. Typical fabrication process flaws include: deposits of chemical residues 28 that remain on the substrate because of incomplete washing (Fig. 2B); areas 30 of incomplete or missing matrix resulting from uneven exposure of photoresist, and subsequent uneven or incomplete deposition of matrix 26 in those areas (Fig. 2C); rinse tracks 32 that remain on the substrate after washing between processes (Fig. 2D); scratches 34, lines 36 and embedded particles 38 (Fig. 2E). Additional fabrication process defects include various other anomalies such as uneven deposition of films and coatings on the substrate (not shown). It is to be appreciated that this list of fabrication process flaws may be considered representative of typical defects, and is not limiting.

Process flaws such as those described above may affect individual FPD substrates, or an entire batch of FPD substrates being processed by a particular unit of fabrication equipment. For example, a robot loader that handles FPD substrates inside fabrication equipment 12 may scratch all the substrates that it handles, thus rendering the substrates defective, or the timing of a rinse may be improperly set so that chemical residues are not fully washed off the substrate.

In order to identify defective in-fabrication FPD substrates as early as possible in the fabrication process, in accordance with a preferred embodiment of the present invention, optical inspection apparatus 14 is situated inside the controlled self-contained environment of fabrication equipment 12 to automatically inspect substrates 24 after the completion of a fabrication process but before removal to fabrication equipment performing downstream fabrication processes. In accordance with an additional feature of the present invention, optical inspection apparatus 14 constructed and operative in accordance with the present

invention may be configured as stand-alone equipment situated in the clean room, but outside of equipment 12.

Reference is made to Fig. 3, which is a perspective view of inspection apparatus 14, constructed and operative in accordance with a preferred embodiment of the invention operative to provide multiple arrangements of diffuse lighting, and to identify defective FPD substrates. Inspection apparatus 14 preferably comprises an upper substantially fully enclosed inspection enclosure 40 shown in phantom lines, and a lower computer cabinet 42 in which a computer controller and image processor 44, preferably an Ultra Sparc AXI 300, available from Sun Micro Systems Corp., is situated. The width and depth dimensions of inspection enclosure 40 are preferably up to about 1.2m width, by 1.0m depth, these dimensions being somewhat larger than the dimensions of typical FPD substrates. It is readily appreciated that larger and smaller dimensions may be used in order to accommodate larger and smaller substrates. The height of enclosure 40 is preferably 1.00 - 1.30 meters in height, depending on the desired inspection resolution and dimensional constraints of the fabrication equipment 12 in which it is situated. Optionally the entire inspection apparatus 14 may be tilted to one side in order to accommodate space constraints imposed by fabrication equipment 12.

A stage 46 is situated in the base of inspection enclosure 40 for supporting an in-fabrication FPD substrate 24. A non-scanning staring array sensor 48, preferably a CCD type non-scanning staring area camera having between 1,200 x 1,000 and 1,500 x 1,000 pixel resolution, is secured to enclosure 40 overhead of stage 46. Sensor 48 is preferably a Hammamatsu C4742-95 CCD camera, provided with a wide angle lens, preferably a Nikkor AF 20mm lens from Nikon Corporation. As is readily appreciated, the camera and lens arrangement provide a field of view that is sufficient to view at least a substantial part of the substrate 24, and preferably the entire substrate. As will be discussed in detail below with reference to Fig. 11, alternatively, an array of non-scanning sensors that together image the entire substrate, may be provided. Alternatively, sensor 48 may be arranged to view only a part of substrate 24, and substrate 24 may be sequentially rotated.

In accordance with a preferred embodiment of the present invention, the sensor 48 is horizontally mounted on top of enclosure 40, and is provided with a flat angularly adjustable reflector 50, configured to direct an image of substrate 24 into sensor 48. It is readily appreciated that due to dimensional constraints on the height of enclosure 40 imposed by

dimensional limitations of fabrication equipment 12 in which it is situated, it may be advantageous to locate sensor 48 elsewhere in the enclosure and to use mirrors (not shown) to fold the optical path. For example, an upward staring sensor positioned adjacent to the stage may be used in combination with a substantially downward reflecting mirror to effectively increase the optical distance between the sensor and the stage without having to increase the height of enclosure 40.

The walls of enclosure 40 are preferably constructed of metal, such as aluminum, and are provided with a light absorbing coating, such as a black matte coating, operative to minimize internal reflections inside enclosure 40. A small access opening (not shown) is provided so that fabrication substrates 24 can be readily positioned on stage 46, or removed therefrom.

An array of illumination units 60 is provided inside enclosure 40, for providing various selectable combinations of illumination, as will be explained in greater detail below. In accordance with a preferred embodiment of the present invention, each illumination unit 60, shown in detail in Fig. 4, preferably comprises a housing 62, a cold cathode lamp 64 located inside the housing, a power supply 66 and a diffuser 68. It is readily appreciated that instead of employing a wide visible spectrum cold cathode lamps, illumination units 60 may employ arrays of individually controllable LEDs configured to provide selectable combinations of wide spectrum or narrow spectrum illumination, flash units, or non-visible spectrum irradiators such as those providing illumination in the near UV spectral region. The diffuser 68 may be formed of a ground glass diffusing element, Fresnel diffuser or suitable diffusing elements.

As shown in Fig. 3, one wall of the inspection enclosure is preferably provided with a first illumination array, referred to herein as tall wall illumination array 70, beginning about 1 cm above stage 46, ranging between 1.00 meter to 1.30 meters in height above the stage 46, and covering substantially the entire width of an inside wall of the cabinet 42. Tall wall illumination array 70 is preferably divided into at least 10 individually controllable illumination units 60. A second illumination array, between 35 - 70 cm in height, referred to herein as short wall illumination array 72, is preferably provided on an inside wall of the enclosure 40, and is typically orthogonal to tall wall illumination array 70.

Short wall illumination array 72 preferably covers substantially the entire width of an

inside wall of enclosure 40, preferably beginning at between 8 to 15 cm above the stage, and preferably comprises at least five individually controllable illumination units 60. A third illumination array, referred to as strip illumination array 74, preferably comprises a single independently controllable illumination unit 60. Strip illumination 74 preferably is situated
5 on an inside wall of enclosure 40 preferably opposite tall wall illumination array 70, at height of between 5 - 10 cm above the stage 46.

Referring now to Fig. 5, it is seen that the spatial orientation of stage 46 is adjustable. Horizontal inclination of stage 46 is preferably selectively adjustable to be at an angle β relative to the horizontal in either the X - Z plane, as shown, or to the Y - Z plane.
10 Inclination of stage 46 may be selected using a linear positioning table, preferably a model 404XR table available from Daedal. Rotational positioning of stage 46 relative to its central axis 75 also may be adjusted using a conventional rotational positioning table (not shown).

One advantage of providing an array of separately controllable illumination elements 60 for illuminating the stage from different angles in combination with a spatially
15 positionable stage 46 is that the angles of illumination between respective illumination units 60 and the stage 46 and between the stage and sensor 48 may thus be selected both to maximize the contrast of various process flaws associated with matrix 25 or substrate 24, and to minimize optical noise, such as the reflection of an image of sensor 48 back through its lens. For example, some process flaws may be better viewed when illuminated by
20 substantially bright field illumination. Other types of process flaws may have higher contrast, and thus be better viewed, when illuminated by dark field illumination that is provided at selected angles to the substrate. It is readily appreciated that in providing a large selection of illumination combinations and of spatial positioning of the stage, typically including multiple combinations of dark field illumination and optionally, in addition, substantially bright field
25 illumination, the contrast of different flaws can be maximized and noise minimized so as to enhance the ease of viewing different types of process flaws in at least one of the illumination configurations.

The operation of a preferred embodiment of the invention for various combinations of illumination and spatial positioning of the substrate 24, are now described with reference to
30 Figs. 6 - 8.

In a first illumination configuration, shown in Fig. 6, a flood diffuse illumination is

provided. Here it is seen that rays 80, geometrically representing a bright field component of illumination, are reflected by a surface 82 of substrate 24 such that for a specularly reflecting surface at least some of rays 80 follow a path that impinges on lens 84 associated with sensor 48. It is appreciated that while this configuration of illumination is referred to herein as substantially bright field, the illumination is diffuse and for a clean and properly fabricated FPD substrate 24 (Fig. 3), the matrix structure 26 (Fig. 2) deposited on the substrate 24 at least partially diffracts and scatters the diffuse light, such that at least some of the rays, typified by non-bright field ray 85, do not impinge on lens 84. Consequently, patterns are typically formed in the reflection as result of non specular reflection corresponding to light diffracted and scattered by the pattern deposited on the substrate.

In order to achieve diffuse substantially bright field illumination, stage 46 is inclined toward the tall wall illumination array 70, preferably at an angle β of between $18^\circ - 26^\circ$ so that bright field components of rays 80 specularly reflected from all regions surface 82 impinge on lens 84. Preferably all of illumination units 60 of the tall wall illumination array 70 are illuminated simultaneously. Surface 82 is imaged by sensor 48, and the acquired image is subsequently processed by computer controller and image processor 44 (Fig. 3).

It is appreciated that in the diffuse substantially bright field configuration described, because of the diffuse illumination, each individual point on the stage may be considered as being illuminated by numerous point sources originating in tall wall illumination array 70, and that each individual point source in tall wall illumination 70 may be considered as illuminating numerous points on the surface 82. The result is an intense flood of diffuse multi-source illumination on surface 82.

It is also appreciated that while it is convenient to refer to such illumination as "bright field illumination", because a specularly reflected light from an illumination source, such as tall wall illumination 70, impinges on lens 84, in fact some of the illumination does not impinge on lens 84. The non-bright field components of the illumination can be generally considered "wasted" light. Preferably, internal walls of enclosure 40 are provided with a conventional anti-reflection coating 86 to minimize undesired reflections from non-bright field rays 85.

Additional illumination configurations, shown in Figs. 7 and 8, provide diffuse dark field illumination. As seen in Figs. 7 and 8 none of rays 88, geometrically representing a

component in the illumination that is reflected by a specularly reflecting surface 82 of substrate 24, impinge on lens 84 associated with sensor 48.

In a first diffuse dark field illumination configuration, shown in Fig. 7, stage 46 is inclined away from tall wall illumination array 70, preferably at an angle β , ranging between 12° - 18° to the horizontal, so that an image of sensor 48 and all rays 88 from tall wall illumination array 70 are not specularly reflected by surface 82 back into lens 84. Initially, illumination is provided by predetermined combinations of illumination units 60 forming part of tall wall illumination array 70. The units 60 in tall wall illumination array 70 that are employed for this purpose are preferably located between 5 and 50 cm above stage 46. The inclination of stage 46 and the angle of the illumination are selected to provide diffuse dark field illumination of at least part of surface 82. The surface 82 is imaged by sensor 48 for each of a plurality of different illumination configurations. If a given illumination configuration does not provide suitable diffuse dark field illumination of the entire surface 82, stage 46 may be rotated as necessary. Preferably, a second combination of dark field illumination is provided in which the units 60 that are located in the range of 40 - 90 cm above stage 46 are employed to illuminate at least part of surface 82.

In a similar manner, diffuse dark field illumination preferably is additionally provided by illumination units 60 forming part of short wall illumination array 72.

Referring now to Fig. 8, there is seen a dark field illumination configuration employing a strip illuminator 74 (Fig. 3). The stage 46 is inclined at angle β , preferably between 12° - 18° relative to the horizontal, away from the tall wall illumination array 70 and toward strip illuminator 74. A blind 94 preferably is provided to adjust the breadth of illumination emanating from strip illuminator 74 to a relatively small strip of between 5 and 12 cm. It is readily appreciated that instead of the blind 94, a narrow illumination source may be employed as strip illuminator 74. It is seen that if an inspected surface 96 supported on stage 46 (Fig. 3) is inclined toward strip illuminator 74, the strip illuminator 74 provides illumination at a sufficiently low angle relative to surface 96 such that the illumination does impinge on lens 84 associated with sensor 48.

It is appreciated that the illumination configurations are preferably determined empirically to maximize the contrast of various types of defects on substrate 24, and to minimize undesired reflections therefrom.

Reference is now made to Fig. 9, which illustrates the structure of an optical head 100 suitable for use in the present invention. Optical head 100 preferably comprises a non-scanning sensor 102, a mirror 104, a plurality of optical filters 106, a mechanical driver 108 for changing optical filters 106, and a blur generator 110. Preferably, the plurality of filters 106 includes both polarizing filters and spectral filters. A surface of substrate 24 (Fig. 3) is preferably imaged using various different combinations of filters 106 to acquire a series of broad spectrum, narrow spectrum and polarized light images. The angular orientation of mirror 104 may be adjustable as shown, to enable imaging of various parts of the substrate or to minimize reflection of images of optical head 100 by the substrate 24 (Fig. 3).

Preferably, during imaging, blur generator 110 is operative to introduce blurring in the image acquired by sensor 102. Blurring is effective to attenuate the Moire effect arising from resolution differences between sensor 102 and the pattern deposited on the substrate 24 (Fig. 3). The blurring may be achieved by means of mechanical vibration that is operative to cause relative displacement between sensor 102, and/or mirror 104 and/or stage 46 (Fig. 3) and/or any other suitable optical element situated along the optical path between the sensor and the stage. Alternatively, blurring may be introduced by an optical blurring filter or by other means such as electronic manipulation of the image signal.

Reference is now made to Fig. 10 which is a flow diagram illustrating the operation of a fabrication equipment and an inspection system, such as the system of Fig. 1, for use in fabricating FPDs. Although the invention is described with reference to the fabrication of FPD's, it is readily appreciated that the invention may be used in the context of applying and inspecting coatings to flat surfaces of other suitable objects and articles. The flow diagram of Fig. 10 shows the steps of performing a fabrication process on a substrate, for example the application of a coating, and inspecting the substrate. The operation illustrated in Fig. 10 preferably identifies fabrication process flaws while an in-fabrication FPD substrate is still within the self-contained environment of fabrication equipment 12 (Fig. 1), and before the substrate is transferred to other equipment that performs downstream fabrication steps.

As shown in Fig. 10, the following steps are preferably performed:

STEP 160: A cassette 20 (Fig. 1) containing FPD substrates 24 (Fig. 3) is placed in fabrication equipment 12 (Fig. 1) that has a self-contained micro environment having a level of airborne contamination substantially lower than the level of airborne contamination in a

surrounding clean room 15 (Fig. 1).

STEP 180: A series of fabrication process steps is sequentially performed on the each of substrates 24. By way of example only, a series of steps performed in particular equipment may include the deposition a photoresist film over a thin metallic film previously deposited on a substrate 24, exposure of the photoresist in a predetermined pattern using conventional exposure equipment, subsequent development of the photoresist and washing away unexposed photoresist to leave on the substrate a patterned deposit of photoresist. Alternatively, any other suitable series of predetermined process steps may be performed.

STEP 200: After the completion of various fabrication process steps performed on a substrate 24 in fabrication equipment 12, and prior to its transfer to other fabrication equipment for subsequent fabrication processing, substrate 24 is positioned on stage 46 (Fig. 3) of the inspection system 14, preferably situated inside the self-contained micro-environment of equipment 12. It is readily appreciated that inasmuch as inspection system 14 is situated inside fabrication equipment 12, substrate 24 does not have to be removed from fabrication equipment 12 to be inspected and it is not necessary to wait for the completion of fabrication processes on an entire batch of substrates 24. Thus, preferably, each substrate 24 is inspected immediately upon the completion of a predetermined fabrication process; thus enabling other fabrication processes to continue simultaneously for other substrates in a batch until all substrates have been processed and inspected.

STEP 210: The spatial orientation of stage 46 is adjusted to position the substrate in a predetermined position for bright field illumination or for one of the dark field illumination combinations. To minimize undesired reflections and to aim the field of view of sensor 48 (Fig. 3) to a desired part of substrate 24 that is to be inspected, the angular orientation of mirror 50 (Fig. 3) is adjusted, as necessary.

STEP 220: A predetermined configuration of illumination is applied to substrate 24. The illumination may include the activation of appropriate illumination units 60 (Fig. 3) if diffuse illumination is desired, and may also include the interposition of suitable optical filters 106. The illumination may be in the form of bright field illumination, or any combination of suitable dark field illumination.

STEP 230: An image of the substrate is acquired in a digitized form by sensor 48 and channeled to computer image processor 44 (Fig. 3) through frame grabber hardware (not

shown) and software such as a PCI DV frame grabber system, available from EDT, Inc. of Oregon. Preferably, a single full frame image of the substrate is acquired.

STEP 240: The image acquired in step 230 is analyzed for fabrication process defects using image analysis techniques, for example techniques more fully described in U.S. Patent 5,771,068, to the present assignee, the disclosure of which is hereby incorporated by reference. Preferably, these techniques include edge definition and registration functions, and are augmented by fine feature detection techniques for identifying particles and lines such as scratches and rinse tracks. Suitable fine feature detection may be adapted from the ultra fine defect detection described in detail in U.S. patent 5,586,058, incorporated herein by reference.

It is a particular feature of the preferred embodiments of the image acquisition and analysis system that image analysis is preferably performed without reference to an external reference.

Because a properly fabricated substrate should be comprised of evenly deposited films and should not have any residues, streaks, scratches, particles or other similar anomalies thereon, fabrication process flaws generally can be identified as areas on the substrate whose reflected intensities differ from those of surrounding areas by an amount that is less than or greater than a predetermined deviation threshold.

STEP 250: If additional combinations of illumination are required, steps 210 - 240 are repeated.

STEP 260: Upon acquisition and analysis of all desired images, a determination is made, using computer image processor 44, whether process defects exist on the substrate. If a defect is found, a defect report 265 issues. The determination may be made for each substrate, and information about defects may be fed into a data base of defects. Substrates found to contain fabrication process defects may be marked as defective and removed for repair or discarded so that further processing resources will not be wasted on a defective substrate until after it is repaired.

The close temporal proximity of detection of fabrication process flaws to completion of a set of process steps provided by the present invention enables close monitoring of the production and control conditions under which equipment 12 fabricates substrates. Thus, computer 44 is preferably programmed to provide an alarm, or in extreme conditions to shut down equipment, when defective substrates are produced.

For example, computer controller and image processor 44 (Fig. 3) may be tailored to selectively provide an alert or shut down the equipment depending on the nature of the flaw. Thus, if a particular flaw, such as a scratch, that necessitates the discarding of affected substrates, occurs in a predetermined number of sequential substrates, such as three substrates, then the computer controller may automatically shut off the defective equipment to prevent production of additional defective substrates. However, if a less critical flaw, for example the presence of a rinse residue, occurs a number of times but non-sequentially, then the affected substrates can be set aside for repair and an appropriate alert may be made so that the machine can be repaired or adjusted when convenient.

It is appreciated that the system whose operation is described hereinabove with reference to Fig. 10 provides considerable flexibility in determining the particular combination of conditions under which affected equipment is shut down, or an alert is provided.

STEP 280: Those substrates which have been determined not to be flawed are placed in cassettes and removed from the self-contained micro-environment of the equipment, and are transferred to other equipment for the next stage of processing and inspection. Those substrates which have been classified as having repairable flaws may be transferred to a suitable repair station, before subsequent process stages are performed.

Reference is now made to Fig. 11 which illustrates some additional features of preferred embodiments of the present invention. Instead of a single sensor 48 as in the embodiment of Fig. 3, here a plurality of non-scanning staring array sensors 148 is shown. Each of the plurality of sensors 148 preferably images a part of a substrate 150. Images produced by each sensor 148 preferably are stitched together to provide a complete image of substrate 150. This arrangement of sensors 148 enables the processing of a relatively large substrate without compromising resolution and without substantially increasing the height of an enclosure 152, which encloses the inspection region.

Illumination may be provided by illuminators 160. Illuminators 160 are preferably provided with reflectors 162 to direct illumination onto substrate 150, and are preferably pivotably mounted on pivots 164. Drivers (not shown) may be provided to enable tilting of the illuminators 160 and to enable the illumination therefrom to be selectively directed. The illuminators 160 may optionally be provided with diffusers or filters 166.

Reference is now made to Fig. 12 which is a simplified pictorial illustration of an illumination and image acquisition subsystem of an inspection system constructed and operative in accordance with an additional preferred embodiment of the present invention, and to Fig. 13 which is a side view of the illumination and image acquisition subsystem shown in Fig. 12.

In the preferred embodiment shown in Figs. 12 and 13 an illumination and image acquisition subsystem 310 of an inspection system 14 (Fig. 1), is operative to provide selectable combinations of focussed bright field and focussed dark field illumination to a surface of an article under inspection, such as a surface of in-process FPD substrate 24.

Subsystem 310 preferably comprises a substantially fully enclosed inspection enclosure 312 shown in phantom lines. The width and depth dimensions of inspection enclosure 312 are preferably up to about 160 x 180 cm so as to accommodate FPD substrates typically having dimensions of about 73 x 92 cm and to facilitate their rotation about a central axis inside inspection enclosure 312. It is readily appreciated that the above indicated dimensions are representative and are not intended to be limiting and that other dimensions may be employed in order to accommodate various other sizes of substrates. The height of inspection enclosure 312 is preferably up to about 150 cm. Typically, in order to accommodate inspection enclosure 312 inside fabrication equipment 12 (Fig. 1), it is necessary to tilt the inspection enclosure 312 to one side.

A stage 314 is situated in the base of the inspection enclosure 312 for supporting a workpiece, such as an in-fabrication FPD substrate 24, and a non-scanning staring array sensor 316, such as sensor 48 (Fig. 3). Sensor 316 is secured to enclosure 312 overhead of stage 314 and is provided with a suitable lens 319 to view a viewing region 318 along an optical axis 320 (Fig. 13). Viewing region 318 constitutes at least a substantial portion of the surface of substrate 24, and preferably at least one half of substrate 24.

Subsystem 310 preferably includes a concentrating optical element, preferably a reflector 322 that is preferably formed as a section of an ellipsoid having first and second foci 324 and 326 (Fig. 13). An illuminator 328 is configured and arranged to illuminate reflector 322 from first focus 324 and to provide a substantially uniform beam of high intensity light, represented by rays 330, which are concentrated by reflector 322 to second focus 326. Second focus 326 is preferably located away from the surface of substrate 24 along an

illuminating light beam axis 327 which forms an angle α with reference to optical axis 320. The concentrated light provided by the combination of illuminator 328 and reflector 322 is intersected by substrate 24 to illuminate a region on the surface of substrate 24 that is preferably closely coincidental to viewing region 318 (Fig. 13). As is readily appreciated, the beam represented by rays 330 actually never reaches second focus 326, but rather is reflected by substrate 24, which typically has a substantially specular surface, to a third, virtual, focus 332 which is situated along a reflection axis 334 forming an angle θ with respect to optical axis 320.

Illuminator 328 preferably includes a light source 335 and fiber optic unit 336, suitably a 250W DC metal halide light box and fiber optic cable available from Mejiro Precision, Inc. of Tokyo Japan, and a projector 338 configured and operative to shape a beam represented by rays 330 and to project it onto reflector 322 so as to substantially fill reflector 322, without overfill.

Reference is now made to Fig. 14 which is a simplified pictorial illustration of illumination and image acquisition subsystem 310 illustrating axes of inclination and rotation of stage 314 and substrate 24 thereon. Operation of the stage is generally self-explanatory in view of the foregoing discussion with reference to Fig. 5, however it is noted stage 314 may be inclined about an axis of inclination 340 that is located substantially along the median of viewing region 318, so that stage 314 forms an angle of inclination β relative to the horizontal. Additionally, stage 314 may be inclined about axis 342 or rotated around axis 344.

Reference is now made to Fig. 15A – 15E which are simplified side view illustrations of illumination and acquisition subsystem 310 showing the effect of changing the angle of inclination β of stage 314 to effect various spatial orientations between stage 314, projector 338 and sensor 316. As is appreciated from the drawings, reflector 322 is illuminated by projector 338. Stage 314 is inclined about axis 340 to form various selectable angles of inclination β with reference to the horizontal. Preferably, reflector 322 is held in stationary orientation relative to projector 338, to receive a beam emitted by projector 338 at first focus 324. Reflector 322 concentrates the beam represented by rays 330 to second focus 326. However, inasmuch as substrate 24 has a specularly reflective surface, such as the glass of an FPD substrate, the beam represented by rays 330 is reflected so that it focuses at third focus

332 located along reflection axis 334.

As the inclination of stage 314 is changed, angle θ between reflection axis 334 and optical axis 320 changes in accordance with the principal that the angle of reflection off of the specular surface of substrate 24 equals the angle of incidence; accordingly the position of third focus 332 moves in space in relation to the angle of inclination β of stage 314. As shown, the inclination of stage 314 may be adjusted to provide focussed bright field illumination (Fig. 15E) in which rays 330 that are specularly reflected impinge on lens 319. The inclination of stage 314 may also be adjusted to provide focussed dark field illumination, in which rays 330 that are specularly reflected are concentrated to focus at a various locations outside lens 319, along a reflection axis 334, at an angle θ to optical axis 320 (Figs. 15A – 15D). Thus, as seen in Fig. 15A, a large positive value of β results in third focus 332 being located at a relatively large distance from sensor 316. As the inclination of stage 314 is reduced, β is reduced and third focus 332 becomes situated closer to sensor 320 (Fig. 15B). The position of third focus 332 is moved closer to sensor 316 when the inclination of stage 314 is made horizontal, for which $\beta = 0$ (Fig. 15C), and is moved still closer to sensor 316 when the stage 314 inclined below horizontal, for which β is negative (Fig. 15D). Eventually, as stage 314 is further inclined, third focus 332 converges at lens 319 to form focussed bright field illumination (Fig. 15E).

Reference is now made to Fig. 16A and 16B which are simplified pictorial illustrations of illumination and image acquisition subsystem 310 illustrating the effect of diffraction, for example due to a periodic spatial feature on substrate 24, and further illustrating on-axis focussed dark-field and off-axis focussed dark field illumination. It is readily appreciated that the surfaces of substrates typically inspected in inspection system 14, such as FPDs, typically have a dense matrix of liquid crystal cells and conductive connectors which form a two dimensional diffraction grating that diffracts light incident thereon such that diffracted light converges at third focus 332 for a central or zero'th order of diffraction, while other, non-zero, orders of diffraction focus at other focal points in 346.

As seen in Fig. 16A, when stage 314 is in a predetermined spatial orientation, preferably inclined along axis 340 and substantially horizontal along the axis 342, rays 331 from the zero'th order of diffraction converge to focal point 332 which is situated outside lens 319. Rays from non-zero orders of diffraction (not shown) converge at other focal points 346

along mutually orthogonal axes, and at least one non-zero order 347 impinges on lens 319. The illumination configuration in which the zero'th order of diffraction converges at a focus 332 outside sensor 316 and at least one non-zero'th order of diffraction 347 impinges on lens 319 is designated "on-axis focussed dark field illumination".

5 It is appreciated that the inclination of stage 314 relative to axis 340 may be adjusted independently of inclination relative to axis 342. Adjustment of the inclination of axis 340 to form non-horizontal angle β , for example as shown in Figs. 15A, 15B, and 15C, changes the angle θ so that various lower and higher orders of diffraction, respectively, reach lens 319.

10 It is further appreciated that in focussed bright field illumination, the zero'th order of diffraction impinges on lens 319, and non-zero orders of diffraction are located outside lens 319 (not shown).

Referring now to Fig. 16B, it is seen that when stage 314 is inclined along axis 342 at an angle γ , then rays 331 forming the zero'th order of diffraction converge at a focal point 348 while non-zero'th order diffraction converge at points 350. In this arrangement, rays 331 from the zero'th order of diffraction and all other orders of diffraction, along their respective mutually orthogonal axes, converge at foci outside lens 319; preferably no orders of diffraction impinge on lens 319. The illumination of this arrangement is designated "off-axis focussed dark field illumination".

20 Reference is now made to Fig. 17A which is a simplified side view illustration of diffraction occurring in the illumination and image acquisition subsystem 310 which provides focussed dark field illumination as described with reference to Figs. 12 – 16B, and to Fig. 17B which is a simplified side view illustration of the illumination and image acquisition subsystem 410 that provides diffuse dark field illumination, such as is provided by a preferred embodiment described above with reference to Figs. 6 – 8.

As seen in Fig. 17A, in an illumination and image acquisition system 310 which provides focussed illumination, for a clean surface 82 which is free of defects, diffracted rays 352 from a zero'th, or central order of diffraction, designated "0", all converge at third focus 332, preferably independent of the location where projected rays 330 from the projector 338 impinge on reflector 322 or where rays 354 impinge on surface 82 of substrate 24. Likewise, for a clean surface 82 which is free of defects, diffracted rays 356 from other non-zero'th,

orders of diffraction mutually converge at other focal points 350 as a function of the order of diffraction. Thus rays from the same or similar orders of diffraction, such as diffracted rays 356 from each of the diffraction orders I, II and III shown in Fig. 17A, by way of example only, generally converge each at the same regions in space independent of the location where
5 projected rays 330 impinge on reflector 322, or where reflected rays 354 impinge on surface 82 of substrate 24.

For defects on surface 82, such as defect 360, reflected light is typically scattered, thus resulting in scattered rays 362 being reflected differently than diffracted rays 352 and 356, which typically results in a difference in light intensity for defect 362, relative to its
10 surroundings, as viewed by sensor 316.

Referring now to in Fig. 17 B, it is seen that in illumination and image acquisition system 410 which provides diffuse illumination, rays 412 emitted by the diffuse illuminator 413 are emitted in various directions from illuminator 413. As a result, rays 415 from a first point of illumination 416 impinge on substrate 24 at various different locations and at various
15 different angles of incidence. At each location on substrate 24 illuminated by first point of illumination 416, rays 418 from other points of illumination, such as point 420, also impinge on substrate 24 at a various and different angles of incidence.

The effect of the differing angles of incidence emitted from the diffuse illuminator 413 is that the zero'th, or central, orders of diffraction, shown as rays "0", and all other orders of diffraction, shown as orders I, II, III and IV, are diffracted in various and different
20 directions. Consequently, in the diffuse illumination configuration of subsystem 410, various orders of diffraction, exemplified by orders "0", "I", "II", "III" and "IV", rather than a single order of diffraction, or nearly similar orders of diffraction, enter a lens 421 which is associated with a sensor 422.

A defect (not shown) on surface 82 of substrate 24 will typically be seen as a variation
25 in reflective intensity in relation to its surroundings, although the variation may not be as pronounced as in the system shown in Fig. 17A.

In accordance with a preferred embodiment of the present invention, multiple images of substrate are acquired. Each image is acquired using a different configuration of
30 illumination, preferably a focussed bright field illumination and various configurations of focussed dark field illumination. A preferable image acquisition sequence may include the

following combination of illumination configurations: Focussed on-axis dark field illumination for θ values of 15°, 20°, 35°, 50° and 70°. Focussed off-axis dark field illumination for θ values of 70°, and stage 314 inclined along axis 342 to an angle γ value of 10°; Focussed bright field illumination through a narrow band optical filter permitting transmission of a narrow bandwidth of light $\Delta\lambda = \pm 10$ nanometers, for wavelength visible to sensor 316. Preferably, the above sequence, in whole or in part is repeated with stage 314 rotated 90°, 180° and 270° about axis 344 respectively.

Reference is now made to Fig. 18 which is a simplified pictorial illustration of an illumination and image acquisition subsystem of an inspection system constructed and operative in accordance with still another preferred embodiment of the present invention employing a fresnel lens and reflector assembly. In accordance with the preferred embodiment illustrated in Fig. 18, illumination and image acquisition subsystem 370 is configured and arranged to provide focussed dark field and focussed bright field illumination, and is similar in construction and operation to illumination and image acquisition subsystem 310 illustrated in Figs. 12 – 16B.

Illumination and image acquisition subsystem 370 differs from illumination and image acquisition subsystem 310 in that it includes a reflector assembly 372 which is constructed from a planar reflector 374 and a concentrating lens 376, preferably a fresnel lens, which is mounted directly on planar reflector 374. Reflector assembly 372 is preferably configured to emulate operation of an elliptical reflector so as to receive a beam of light, represented by rays 378, from projector 380, which is generally situated at a first focus of reflector assembly 372, and to reflect the light beam represented by rays 378 to a second focus of reflector assembly 372. Substrate 24 intersects the light beam represented by rays 378 so that specularly reflected rays 378 converge at a focus 382 at distance from projector 380.

Reference is now made to Fig. 19 which is a simplified pictorial illustration of an illumination and image acquisition subsystem 390 of an inspection system constructed and operative in accordance with still another preferred embodiment of the present invention employing a transmissive fresnel lens. In accordance with the preferred embodiment illustrated in Fig. 19, illumination and image acquisition subsystem 390 is configured and arranged to provide focussed dark field and focussed bright field illumination.

Illumination and image acquisition subsystem 390 includes a lens 392, preferably a

fresnel lens. Projector 394 is located at a first focus located one side of lens 392. Lens 392 concentrates light emitted by projector 394, represented by rays 396, and substrate 24 intersects the concentrated light so that specularly reflected rays converge at a focus 398.

Reference is now made to Fig. 20, which illustrates another preferred embodiment of the present invention. In the embodiment of Fig. 20, an inspection system 400 constructed and operative in accordance with a preferred embodiment of the present invention, such as any of the systems shown and described with reference to Figs. 3 – 19, is preferably located inside a self-contained ultra-clean micro environment 402 of fabrication equipment 404, which is located inside a clean room area 406 of a fabrication facility, such as fabrication facility 10 (Fig. 1). It is a particular feature of this embodiment that the inspection system is connected to a control unit 408, situated outside the clean room area 406, preferably by means of a cable 410. Control unit is preferably manually operated by a human operator, preferably using a display 412.

As seen in Fig. 20, images of FPD substrates acquired by a sensor in the inspection system 400, may be viewed on display 412, and illumination combinations and camera-substrate angles may be determined by a set routine or controlled by the operator, for example by using a joystick 414, other suitable spatial positioning device, or by choosing positions from a predetermined set. It is appreciated, that the inspection system of Fig. 20 provides for close human control of fabrication and inspection by a remotely located operator, and represents a dramatic improvement over systems that require the physical presence of numerous human inspectors inside clean room areas.

It is appreciated that the particular embodiments described herein are intended to be a detailed disclosure of the invention, and are not intended to be limiting. While various of the features have been described for clarity in the context of separate embodiments, these features may also be provided in a single embodiment. Conversely, various features which have been described in the context of a single embodiment may also be provided separately or in a suitable alternative combination.

It should be also be appreciated by persons skilled in the art that the present invention is not limited to what has been particularly shown and described hereinabove. Rather, the scope of the present invention includes combinations and subcombinations of various features described hereinabove as well as modifications and additions thereto which would occur to a

person of skill in the art upon reading the foregoing description and which are not in the prior art.

CLAIMS

1. A system for manufacture of flat panel displays comprising:
a plurality of manufacturing devices located in a first controlled environment,
5 at least some of said plurality of manufacturing devices each including an enclosure defining
a second controlled environment different from said first controlled environment; and
a plurality of optical inspection devices operative to inspect flat panel display
substrates at various stages of the production thereof by said plurality of manufacturing
devices, at least some of said plurality of optical inspection devices being located within said
10 enclosures defining said second controlled environments.

2. A system for manufacture of flat panel displays comprising wherein the first
controlled environment is an airborne particle controlled environment having a first level of
controlled airborne particulate contamination, and the second controlled environment is an
15 airborne particle controlled environment having a second level of controlled airborne
particulate contamination that is less than the first level of controlled airborne particulate
contamination.

3. A system for manufacture of flat panel displays according to claim 1 or claim
20 2 and wherein said plurality of optical inspection devices are operative in coordination with
said plurality of manufacturing devices for inspecting said substrates prior to transfer thereof
out of said second controlled airborne particle contamination environment.

4. A system for manufacture of flat panel displays according to either of the
25 preceding claims and wherein at least some of said plurality of optical inspection devices
comprise non-scanning sensors.

5. A system for manufacture of flat panel displays according to any of the
preceding claims and wherein said plurality of optical inspection devices are operative to
30 identify fabrication process defects occurring during production of flat panel display
substrates.

6. A system for manufacture of flat panel displays according to claim 5 and wherein said process defects include at least one of the following: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

7. A system for manufacture of flat panel displays according to any of the preceding claims and wherein each of said plurality of optical inspection devices includes at least one non-scanning sensor which views substantially all of the surface of said substrate.

8. A system for manufacture of flat panel displays according to claim 7 and wherein the at least one non-scanning sensor comprises a plurality of non-scanning sensors wherein each sensor views a portion of the substrate and together the plurality of sensors views substantially the entire surface of said substrate.

9. A system for manufacture of flat panel displays according to any of the preceding claims and wherein each of said plurality of optical inspection devices comprises an illuminating array operative to provide various combinations of illumination.

10. A system for manufacture of flat panel displays according to claim 9 in which the combinations include at least dark field and substantially bright field illumination.

11. A system for manufacture of flat panel displays according to claim 9 in which the non-scanning sensor acquires at least one image of the substrate for each combination of illumination.

12. A system for manufacture of flat panel displays according to claim 11 and also comprising an image analyzer for identifying process defects by computer analysis of a plurality of image of the substrate taken under various ones of said combinations of illumination.

13. A system for manufacture of flat panel displays according to claim 12 and wherein said image analyzer is operative without comparison to an external reference.

5 14. A system for manufacture of flat panel displays according to any of the preceding claims and wherein said enclosure contains a first plurality of illuminators mounted on a first wall of said enclosure and a second plurality of illuminators mounted on a second wall of said enclosure, orthogonal to said first wall.

10 15. A system for manufacture of flat panel displays according to any of the preceding claims and also comprising directionally adjustable illuminators..

15 16. An inspection system for use in inspecting flat panel displays comprising:
a non-scanning optical array for viewing a flat panel display substrate; and
an illumination subsystem sequentially providing dark field and bright field
illumination of said flat panel display substrate when said optical array views at least a part of
said flat panel display substrate.

20 17. An inspection system according to claim 16 and wherein said illumination subsystem provides various combinations of dark field and bright field illumination of said flat panel display substrate when said optical array views said flat panel display substrate.

25 18. An inspection system according to claim 17 and wherein said dark field and said bright field illumination are diffuse .

19. An inspection system according to claim 17 and wherein said dark field and said bright field illumination are focussed.

30 20. An inspection system according to claim 19 and wherein said flat panel display substrate has a surface that includes a periodic spatial feature, and said dark field and said bright field illumination are diffracted by said spatial feature.

21. An inspection system according to any of claims 17 – 20 and also comprising a spatially positionable stage to support the flat panel display substrate, wherein the stage spatially positions the substrate at various angles relative to the illumination subsystem.

22. An inspection system according to claim 21 and wherein the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the flat panel display substrate such that a non-zero'th order of diffraction impinges on the non-scanning optical array.

23. An inspection system according to claim 22 and wherein a multiplicity of the non-zero'th orders of diffraction of a similar order impinge on said non-scanning optical array.

24. An inspection system according to either of claims 22 and 23 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the flat panel display substrate such that a zero'th order of diffraction impinges on the non-scanning optical array.

25. An inspection according to any of claims 22 – 24 and wherein the optical array the illumination subsystem and the stage are configured and arranged to additionally enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

26. An inspection system according to claim 25 and wherein the optical array and the illumination subsystem are configured and arranged to sequentially view the flat panel display substrate and wherein in one view a selected non-zero'th order of diffraction impinges on the optical array, and in other each sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional selected non-zero'th order of diffraction, no order of diffraction, the same non-zero'th order of diffraction of a different region of the article.

27. An inspection system according to any of claims 21 – 26 and also comprising an image analyzer receiving an output from said non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate. scratches, lines, and particles embedded in the substrate.

28. An inspection system according to any of claims 17 – 18 and wherein said optical array views substantially all of a surface of said substrate.

29. An inspection system according to any of claims 17 – 18 and wherein said optical array views only part of a surface of said substrate.

30. An inspection system according to any of claims 17 - 29 and wherein said optical array acquires at least one image of said substrate for each of a plurality of different illuminations.

31. An inspection system according to claim 27 in which an image analyzer identifies said defects by computer analysis of a plurality of images of said substrate taken under differing illumination.

32. An inspection system according to any of claims 17 – 21 and also comprising an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

33. An inspection system according to claim 32 and also comprising a third illuminator mounted on a third wall of said enclosure.

34. An inspection system according to any of claims 17 – 23 and also comprising a diffuser associated with said illumination subsystem.

35. An inspection system according to any of claims 17 – 21 and also comprising a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

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36. An inspection system according to claim 35 wherein said reflector has two points of focus, and wherein a projector is situated at a first of points of focus, and the second point of focus is situated away from the flat panel display substrate.

10 37. An inspection system according to claim 36 and wherein the reflector is a section of an ellipsoid.

38. An inspection system according to claim 36 and wherein the reflector is flat and is operatively associated with a lens.

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39. An inspection system according to claim 38 and wherein the lens is a fresnel lens attached to the reflector.

40. An inspection system according to any of claims 17 – 21 and also comprising a light source and a lens operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

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41. An inspection system according to claim 40 wherein the projector is situated at a first focus of the lens, and a second focus of the lens is situated away from the flat panel display substrate.

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42. An inspection system according to any of claims 17 – 41 and comprising an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said substrate.

30

43. An inspection system for use in inspecting surfaces of articles comprising:
a non-scanning optical array for viewing a surface of an article; and
an illumination subsystem sequentially providing dark field and bright field
illumination of said surface while said optical array views said surface.

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44. An inspection system according to claim 43 and wherein said illumination
subsystem provides various combinations of dark field and bright field illumination of said
surface when said optical array views said surface.

10 45. An inspection system according to claim 44 and wherein said dark field and
said bright field illumination are diffuse .

46. An inspection system according to claim 44 and wherein said dark field and
said bright field illumination are focussed.

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47. An inspection system according to claim 46 and wherein said surface includes
a periodic spatial feature operative to diffract light impinging thereon.

48. An inspection system according to any of claims 43 – 47 and also comprising a
20 spatially positionable stage to support the article, wherein the stage spatially positions the
article at various angles relative to the illumination subsystem.

49. An inspection system according to claim 48 and wherein the optical array,
illumination subsystem and stage are configured and arranged to selectively enable viewing
25 the surface such that a non-zero'th order of diffraction impinges on the non-scanning optical
array.

50. An inspection system according to claim 49 and wherein a multiplicity of non-
zero'th orders of diffraction of substantially the same order impinge on the non-scanning
30 optical array.

51. An inspection system according to either of claims 49 and 50 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing of the surface such that a zero'th order of diffraction impinges on the non-scanning optical array.

5

52. An inspection according to any of claims 49 – 51 and wherein the optical array the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the object such that substantially no orders of diffraction impinge on the non-scanning optical array.

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53. An inspection system according to claim 52 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to sequentially view the object and wherein in one view a selected non-zero order of diffraction impinges on the optical array, and in other sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional non-zero'th order of diffraction, the same non-zero'th order of diffraction of a different region of the surface of the article, and no order of diffraction.

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54. An inspection system according to any of claims 43 – 53 and also comprising an image analyzer receiving an output from said non-scanning optical array and being operative to detect process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

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55. An inspection system according to any of claims 43 - 54 and wherein said optical array views substantially all of a surface of said substrate.

56. An inspection system according to any of claims 43 - 54 and wherein said optical array views only a part of a surface of said substrate.

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57. An inspection system according to any of claims 43 – 56 and wherein said optical array acquires at least one image of said substrate for each of a plurality of different illuminations.

5 58. An inspection system according to claim 54 in which image analyzer identifies said defects by computer analysis of a plurality of images of said substrate taken under differing illuminations.

59. An inspection system according to any of claims 43 - 58 and also comprising
10 an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

60. An inspection system according to claim 59 and also comprising a third
15 illuminator mounted on a third wall of said enclosure.

61. An inspection system according to any of claims 43 - 60 and also comprising
a diffuser associated with said illumination subsystem.

62. An inspection system according to any of claims 50 – 58 and also comprising a
20 light source and a reflector operative to provide concentrated light from the light source to at least part of said surface.

63. An inspection system according to claim 62 wherein said reflector has two
25 points of focus, and wherein a projector is situated at a first focus, and a second focus is situated not on the surface.

64. An inspection system according to claim 63 and wherein the reflector is a
section of an ellipsoid.

30 65. An inspection system according to claim 64 and wherein the reflector is flat and is operatively associated with a lens.

66. An inspection system according to claim 65 and wherein the lens is a fresnel lens attached to the reflector.

5 67. An inspection system according to any of claims 44 - 58 and also comprising a light source and a lens operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

68. An inspection system according to claim 67 wherein a projector is situated at a
10 first focus of the lens, and a second focus of the lens is situated not on the flat panel display substrate.

69. An inspection system according to any of claims 43 - 61 and comprising an adjustable mounting assembly for selectably determining at least one of relative inclination,
15 spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said substrate.

70. Apparatus for optically inspecting a substantially planar surface of an article, comprising:

20 an inspection region;
an illuminator to selectably illuminate a substantially planar surface of an article located in the inspection region with at least two predetermined configurations of illumination;

25 an image acquisition sub-system comprising at least one non-scanning camera for acquiring images of the surface of the article when illuminated by at least one predetermined configuration of illumination; and

an image analysis subsystem for computer analysis of the images and detecting anomalies in the surface as a function of variations in reflected intensities of illumination.

30 71. Apparatus for optically inspecting the surface of an article according to claim 70 and also comprising a spatially positionable stage for supporting the article in the

inspection region in selectable orientation relative to the illumination apparatus.

72. Apparatus for optically inspecting the surface of an article according to any of claims 70 – 37, wherein the image analysis subsystem is operative to identify anomalies that are substantially at least as large as the resolution of the camera.

73. Apparatus for coating an article having a substantially planar surface, comprising:

a coating generator operative to generate a coating on a surface of the article;

an illuminator selectably illuminating said surface bearing said coating with at least two predetermined configurations of illumination;

an image acquisition sub-system comprising at least one non-scanning sensor for acquiring images of the surface of the article for each combination of illumination; and

an image analysis subsystem for analyzing the images and detecting anomalies in the surface on the basis of variations in reflected intensities of illumination.

74. Apparatus for inspecting an article in a clean room, comprising:

an inspection device situated in a clean room and including:

an inspection stage selectably positionable by remote control;

at least one non-scanning sensor viewing a part of the entire inspection stage;

an array of illuminators illuminating the part of inspection stage viewed by the sensor;

automated feed apparatus;

a control station situated outside the clean room including a viewer for viewing articles placed in the inspection device, and a controller for positioning the stage and providing selected combinations of illumination to illuminate the article.

75. A method for manufacture of flat panel displays comprising:

providing a plurality of manufacturing devices located in a first controlled airborne particle contamination environment, at least some of said plurality of manufacturing devices each including an enclosure defining a second controlled airborne particle

contamination environment having a lower level of contamination than that of said first controlled airborne particle contamination environment; and

inspecting flat panel display substrates at various stages of the production thereof by said plurality of manufacturing devices at a location within said enclosures
5 defining said second controlled airborne particle contamination environments.

76. A method according to claim 75 and wherein said inspecting step comprises inspecting said substrates prior to transfer thereof out of said second controlled airborne particle contamination environment.

10

77. A method according to either of claims 75 and 76 and wherein said inspecting step comprises inspecting using non-scanning sensors.

78. A method according to any of claims 75 - 77 and further comprising
15 identifying fabrication process defects occurring during production of flat panel display substrates.

79. A method according to claim 78 and wherein said identifying step comprises identifying process defects including at least one of the following: uneven deposition of
20 coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

80. A method according to any of claims 75 - 79 and wherein said inspecting step
25 comprises inspecting using at least one non-scanning sensor which views substantially all of the surface of said substrate.

81. A method according to claim 80 and wherein said inspecting step comprises inspecting using a plurality of non-scanning sensors wherein each sensor views a portion of
30 the substrate and together the plurality of sensors view substantially the entire surface of said substrate.

82. A method according to any of claims 75 - 81 and wherein said inspecting step comprises illuminating the substrate with an illuminating array operative to provide various combinations of illumination.

5

83. A method according to claim 82 in which the combinations include at least dark field and substantially bright field illumination.

84. A method according to claim 82 and wherein said inspecting step comprises acquiring at least one image of the substrate for each combination of illumination using said non-scanning sensor.

85. A method according to claim 84 and also comprising performing image analysis of the process defects by computer analysis of a plurality of images of the substrate taken under various ones of said combinations of illumination.

86. A method according to claim 85 and wherein said image analysis step is performed without comparison to an external reference.

87. A method according to any of claims 75 - 86 and wherein said providing step comprises further providing said enclosure with a first plurality of illuminators mounted on a first wall of said enclosure and a second plurality of illuminators mounted on a second wall of said enclosure, orthogonal to said first wall.

88. A method according to any of the preceding claims 75 - 87 and wherein said providing step comprises further providing directionally adjustable illuminators.

89. A method for inspecting flat panel displays comprising:
viewing a flat panel display substrate using a non-scanning optical array; and
sequentially illuminating said flat panel display substrate with dark field and bright field illumination when said optical array views said flat panel display substrate.

90. A method according to claim 89 and wherein said sequentially illuminating step illuminates using various combinations of dark field and bright field illumination of said flat panel display substrate when said optical array views said flat panel display substrate.

5

91. A method according to claim 90 and also comprising supporting the substrate with a spatially positionable stage, and spatially positioning the stage at various angles to illuminate the substrate with dark field and bright field illumination.

10

92. A method according to claim 90 or claim 91 and also comprising: receiving an output from said non-scanning optical array; and detecting process defects including at least one of: uneven deposition of coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

15

93. A method according to any of claims 89 - 92 and wherein said viewing step comprises viewing substantially all of a surface of said substrate.

20

94. A method according to any of claims 89 - 93 and wherein said viewing step comprises acquiring at least one image of said substrate for each of a plurality of different illuminations.

25

95. A method according to claim 92 and wherein said detecting step comprises identifying said defects by computer analysis of a plurality of images of said substrate taken under differing illumination.

30

96. A method according to any of claims 89 - 95 and also comprising providing an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

97. A method according to claim 96 and wherein said providing step also comprises providing a third illuminator mounted on a third wall of said enclosure.

5 98. A method according to any of claims 89 - 97 and also comprising providing a diffuser associated with said illumination subsystem.

99. A method according to any of claims 89 - 64 and also comprising providing an adjustable mounting assembly for selectably determining at least one of relative inclination,
10 spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said substrate.

100. A method for inspecting objects comprising:
viewing an object using a non-scanning optical array; and
15 sequentially illuminating said object with dark field and bright field illumination when said optical array views said object.

101. A method according to claim 96 and wherein said sequentially illuminating step illuminates using various combinations of dark field and bright field illumination of said
20 object when said optical array views said object.

102. A method according to claim 101 and also comprising:
receiving an output from said non-scanning optical array; and
detecting process defects including at least one of: uneven deposition of
25 coatings, uneven removal of coatings, rinse residues, chemical residues, incomplete exposure of a photo-resist deposited on the substrate, scratches, lines, and particles embedded in the substrate.

103. A method according to any of claims 100 - 102 and wherein said viewing
30 step comprises viewing substantially all of a surface of said object.

104. A method according to any of claims 100 – 103 and wherein said viewing step comprises acquiring at least one image of said object for each of a plurality of different illuminations.

5 105. A method according to claim 102 and wherein said detecting step comprises identifying said defects by computer analysis of a plurality of images of said object taken under differing illumination.

10 106. A method according to any of claims 100 – 105 and also comprising providing an enclosure containing a first plurality of illuminators mounted on one wall thereof and a second plurality of illuminators mounted on a second wall thereof.

15 107. A method according to claim 106 and wherein said providing step also comprises providing a third illuminator mounted on a third wall of said enclosure.

108. A method according to any of claims 100 – 107 and also comprising providing a diffuser associated with said illumination subsystem.

20 109. A method according to any of claims 100 – 108 and also comprising providing an adjustable mounting assembly for selectably determining at least one of relative inclination, spatial separation and axial orientation of at least two of said optical array, said illumination subsystem and said object.

25 110. A method for optically inspecting the surface of an article having a substantially planar surface, comprising:

defining an inspection region;

selectably illuminating the surface of an article located in the inspection region with at least two predetermined configurations of illumination;

30 acquiring images of the surface of the article when illuminated by at least one predetermined configuration of illumination using at least one non-scanning camera; and

analyzing the images and detecting anomalies in the surface as a function of

variations in reflected intensities of illumination.

111. A method for optically inspecting the surface of an article according to claim 110 and also comprising supporting the article on a spatially positionable stage in the inspection region, and selectably spatially orienting the stage relative to a predetermined configuration of illumination.

112. A method for optically inspecting the surface of an article according to claim 110 or 111, wherein the analyzing step is operative to identify anomalies that are substantially the same size as the resolution of the non-scanning camera.

113. A method for coating an article having a substantially planar surface, comprising:
generating a coating on a surface of the article;
selectably illuminating said surface bearing said coating with at least two predetermined configurations of illumination;
acquiring images of the surface of the article for each combination of illumination using at least one non-scanning sensor; and
analyzing the images and detecting anomalies in the surface on the basis of variations in reflected intensities of illumination.

114. A method for inspecting an article in a clean room, comprising:
situating an inspection device in the clean room;
selectably positioning an inspection stage of said inspection device by remote control;
viewing substantially the entire inspection stage using at least one non-scanning sensor of said inspection device;
illuminating the inspection stage using an array of illuminators of said inspection device;
placing articles in the inspection device using automated feed apparatus of said inspection device; and

situating a remote controller outside the clean room for viewing articles placed in the inspection device, said remote controller comprising a viewer and a controller for remotely positioning the stage and selecting combinations of illumination.

- 5 115. A method for inspecting the surface of an article, comprising the steps of:
placing the article in an inspection region defined by a stage;
illuminating a portion of the surface of the article with at least one
configuration of dark field illumination;
acquiring an image of substantially the entire surface for the at least one
10 configuration of dark field illumination;
illuminating the surface with at least one configuration of at least substantially
bright field illumination;
acquiring an image of substantially the entire surface for the at least one
configuration of at least substantially bright field illumination; and
15 analyzing the images by computer to determine non uniformities in reflected
intensities.

116. The method of claim 115 in which the at least one configuration of dark field
illumination comprises a plurality of dark field illumination combinations, and separate
20 images are acquired for each of the combinations.

117. The method of claim 115 in which the at least one configuration of
substantially bright illumination comprises a plurality of bright field illumination
combinations, and separate images are acquired for each of the combinations.

- 25 118. The method of claim 117 comprising the additional step of selecting for each
predetermined combination of illumination a predetermined inclination and orientation of the
substrate, and acquiring separate images of the surface for each said inclination and axial
orientation.

- 30 119. The method of claim 115 comprising the additional step of optically treating

the illumination prior to acquiring an image.

120. The method of claim 119 in which the treatment is provided by optical filters.

5 121. The method of claim 120 in which the optical filters filter light at all but selected wavelengths.

122. The method of claim 120 in which the filters filter light to transmit light having a selected polarization.

10

123. The method of claim 119 in which the surface is illuminated with a selected combination of broad spectrum illumination and imaged through an optical filter operative to transmit light in a first predetermined spectral range, and subsequently imaged through an optical filter operative to transmit light in a second predetermined spectral range.

15

124. The method of claim 119 in which the surface is illuminated with a first combination illumination provided in first predetermined spectral range and imaged, and subsequently illuminated with a second combination of illumination provided in a second predetermined spectral range and imaged.

20

125. The method of claim 119 in which the surface is illuminated with a selected combination of broad spectrum illumination and imaged through an optical filter operative to transmit light in a first predetermined polarization, and subsequently imaged through an optical filter operative to transmit light having a predetermined polarization.

25

126. The method of claim 119 in which the surface is illuminated with a first combination of illumination having a first predetermined polarization and imaged, and subsequently illuminated with a second combination of illumination having a second predetermined polarization and imaged.

30

127. The method of claim 115 comprising the additional step of blurring the image

during acquisition.

128. The method of claim 127 in which the at least one image is blurred by introducing relative movement between at least two of the following: the surface, the camera,
5 and an optical element between the surface and the camera.

129. The method of claim 115 comprising the further step of analyzing said non-uniformities by computer to determine the presence of defects in coatings on the substrate.

10 130. The method of claim 115 in which the article is a flat display panel substrate.

131. A method for coating the surface of an article with a film, comprising the steps of:

15 depositing a film coating on at least part of a surface of the article; placing the article in an inspection region;

illuminating a portion of the coated surface of the article with at least one configuration of dark field illumination;

acquiring an image of the surface illuminated by the at least one configuration of dark field illumination;

20 illuminating the surface with at least one configuration of substantially bright field illumination;

acquiring an image of the entire surface illuminate by the least one configuration of substantially bright field illumination; and

25 analyzing each image by computer to determine non uniformities in reflected intensities.

132. Apparatus for automatic optical inspection of generally flat articles having at least one generally periodic spatial feature, comprising:

30 a light beam generator providing an illuminating beam of light along an illuminating light beam axis onto a generally flat article having at least one at least generally periodic spatial feature; and

a sensor viewing the article along a light receiving axis disposed at an angle with respect to the illumination light beam axis whereby a generally non-zero'th orders of diffracted light reflected from said article impinges on a lens of said sensor.

5 133. Apparatus according to claim 132 and wherein the sensor is a staring array sensor operative to view at least a portion of the article.

134. Apparatus according to either of claims 132 and 133 and also comprising a positioner for changing the spatial orientation of the generally flat article with respect to the
10 illumination light beam axis and said light receiving axis.

135. Apparatus according to claim 133 and wherein said positioner is operative to selectably spatially position the generally flat article so that it lies in a plane which is angularly inclined to the plane defined by the illuminating light beam axis and the light
15 receiving axis.

136. Apparatus according to claim 135 and wherein said positioner is operative to selectively provide various spatial orientations of the flat article so that a sequence of various non-zero'th orders of diffracted light from the illuminating beam impinge on said sensor.
20

137. Apparatus according to claim 135 and wherein said positioner is operative to selectively provide various spatial orientations of the flat article so that a non-zero'th order of diffracted light from the illuminating beam impinges on said sensor, and in sequence at least one of the following orders of diffracted light from the illuminating beam impinges on said
25 sensor: an additional non-zero'th order, a zero'th order, no order.

138. Apparatus according to and of preceding claims 134 – 137 and wherein said sensor acquires an image of the article for each spatial orientation of the article.

30 139. A method for automatic optical inspection of generally flat articles having at least one generally periodic spatial feature, comprising:

generating an illuminating beam of light along an illuminating light beam axis onto a generally flat article having at least one at least generally periodic spatial feature; and sensing light reflected by the article along a light receiving axis disposed at an angle with respect to the illumination light beam axis whereby a generally non-zero'th order of diffracted light reflected from said article impinges on a lens of said sensor.

140. A method according to claim 139 and wherein the sensing step is performed using a staring array sensor operative to view at least a portion of the article.

141. A method according to either of claims 139 and 140 and also comprising changing the spatial orientation of the generally flat article with respect to the illumination light beam axis and said light receiving axis.

142. A method according to claim 140 and wherein said changing spatial orientation step includes selectably positioning the generally flat article so that it lies in a plane which is angularly inclined to the plane defined by the illuminating light beam axis and the light receiving axis.

143. A method according to claim 142 and wherein the spatial orientation step includes selectively providing various spatial orientations of the flat article so that a sequence of various non-zero'th orders of diffracted light from the illuminating beam impinge on said sensor.

144. Apparatus according to claim 142 and wherein the spatial orientation step includes selectively providing various spatial orientations of the flat article so that a non-zero'th order of diffracted light from the illuminating beam impinges on said sensor, and in sequence at least one of the following orders of diffracted light from the illuminating beam impinges on said sensor: an additional non-zero'th order, a zero'th order, no order.

145. Apparatus according to any of preceding claims 141 – 144 and wherein said sensing step includes acquiring an image of the article for each spatial orientation of the

article.

146. A method for manufacturing flat panel displays comprising the steps of:
providing a first controlled environment in which an airborne particle
5 controlled environment having a first level of controlled airborne particulate contamination,
and a second controlled environment in which an airborne particle controlled environment
having a second level of controlled airborne particulate contamination is less than the first
level of controlled airborne particulate contamination.

10 147. A method according to claim 89 and wherein said dark field and said bright
field illumination are diffuse.

148. A method according to claim 89 and wherein said dark field and said bright
field illumination are focussed.

15 149. A method according to claim 148 and wherein said flat panel display substrate
has a surface that includes a periodic spatial feature, and said dark field and said bright field
illumination are diffracted by said spatial feature.

20 150. A method according to claim 99 and wherein the optical array, illumination
subsystem and stage are configured and arranged to selectively enable viewing the flat panel
display substrate such that a non-zero'th order of diffraction impinges on the non-scanning
optical array.

25 151. A method according to claim 150 and wherein a multiplicity of the non-zero'th
orders of diffraction of a similar order impinge on said non-scanning optical array.

152. A method according to either of claims 150 and 151 and wherein the optical
array, the illumination subsystem and the stage are configured and arranged to additionally
30 enable selectively viewing the flat panel display substrate such that a zero'th order of
diffraction impinges on the non-scanning optical array.

153. A method according to any of claims 150 – 152 and wherein the optical array the illumination subsystem and the stage are configured and arranged to additionally enable selective viewing of the flat panel display substrate such that substantially no orders of diffraction impinge on the non-scanning optical array.

154. A method according to claim 153 and wherein the optical array and the illumination subsystem are configured and arranged to sequentially view the flat panel display substrate and wherein in one view a selected non-zero'th order of diffraction impinges on the optical array, and in other each sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional selected non-zero'th order of diffraction, no order of diffraction, the same non-zero'th order of diffraction of a different region of the article.

155. A method according to any of claims 89 – 95 and also comprising providing a light source and a reflector operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

156. A method according to claim 155 wherein said reflector has two points of focus, and wherein a projector is situated at a first of points of focus, and the second point of focus is situated away from the flat panel display substrate.

157. A method according to claim 156 and wherein the reflector is a section of an ellipsoid.

158. A method according to claim 156 and wherein the reflector is flat and is operatively associated with a lens.

159. A method according to claim 158 and wherein the lens is a fresnel lens attached to the reflector.

160. A method according to any of claims 89 – 95 and also comprising providing a light source and a lens operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

5 161. A method according to claim 160 wherein the projector is situated at a first focus of the lens, and a second focus of the lens is situated away from the flat panel display substrate.

10 162. A method according to claim 90 and wherein said dark field and said bright field illumination are diffuse .

163. A method according to claim 90 and wherein said dark field and said bright field illumination are focussed.

15 164. A method according to claim 163 and wherein said surface includes a periodic spatial feature operative to diffract light impinging thereon.

20 165. A method according to any of claims 89, 90 and 160 - -164 and also comprising providing a spatially positionable stage to support the article, wherein the stage spatially positions the article at various angles relative to the illumination subsystem.

25 166. A method according to claim 165 and wherein the optical array, illumination subsystem and stage are configured and arranged to selectively enable viewing the surface such that a non-zero'th order of diffraction impinges on the non-scanning optical array.

167. A method according to claim 166 and wherein a multiplicity of non-zero'th orders of diffraction of substantially the same order impinge on the non-scanning optical array.

30 168. A method according to either of claims 166 and 167 and wherein the optical array, the illumination subsystem and the stage are configured and arranged to additionally

enable selectively viewing of the surface such that a zero'th order of diffraction impinges on the non-scanning optical array.

169. A method according to any of claims 166 – 168 and wherein the optical array
5 the illumination subsystem and the stage are configured and arranged to additionally enable selectively viewing the object such that substantially no orders of diffraction impinge on the non-scanning optical array.

170. A method according to claim 169 and wherein the optical array, the
10 illumination subsystem and the stage are configured and arranged to sequentially view the object and wherein in one view a selected non-zero order of diffraction impinges on the optical array, and in other sequential views at least one of the following impinges on the optical array: a zero'th order of diffraction, an additional non-zero'th order of diffraction, the same non-zero'th order of diffraction of a different region of the surface of the article, and no
15 order of diffraction.

171. A method according to any of claims 89 - 92 and wherein said optical array views only a part of a surface of said substrate.

172. A method according to any of claims 89 – 95 and 167 – 169 and also
20 comprising providing a light source and a reflector operative to provide concentrated light from the light source to at least part of said surface.

173. A method according to claim 172 wherein said reflector has two points of
25 focus, and wherein a projector is situated at a first focus, and a second focus is situated not on the surface.

174. A method according to claim 173 and wherein the reflector is a section of an
30 ellipsoid.

175. A method according to claim 174 and wherein the reflector is flat and is

operatively associated with a lens.

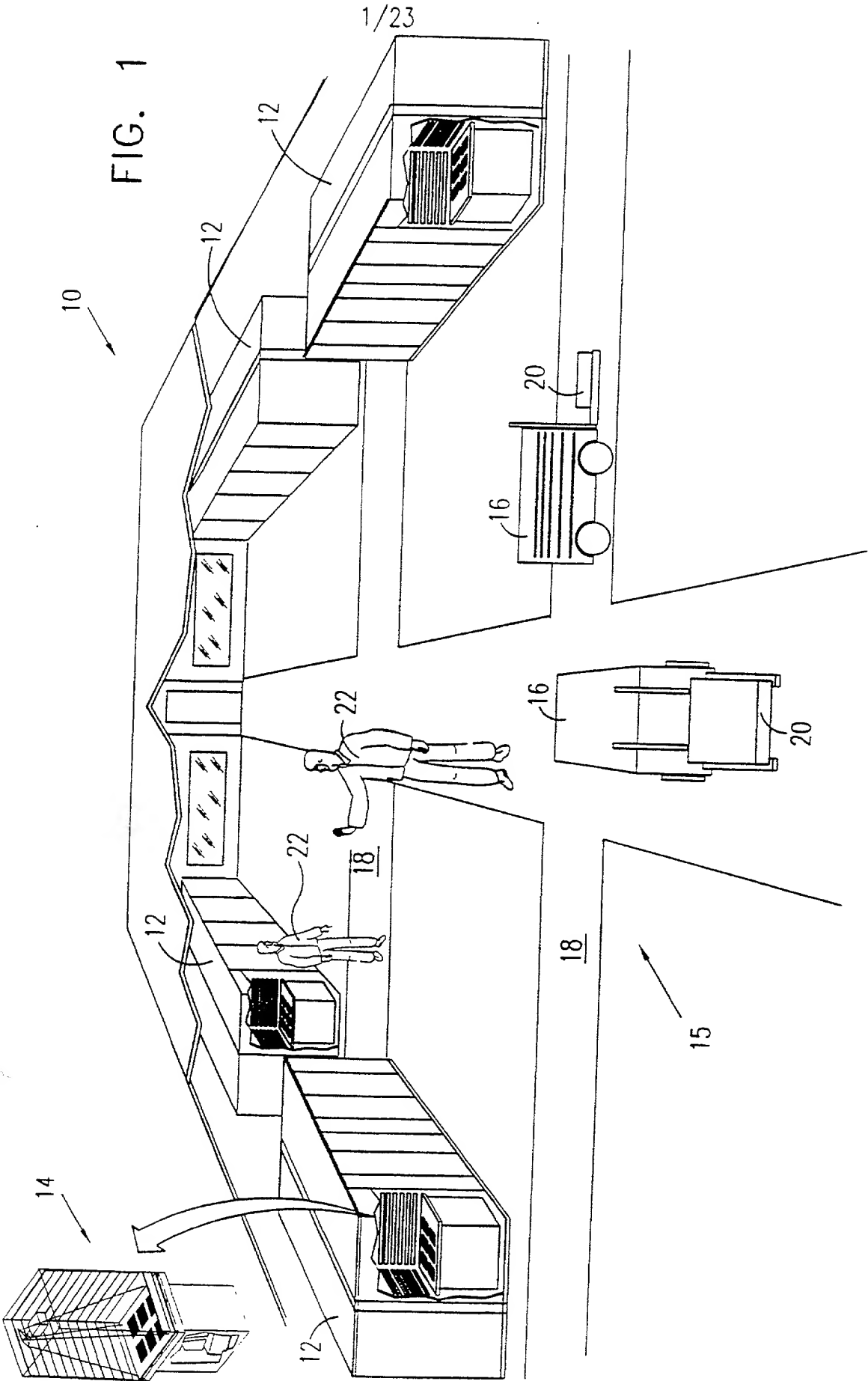
176. A method according to claim 175 and wherein the lens is a fresnel lens attached to the reflector.

5

177. A method according to any of claims 89 - 95 and also comprising providing a light source and a lens operative to provide concentrated light from the light source to at least part of said flat panel display substrate.

10 178. A method according to claim 177 providing a projector which is situated at a first focus of the lens, and a second focus of the lens is situated not on the flat panel display substrate.

15 179. A method according to any of claims 75 - 79 and wherein said optical array views only part of a surface of said substrate.



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FIG. 2A

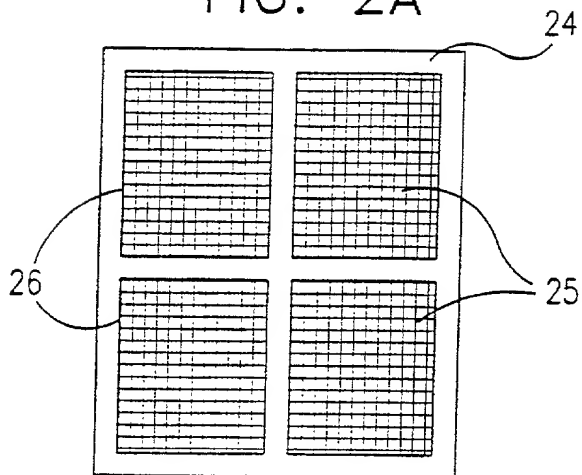


FIG. 2B

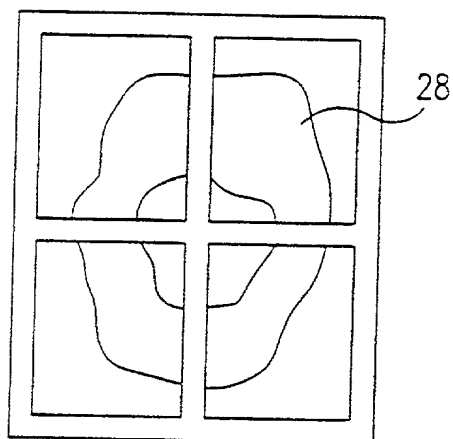


FIG. 2C

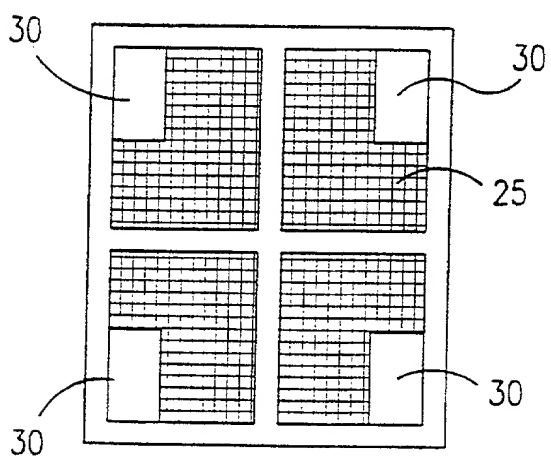


FIG. 2D

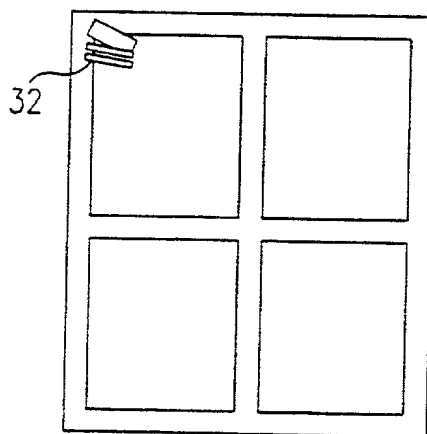
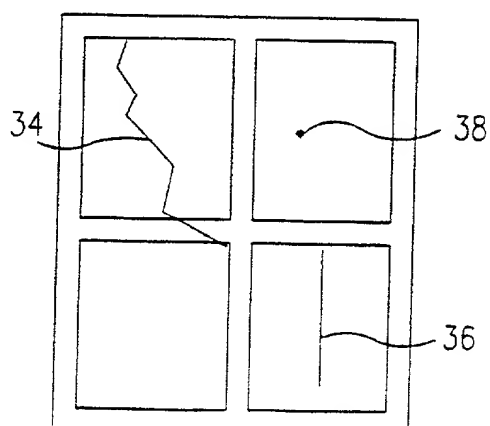


FIG. 2E



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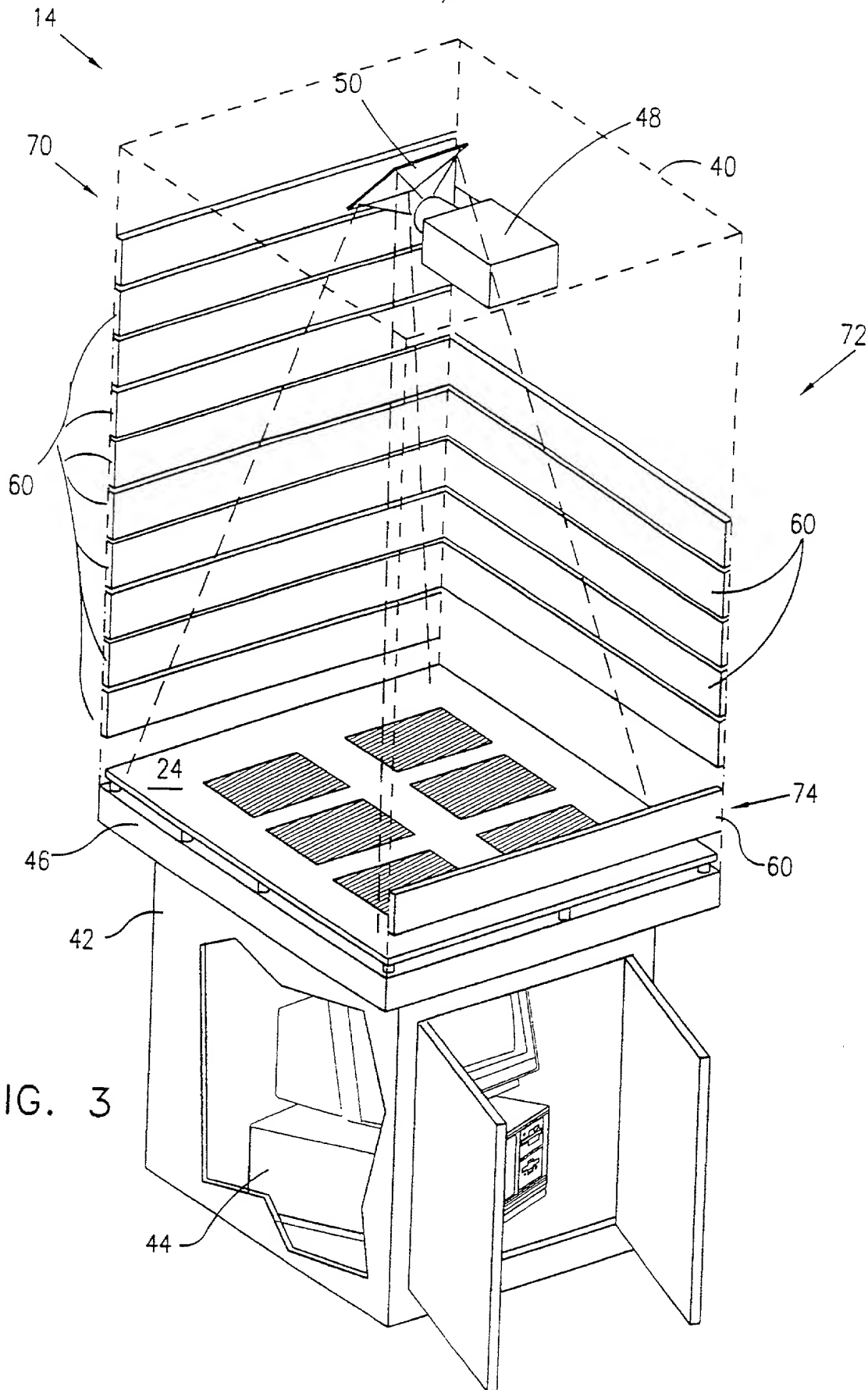
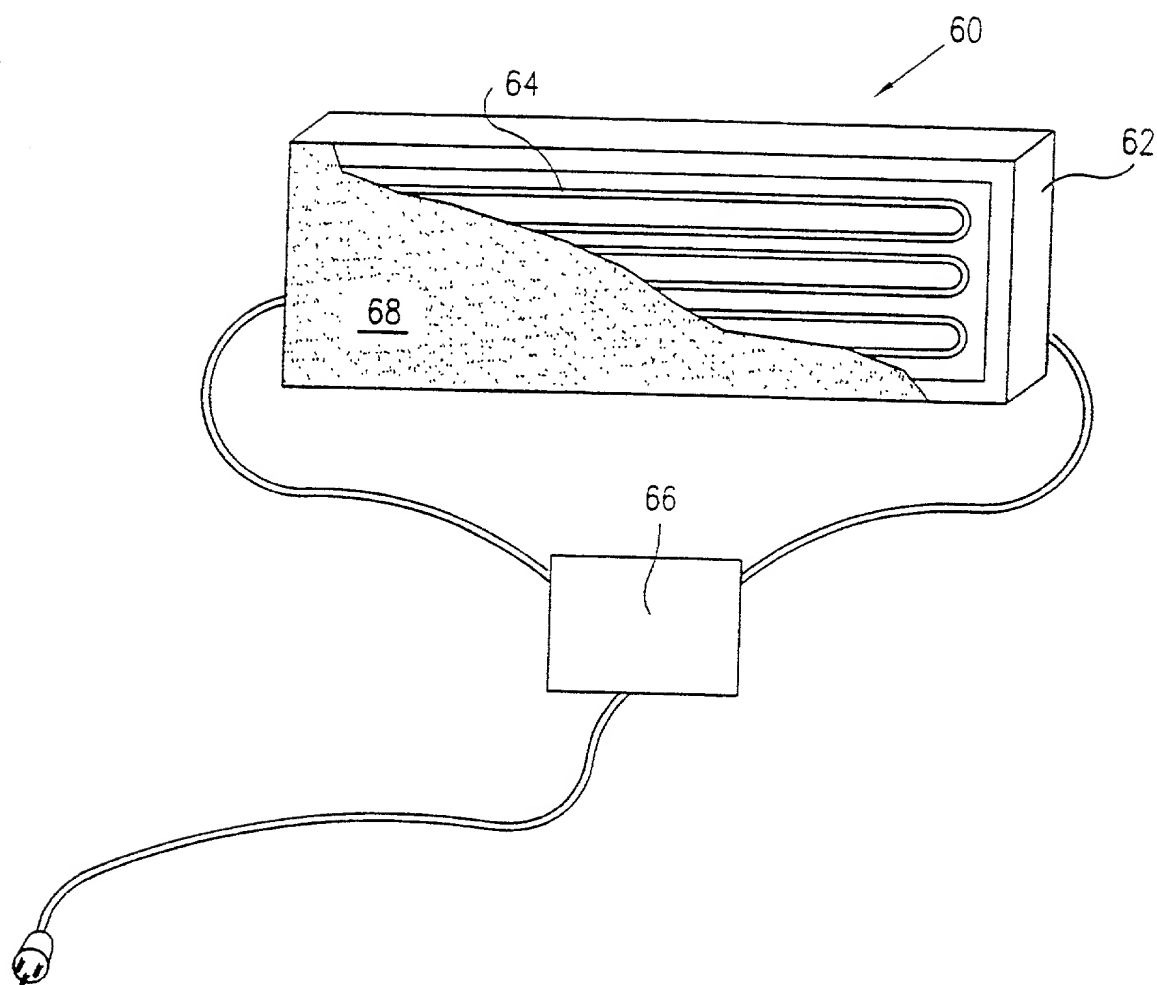


FIG. 3

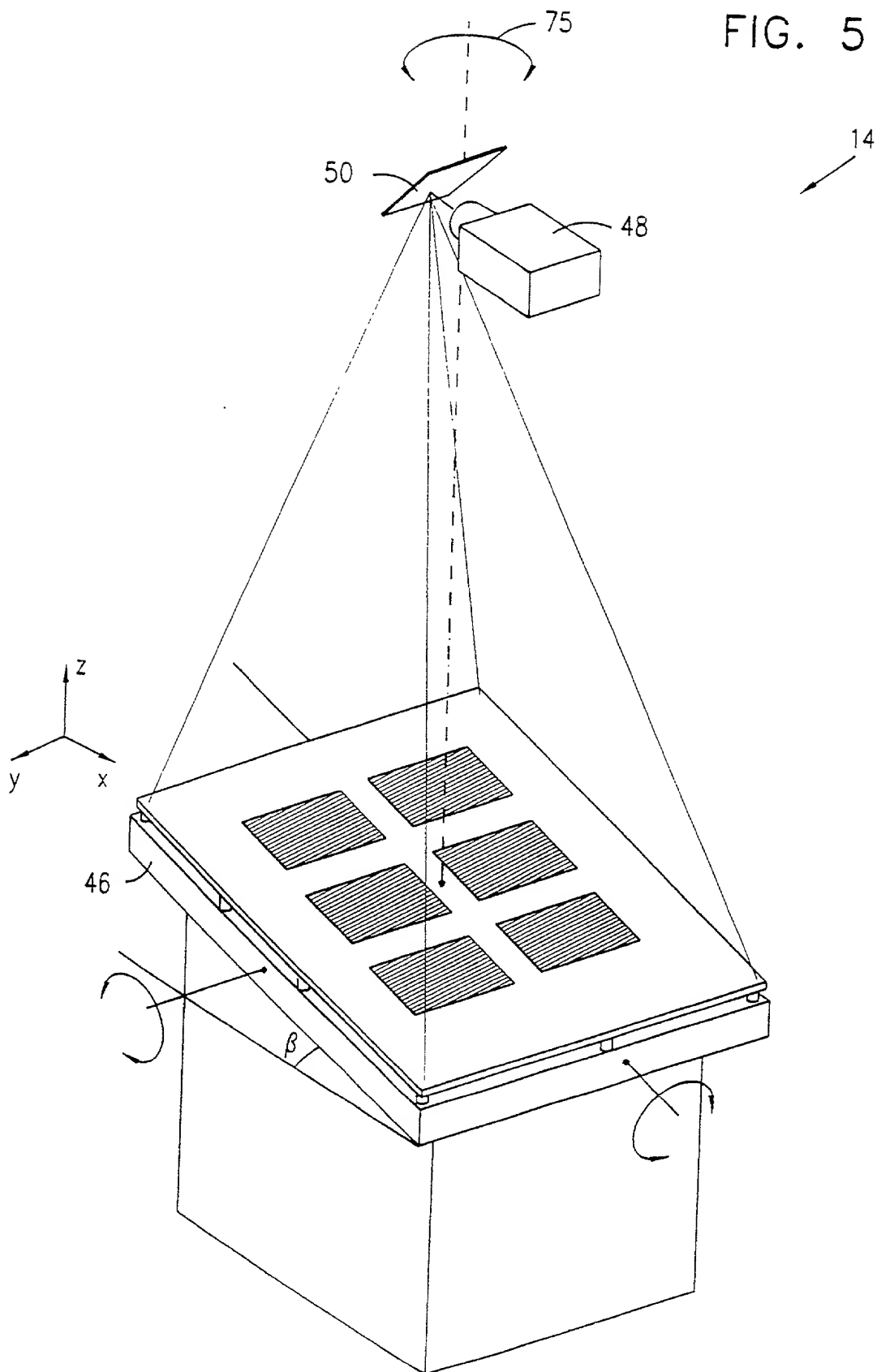
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FIG. 4



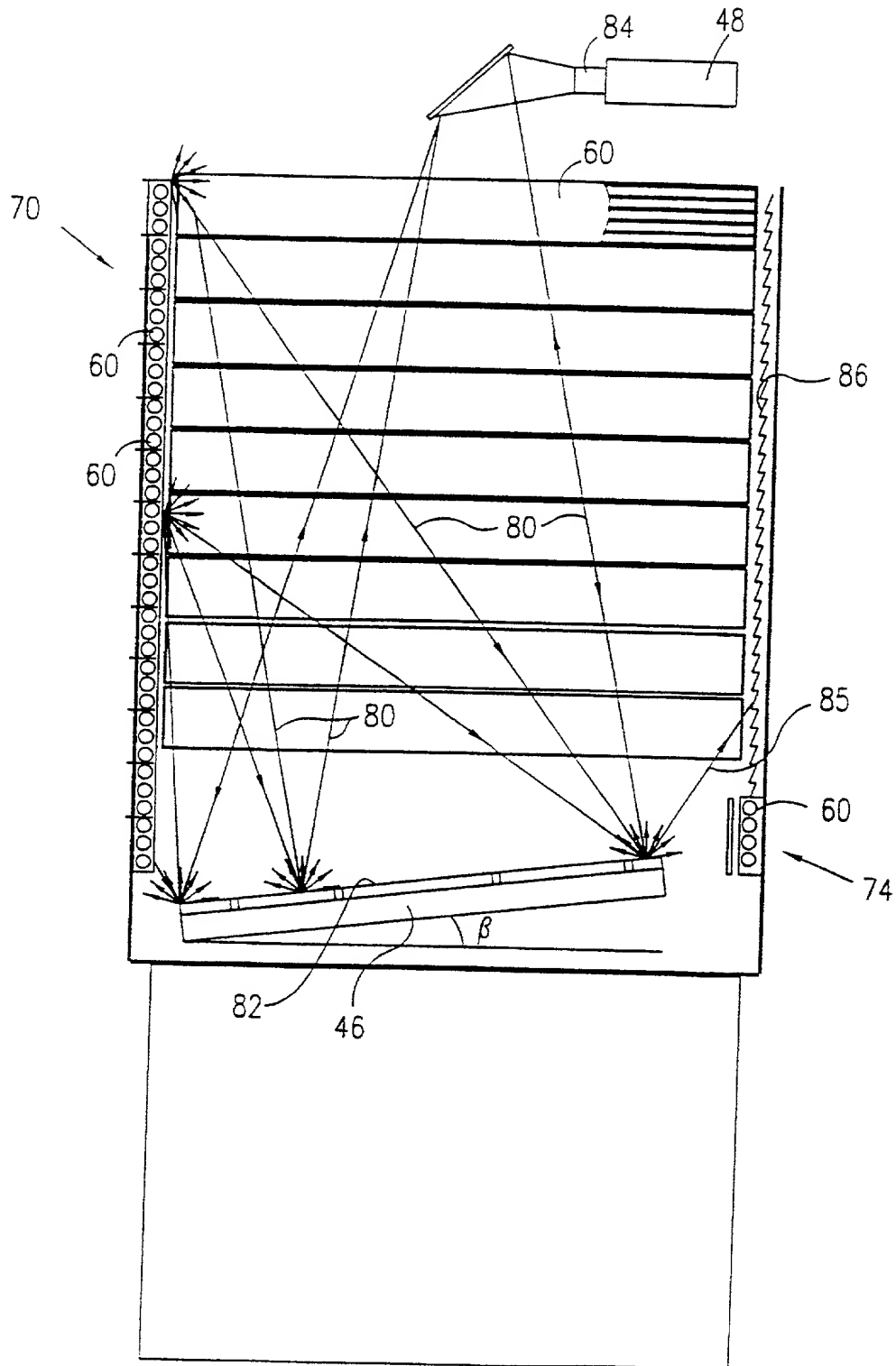
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FIG. 5



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FIG. 6



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FIG. 7

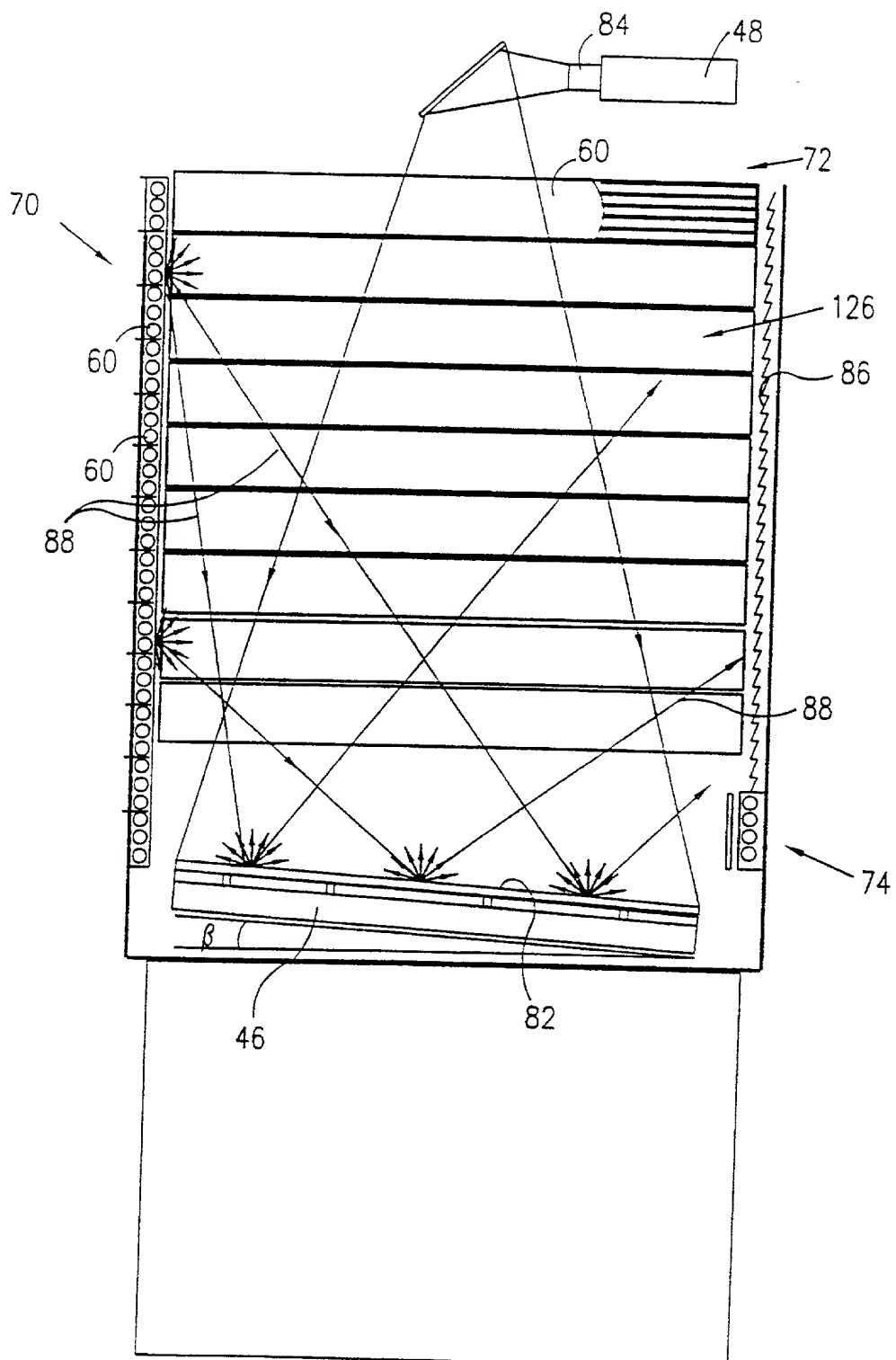
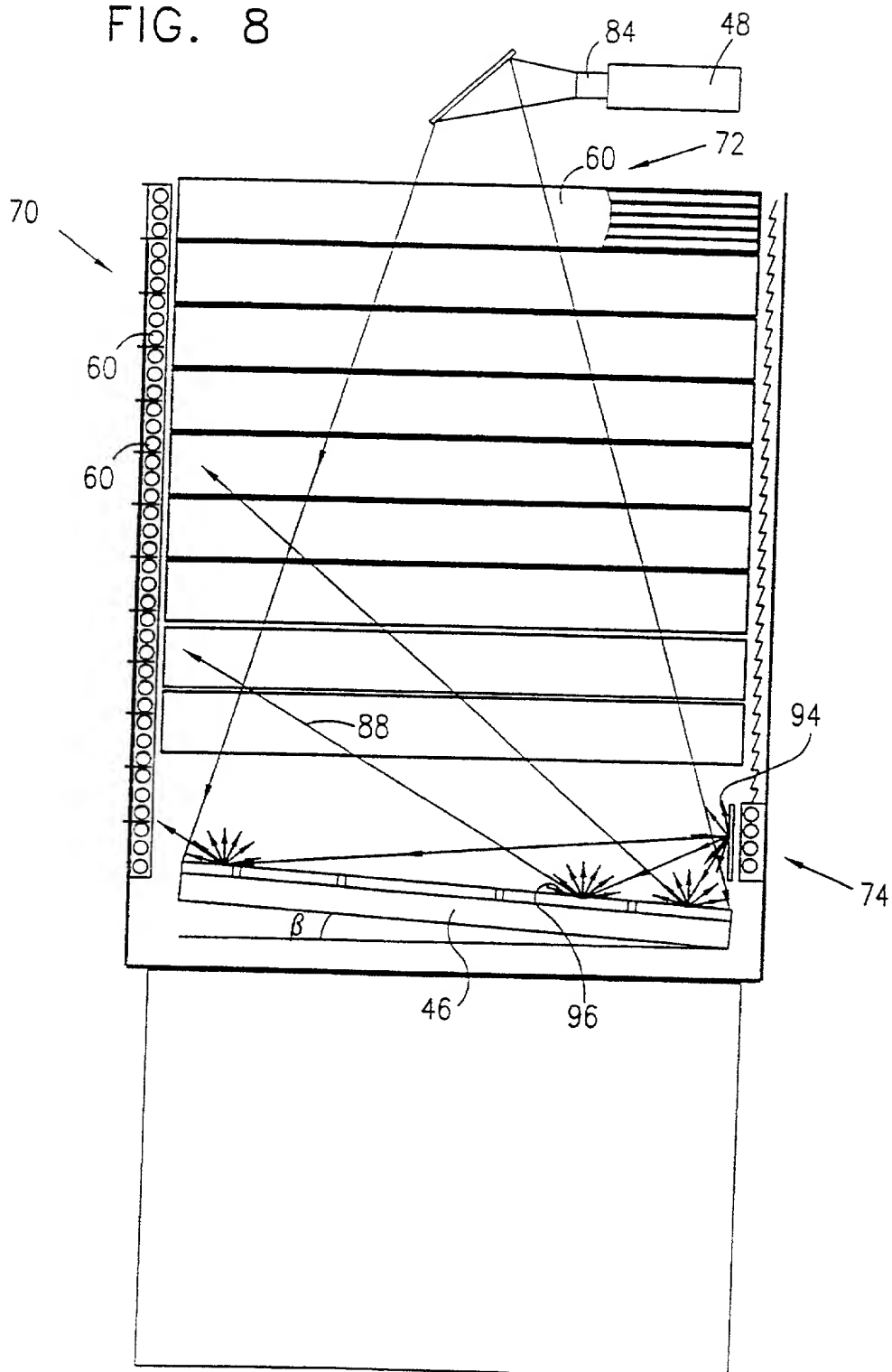
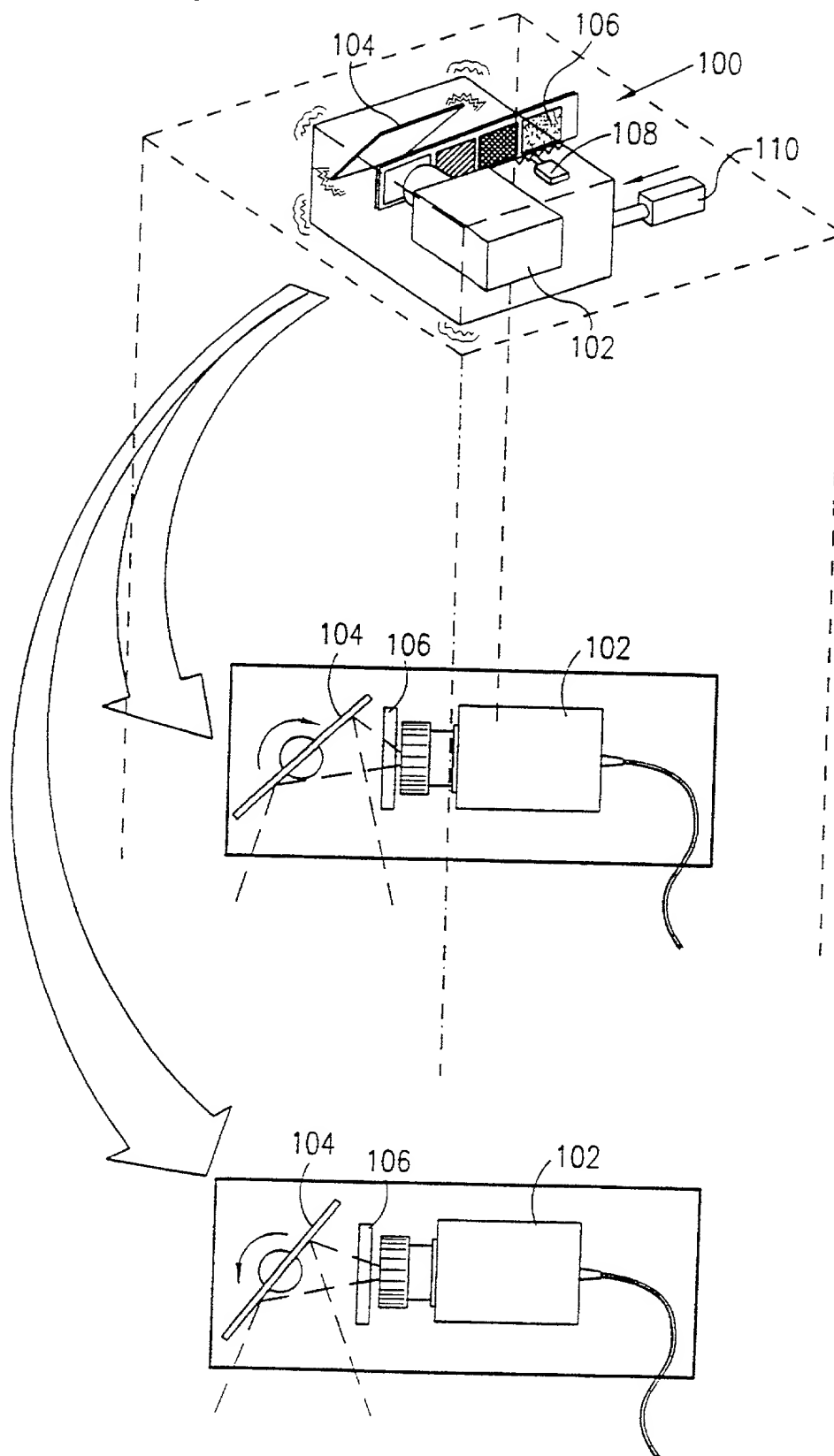


FIG. 8



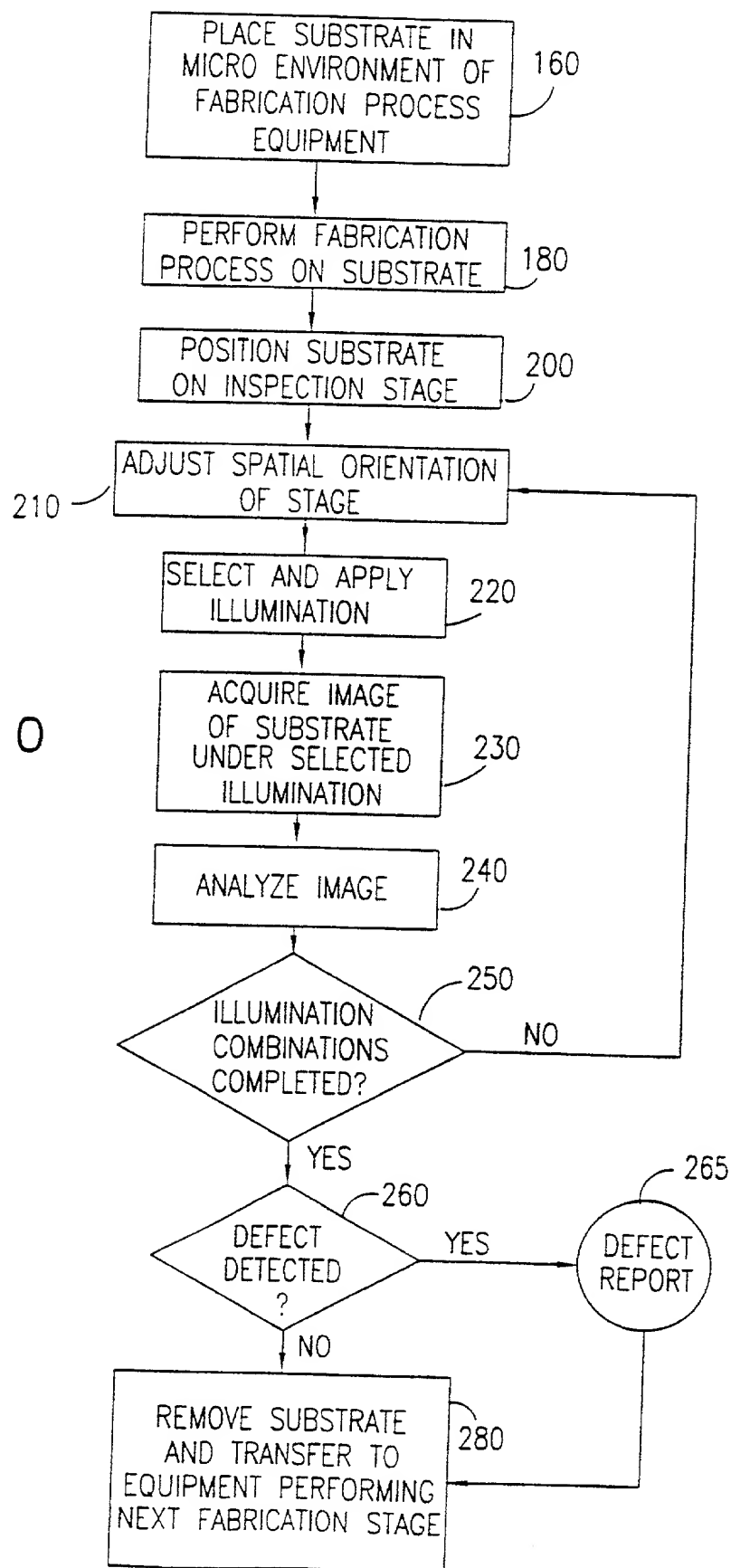
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FIG. 9



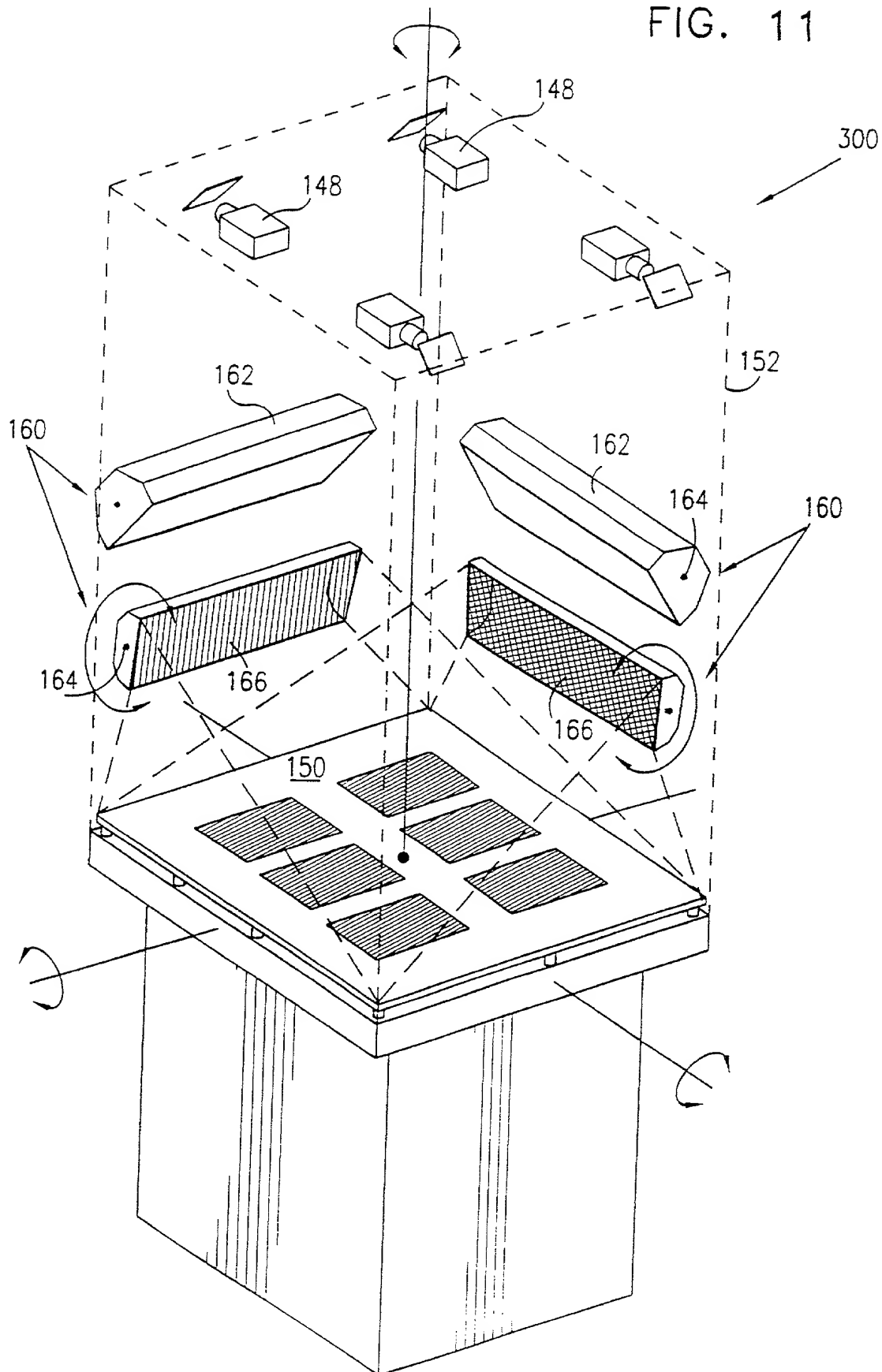
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FIG. 10



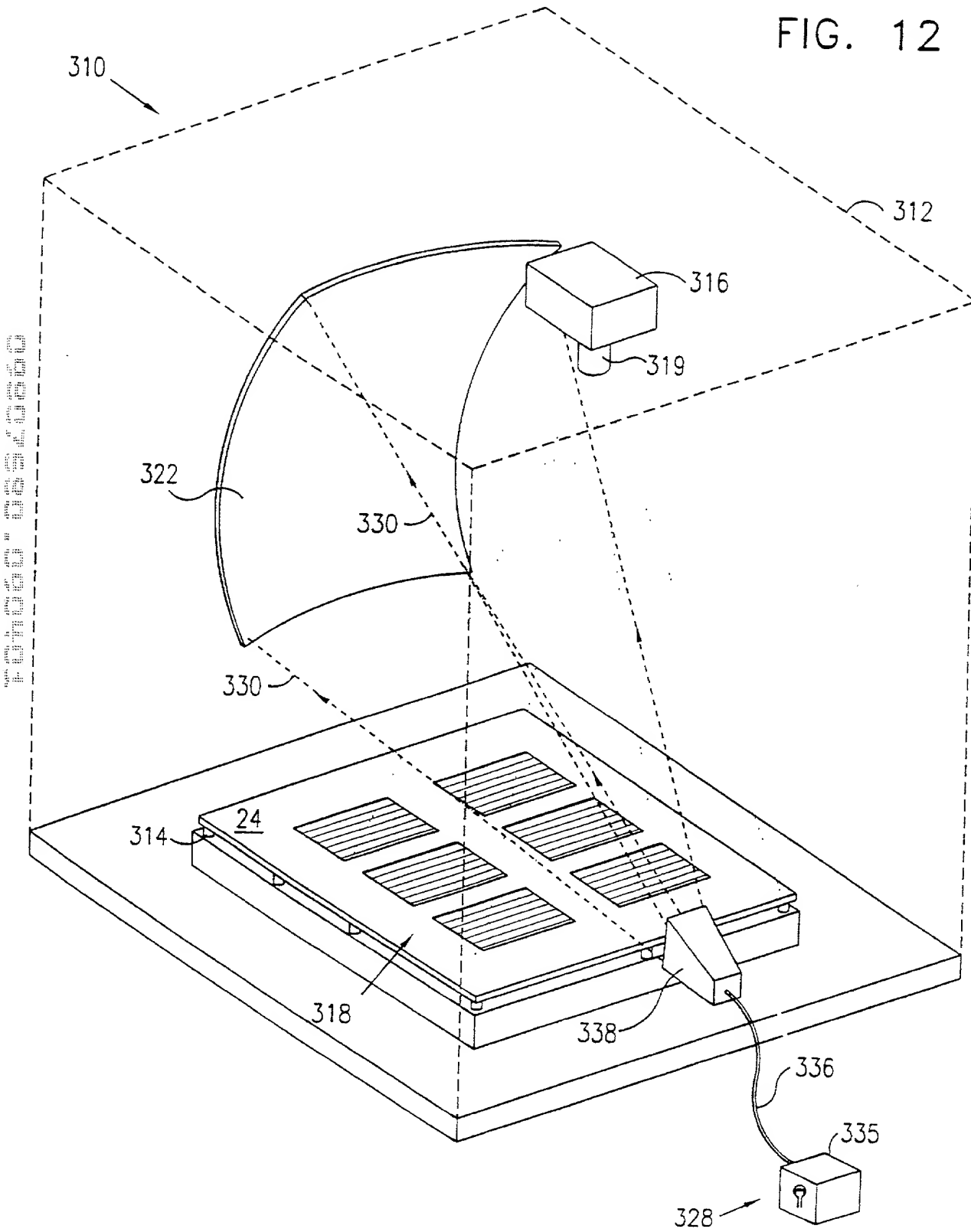
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FIG. 11



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FIG. 12



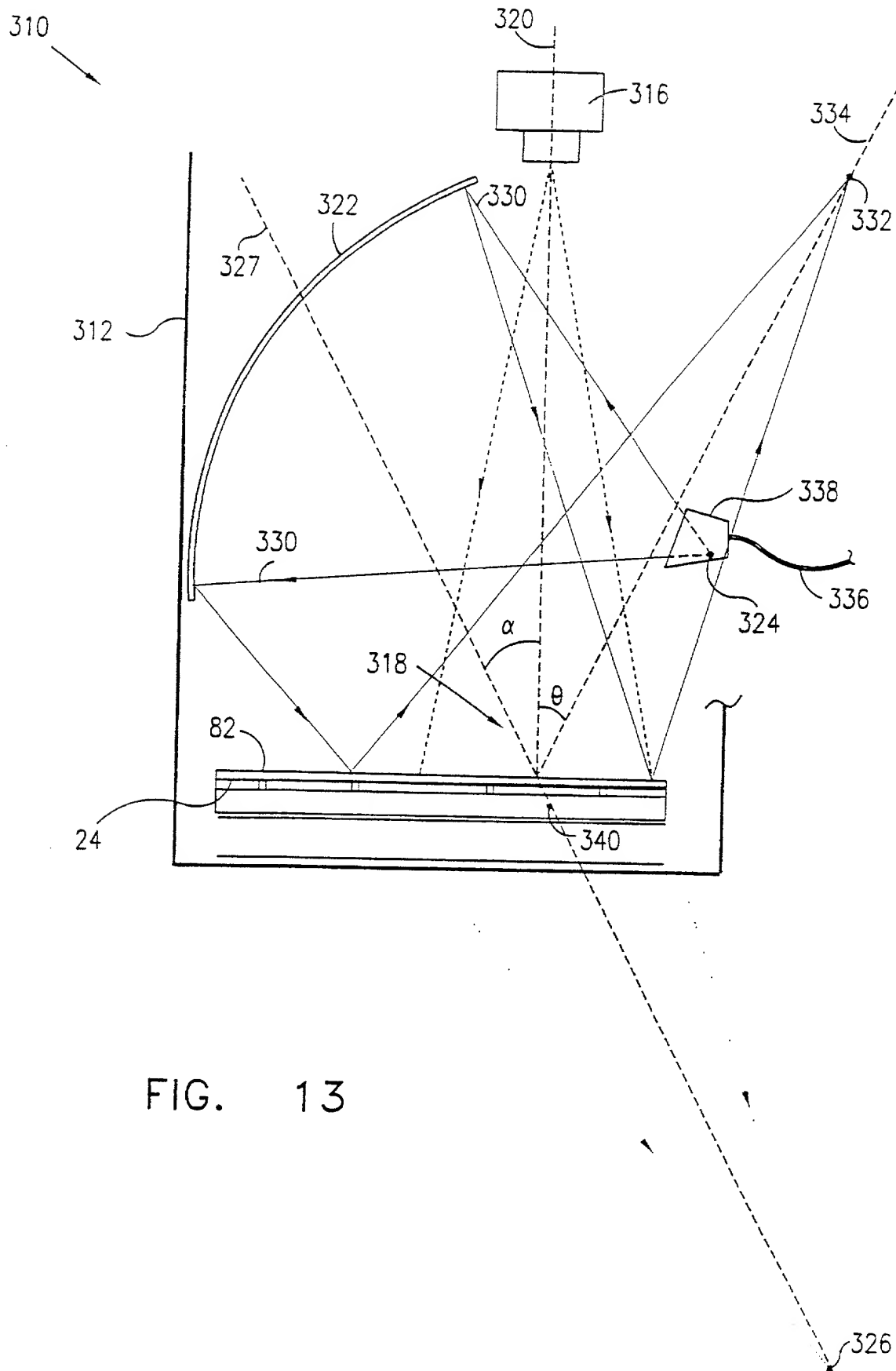


FIG. 13

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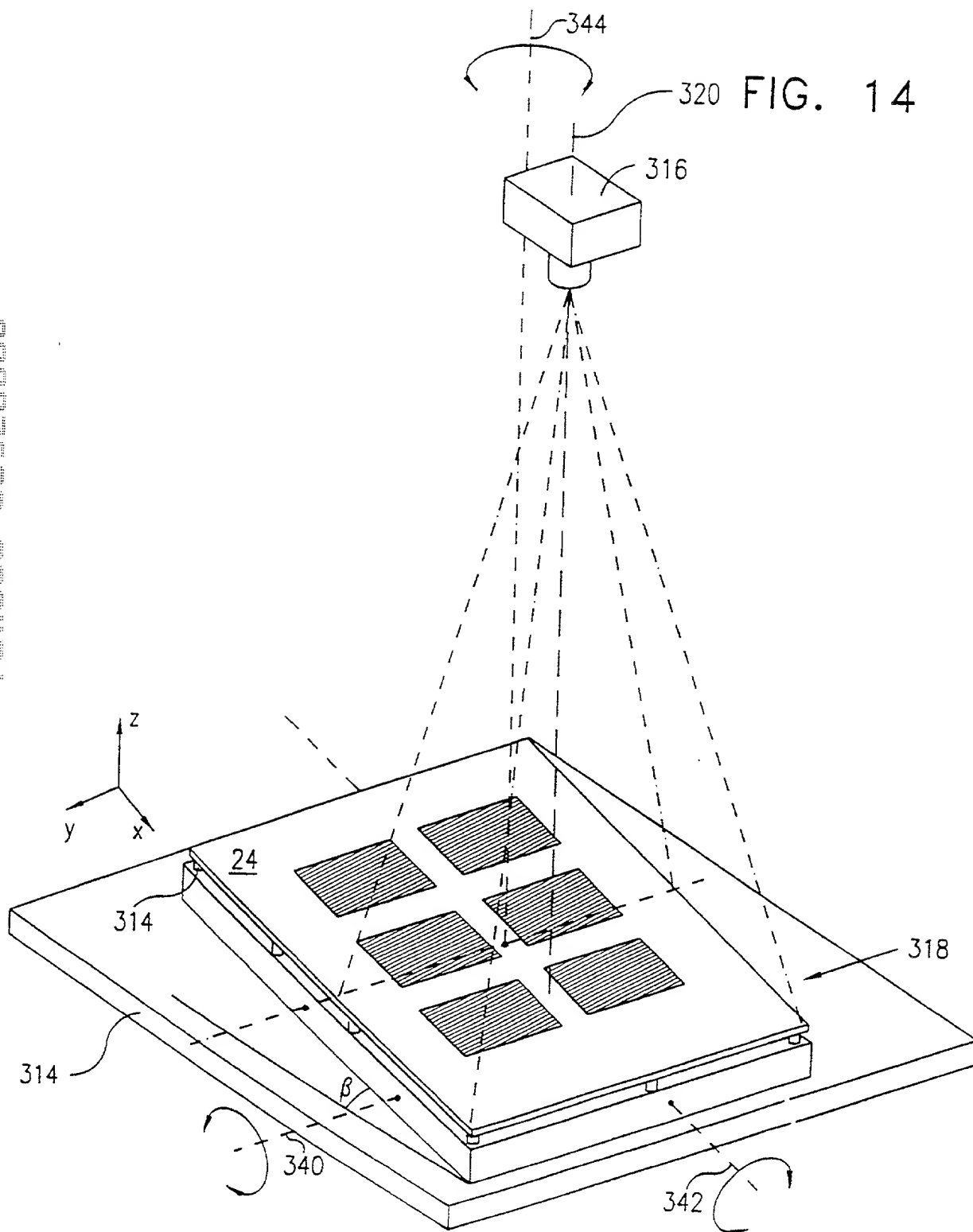
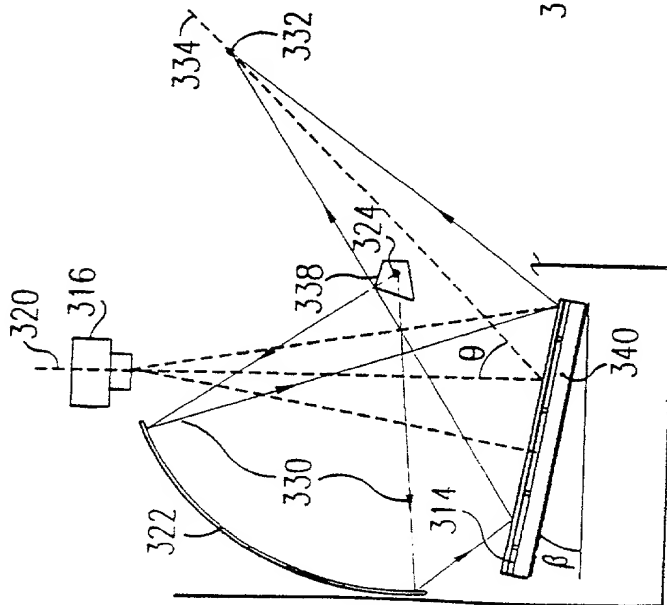
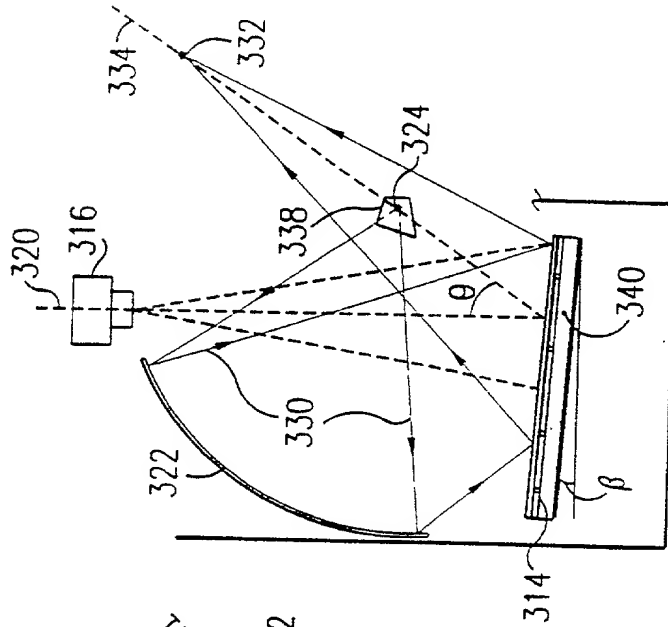


FIG. 15A



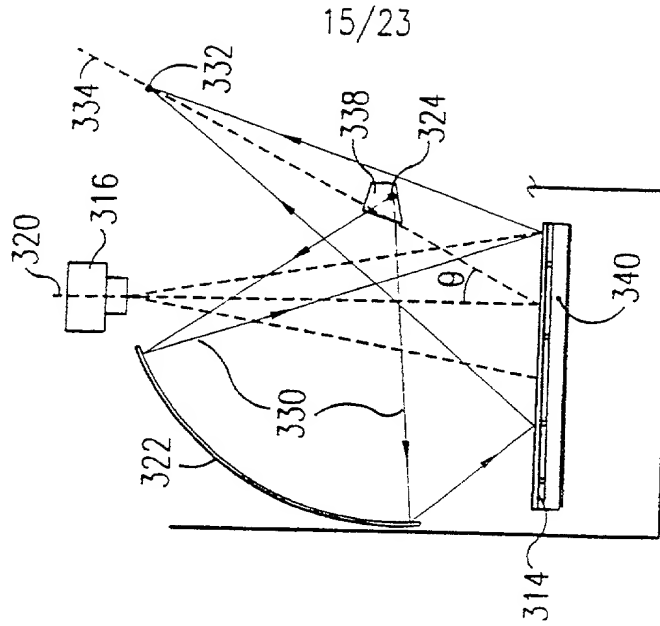
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FIG. 15B



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FIG. 15C



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FIG. 15D

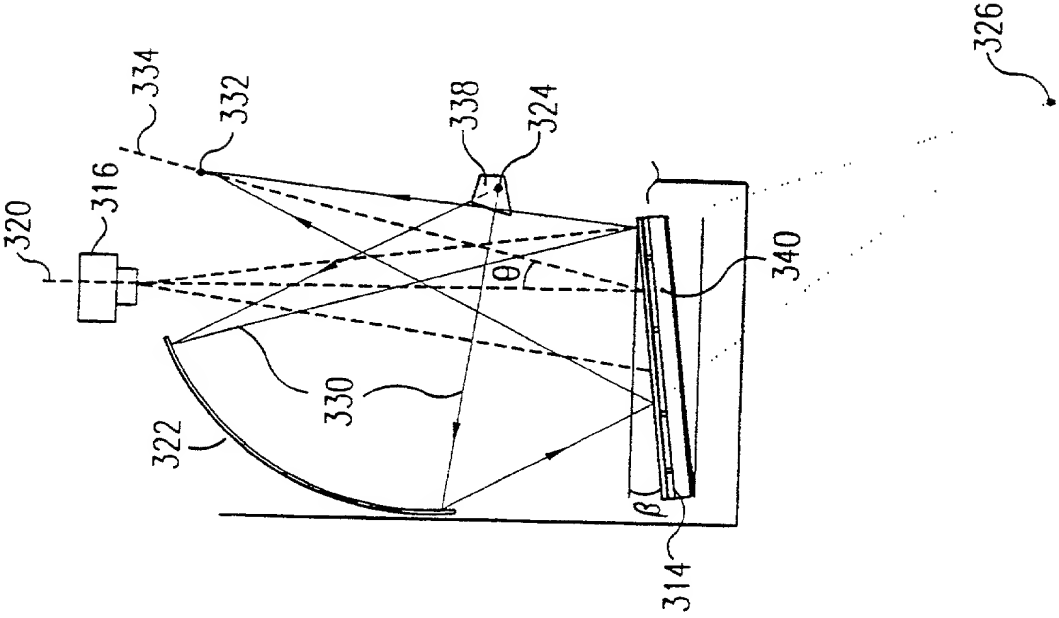


FIG. 15E

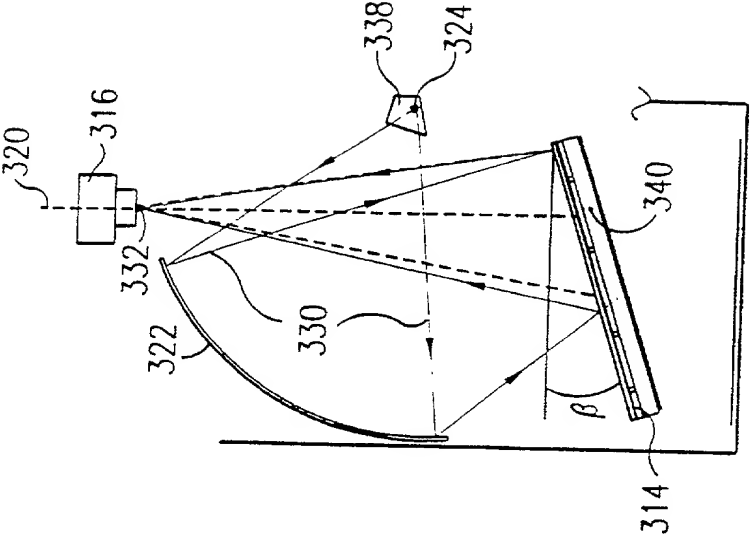
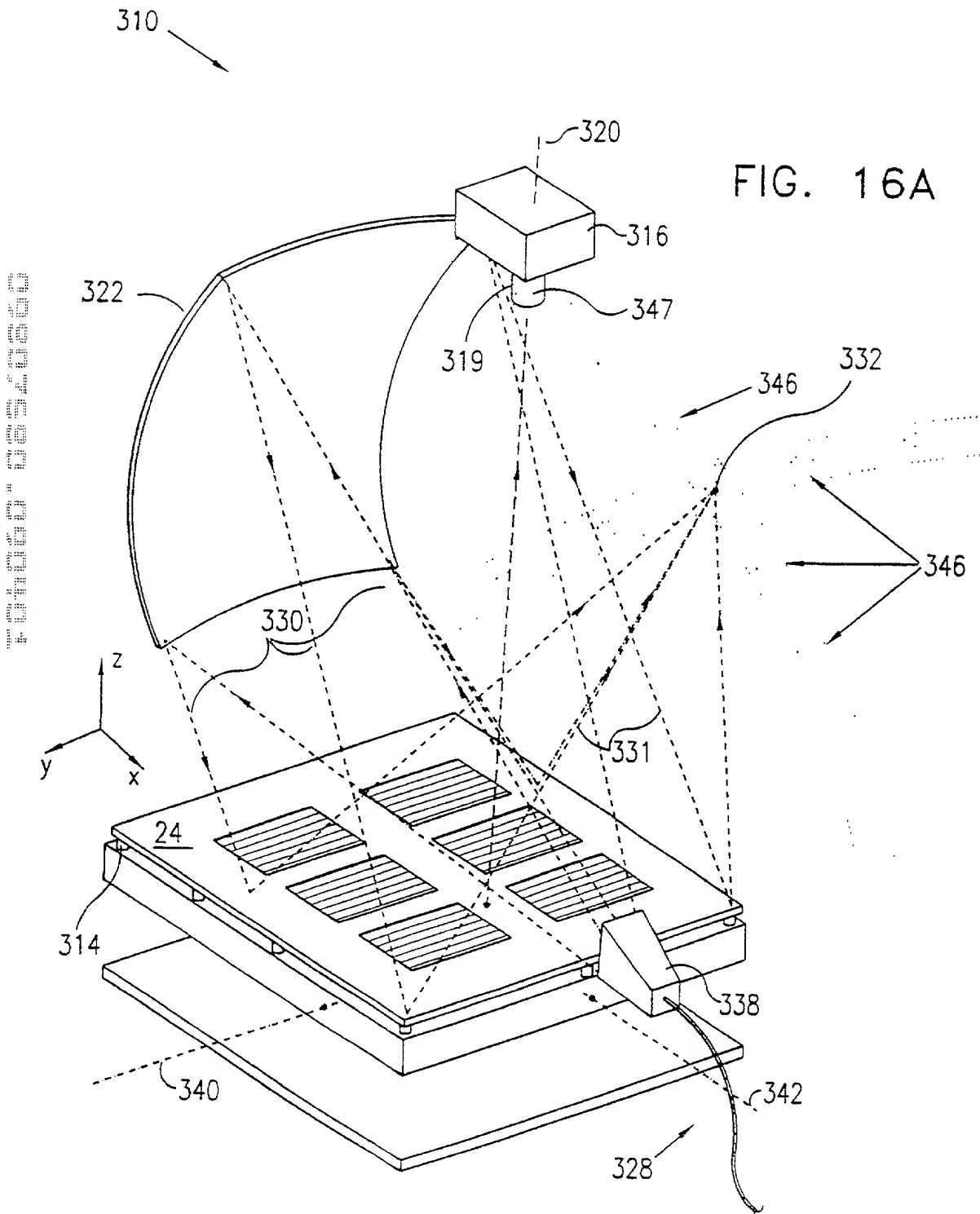
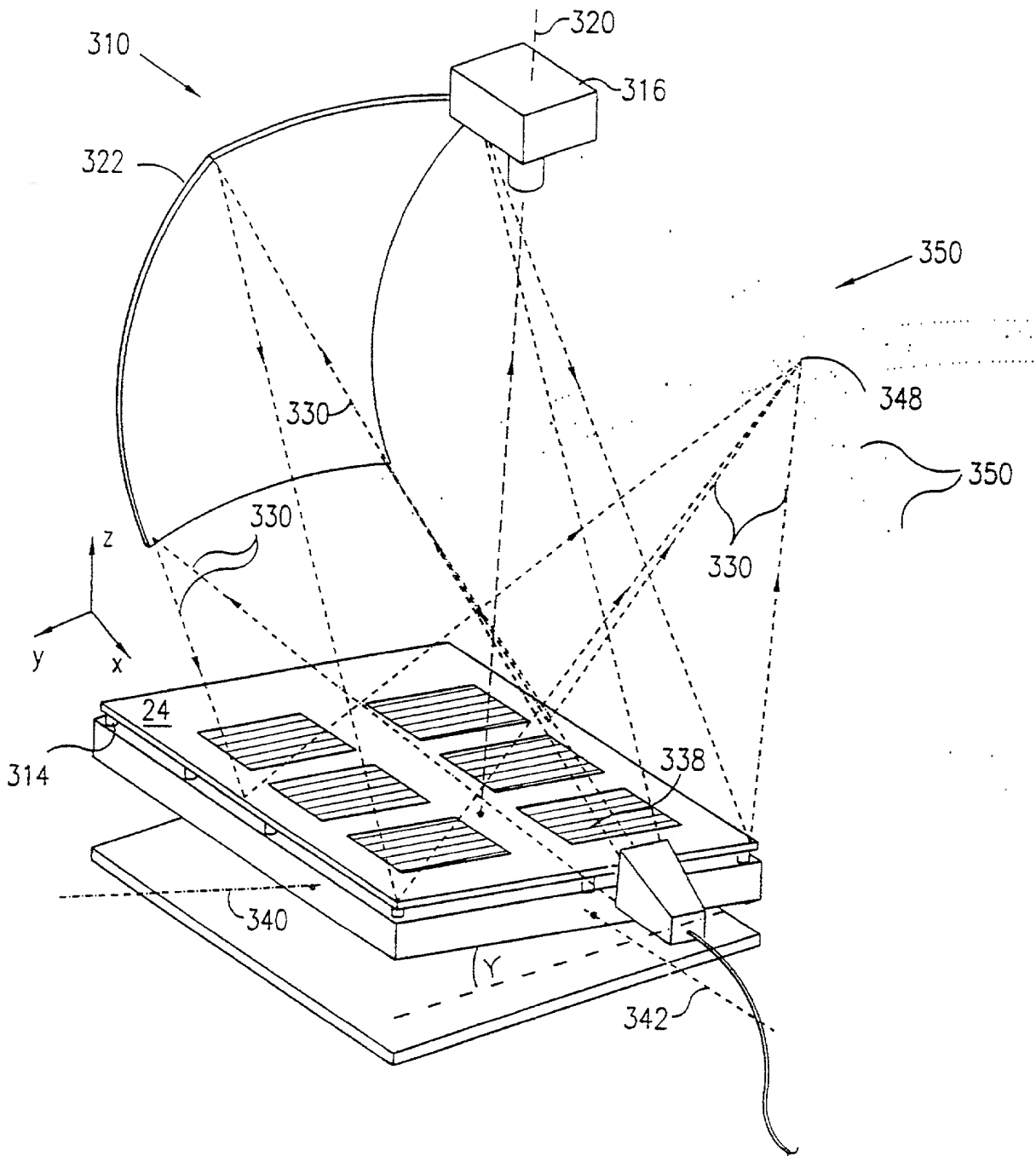


FIG. 16A



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FIG. 16B



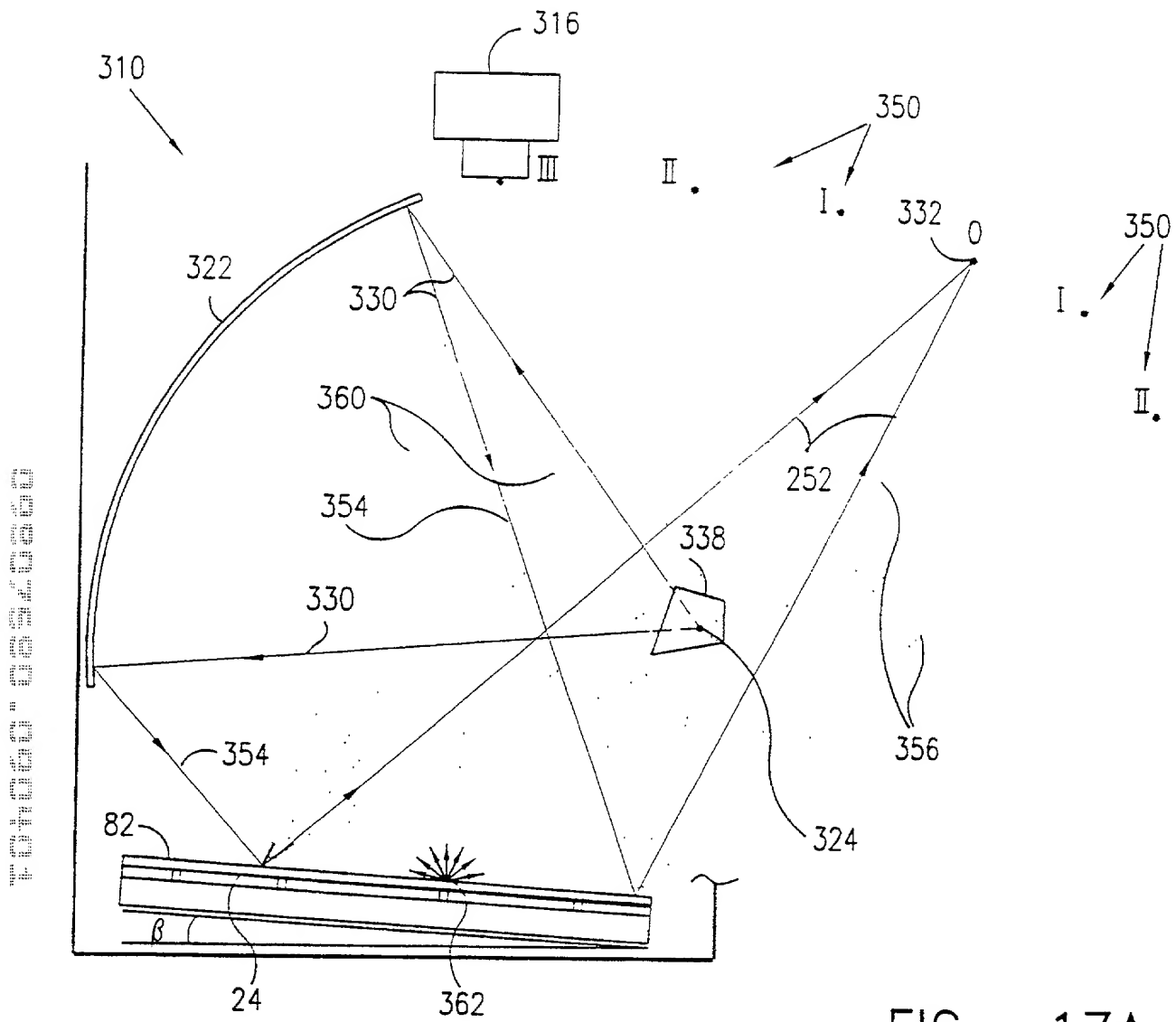


FIG. 17A

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FIG. 17B

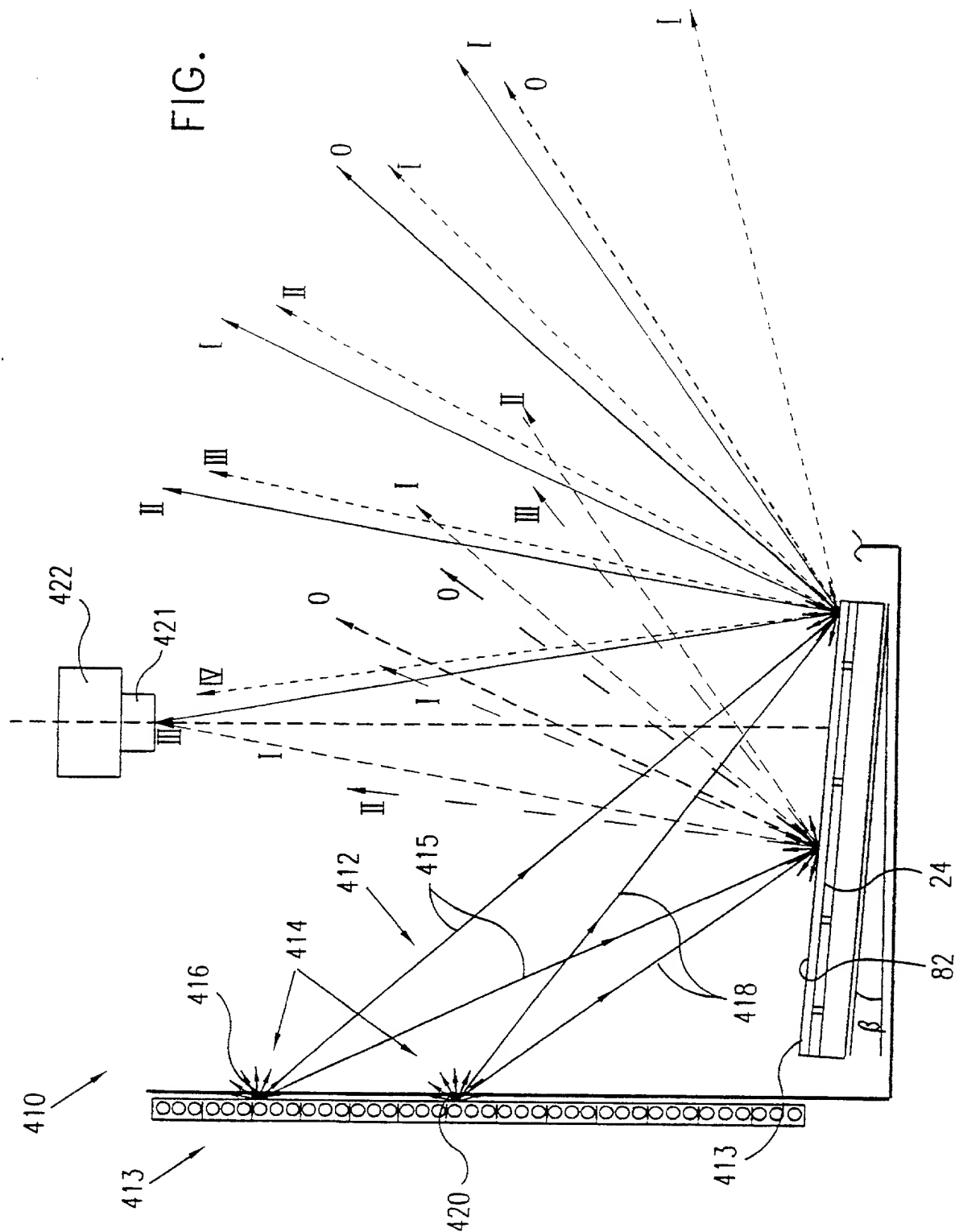
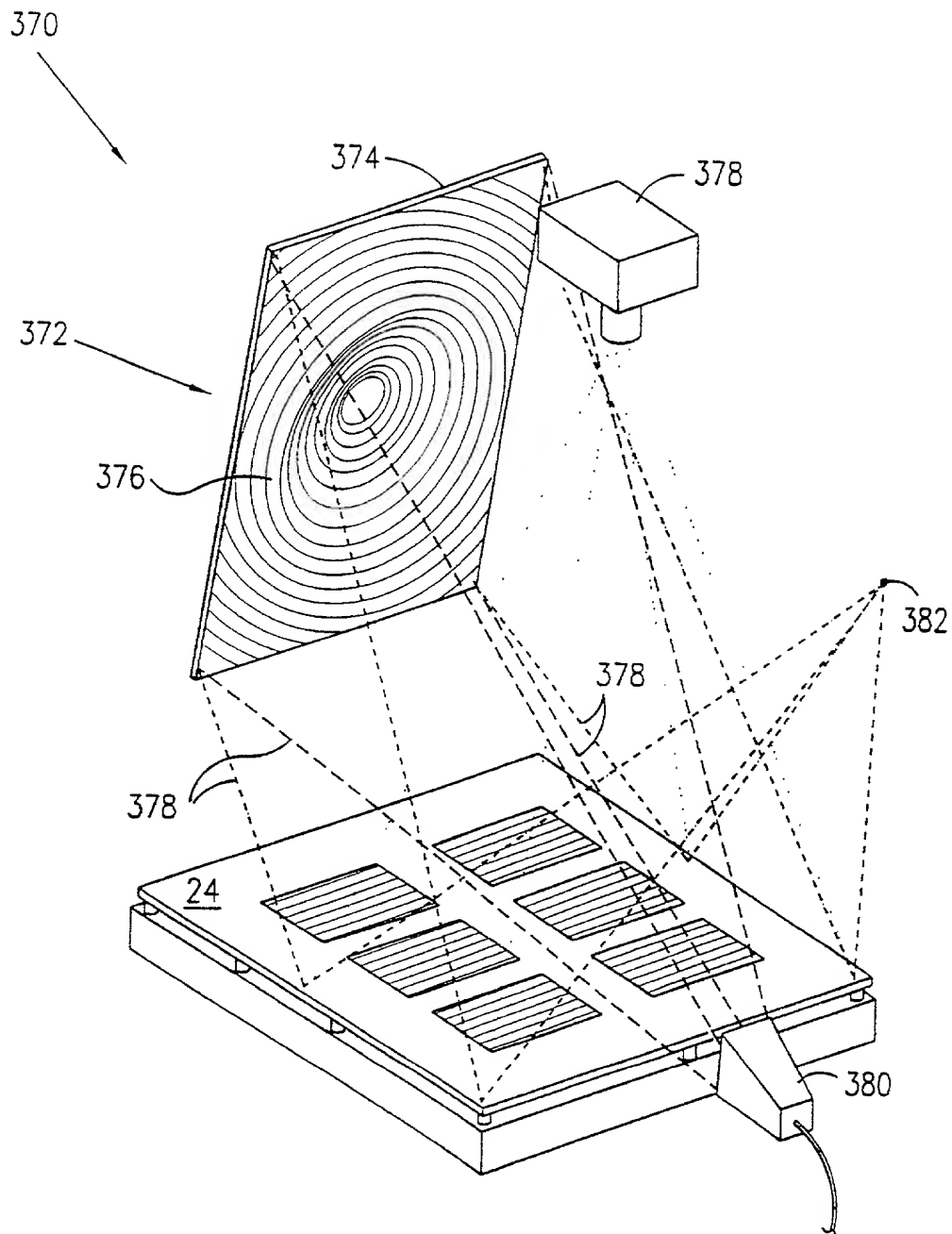
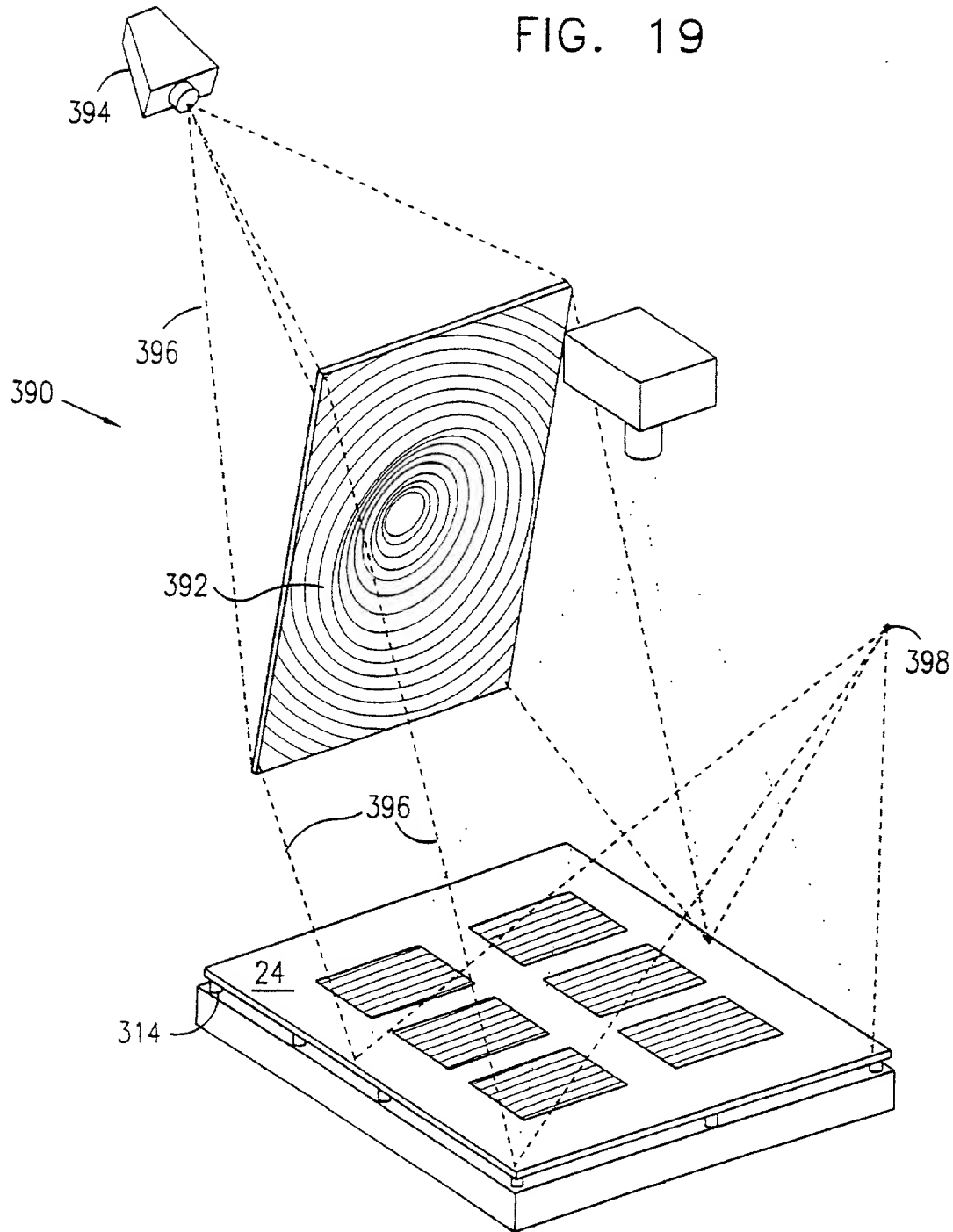


FIG. 18

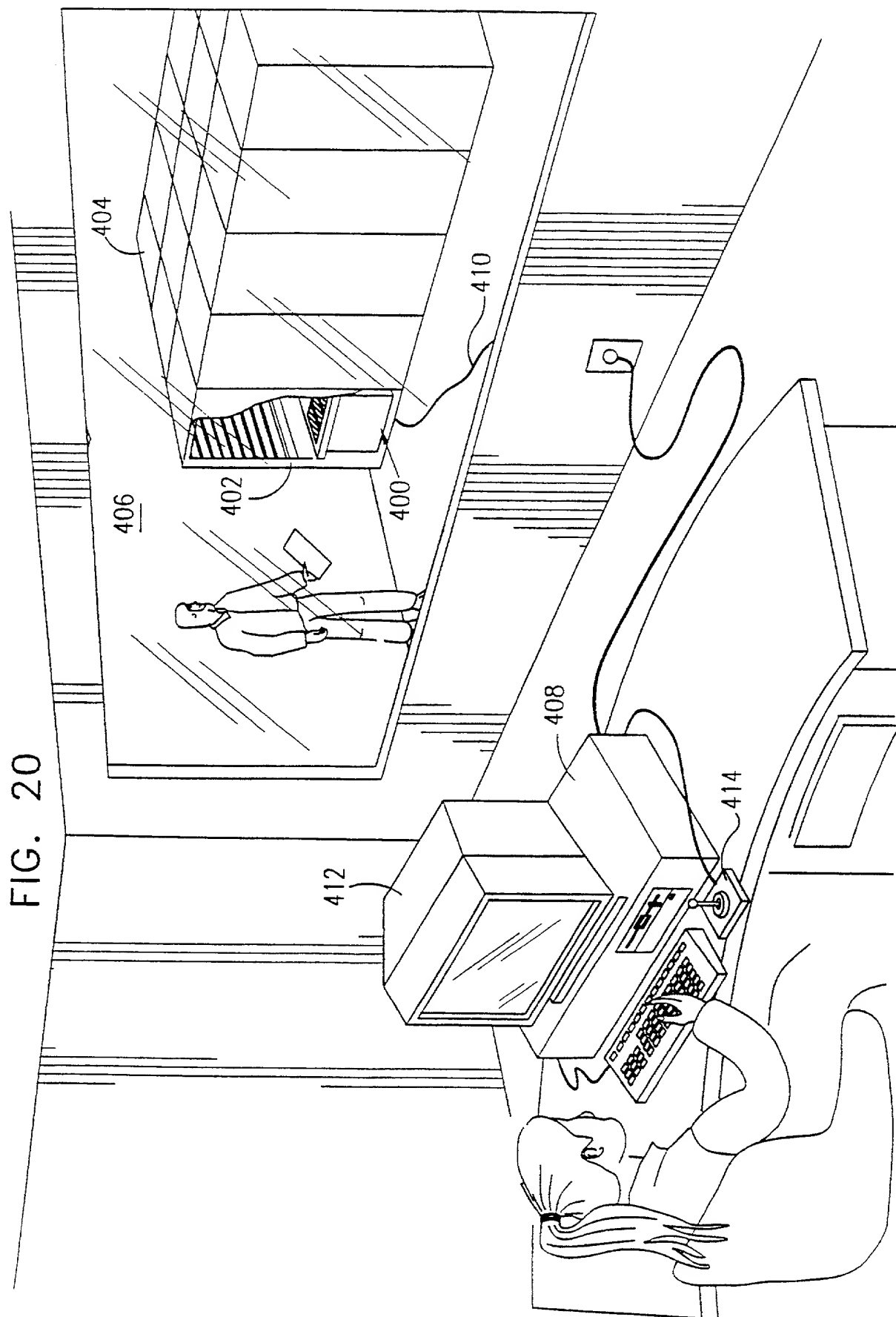


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FIG. 19



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SEP 04 2001

Practitioner's Docket No. U013399-2

**ADDED PAGE TO COMBINED DECLARATION AND POWER OF
ATTORNEY FOR SIGNATURE BY FOURTH AND SUBSEQUENT INVENTORS**

Full name of fourth joint inventor, if any

Avi Gross
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) _____

Date (x) _____ Country of Citizenship IsraelResidence 26 Ben Yosef Street, Ramat Aviv, 69125, IsraelPost Office Address Same as above

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Technology Center 2600

Full name of fifth joint inventor, if any

(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature _____

Date _____ Country of Citizenship _____

Residence _____

Post Office Address _____

Full name of sixth joint inventor, if any

(Given Name) (Middle Initial or Name) Family (Or Last Name)

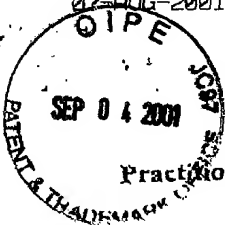
Inventor's signature _____

Date _____ Country of Citizenship _____

Residence _____

Post Office Address _____

(Added Page to Combined Declaration and Power of Attorney for Signature by Fourth and Subsequent Inventors
page 1 of 1) 1-2

Practitioner's Docket No. U013399-2

PATENT

Optional Customer No. Bar Code



00140

PATENT TRADEMARK OFFICE

RECEIVED
SEP 06 2001
Technology Center 2000**COMBINED DECLARATION AND POWER OF ATTORNEY**(ORIGINAL, DESIGN, NATIONAL STAGE OF PCT, SUPPLEMENTAL, DIVISIONAL,
CONTINUATION, OR C-I-P)

As a below named inventor, I hereby declare that:

TYPE OF DECLARATION

This declaration is of the following type:

(check one applicable item below)

- ☐ original.
☐ design.

NOTE: With the exception of a supplemental oath or declaration submitted in a reissue, a supplemental oath or declaration is not treated as an amendment under 37 CFR 1.312 (Amendments after allowance), M.P.E.P. Section 714.16, 7th Ed.

- ☐ supplemental.

NOTE: If the declaration is for an International Application being filed as a divisional, continuation or continuation-in-part application, do not check next item; check appropriate one of last three items.

- ☒ national stage of PCT.

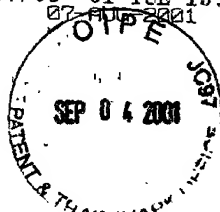
NOTE: If one of the following 3 items apply, then complete and also attach **ADDED PAGES FOR DIVISIONAL, CONTINUATION OR C-I-P**.

NOTE: See 37 C.F.R. Section 1.63(d) (continued prosecution application) for use of a prior nonprovisional application declaration in the continuation or divisional application being filed on behalf of the same or fewer of the inventor(s) named in the prior application.

- ☐ divisional.
☐ continuation.

NOTE: Where an application discloses and claims subject matter not disclosed in the prior application, or a continuation or divisional application names an inventor not named in the prior application, a continuation-in-part application must be filed under 37 C.F.R. Section 1.53(b) (application filing requirements-nonprovisional application).

- ☐ continuation-in-part (C-I-P).



INVENTORSHIP IDENTIFICATION

WARNING:

If the inventors are each not the inventors of all the claims, an explanation of the facts, including the ownership of all the claims at the time the last claimed invention was made, should be submitted.

My residence, post office address and citizenship are as stated below, next to my name. I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter that is claimed, and for which a patent is sought on the invention entitled:

TITLE OF INVENTION

APPARATUS AND METHOD FOR FABRICATING FLAT WORKPIECES

Technology Center 2600

SEP 06 2001

RECEIVED

SPECIFICATION IDENTIFICATION

The specification of which:

(complete (a), (b), or (c))

(a) ☐ is attached hereto.

NOTE: "The following combinations of information supplied in an oath or declaration filed on the application filing date with a specification are acceptable as minimums for identifying a specification and compliance with any one of the items below will be accepted as complying with the identification requirement of 37 C.F.R. Section 1.63:

"(1) name of inventor(s), and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration on filing;

"(2) name of inventor(s), and attorney docket number which was on the specification as filed; or

"(3) name of inventor(s), and title which was on the specification as filed."

Notice of July 13, 1995 (1177 O.G. 60).

(b) ☐ was filed on _____, ☐ as Application No. _____
☐ and was amended on _____ (if applicable).

NOTE: Amendments filed after the original papers are deposited with the PTO that contain new matter are not accorded a filing date by being referred to in the declaration. Accordingly, the amendments involved are those filed with the application papers or, in the case of a supplemental declaration, are those amendments claiming matter not encompassed in the original statement of invention or claims. See 37 C.F.R. Section 1.67.

NOTE: "The following combinations of information supplied in an oath or declaration filed after the filing date are acceptable as minimums for identifying a specification and compliance with any one of the items below will be accepted as complying with the identification requirement of 37 C.F.R. Section 1.63:

(A) application number (consisting of the series code and the serial number, e.g., 08/123,456);

(B) serial number and filing date;

(C) attorney docket number which was on the specification as filed;

(D) title which was on the specification as filed and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration; or

(E) title which was on the specification as filed and accompanied by a cover letter accurately identifying the application for which it was intended by either the application number (consisting of the series code and the serial number, e.g., 08/123,456), or serial number and filing date. Absent any statement(s) to the contrary, it will be presumed that the application filed in the PTO is the application which the inventor(s) executed by signing the oath or declaration.

M.P.E.P. Section 601.01(a), 7th ed.

- (c) [x] was described and claimed in PCT International Application No. PCT/IL99/00583 filed on November 2, 1999 and as amended under PCT Article 19 on _____ (if any).

SUPPLEMENTAL DECLARATION (37 C.F.R. Section 1.67(b))

(complete the following where a supplemental declaration is being submitted)

[] I hereby declare that the subject matter of the

[] attached amendment

[] amendment filed on _____

was part of my/our invention and was invented before the filing date of the original application, above identified, for such invention.

ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to patentability as defined in 37, Code of Federal Regulations, Section 1.56,

(also check the following items, if desired)

[] and which is material to the examination of this application, namely, information where there is a substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent, and

[] in compliance with this duty, there is attached an information disclosure statement, in accordance with 37 C.F.R. Section 1.98.

PRIORITY CLAIM (35 U.S.C. Section 119(a)-(d))

NOTE: "The claim to priority need be in no special form and may be made by the attorney or agent if the foreign application is referred to in the oath or declaration as required by Section 1.63. The claim for priority and the certified copy of the foreign application specified in 35 U.S.C. Section 119(b) must be filed in the case of an interference (Section 1.630), when necessary to overcome the date of a reference relied upon by the examiner, when specifically required by the examiner, and in all other situations, before the patent is granted. If the claim for priority or the certified copy of the foreign application is filed after the date the issue fee is paid, it must be accompanied by a petition requesting entry and by the fee set forth in Section 1.17(i). If the certified copy is not in the English language, a translation need not be filed except in the case of interference, or when necessary to overcome the date of a reference relied upon by the examiner, or when specifically required by the examiner, in which event an English language translation must be filed together with a statement that the translation of the certified copy is accurate." 37 C.F.R. Section 1.55(a).

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

(complete (d) or (e))

- (d) ☐ no such applications have been filed.
(e) ☒ such applications have been filed as follows.

NOTE: Where item (c) is entered above and the International Application which designated the U.S. itself claimed priority check item (e), enter the details below and make the priority claim.

**PRIOR FOREIGN/PCT APPLICATION(S) FILED WITHIN 12 MONTHS
(6 MONTHS FOR DESIGN) PRIOR TO THIS APPLICATION
AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. SECTION 119(a)-(d)**

COUNTRY (OR INDICATE IF PCT)	APPLICATION NUMBER	DATE OF FILING DAY, MONTH, YEAR	PRIORITY CLAIMED UNDER 35 USC 119
IL	126866 ✓	2 November 1998 ✓	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO

**CLAIM FOR BENEFIT OF PRIOR U.S. PROVISIONAL APPLICATION(S)
(35 U.S.C. Section 119(e))**

I hereby claim the benefit under Title 35, United States Code, Section 119(e) of any United States provisional application(s) listed below:

PROVISIONAL APPLICATION NUMBER

FILING DATE

**CLAIM FOR BENEFIT OF EARLIER U.S./PCT APPLICATION(S)
UNDER 35 U.S.C. SECTION 120**

- ☐ The claim for the benefit of any such applications are set forth in the attached
ADDED PAGES TO COMBINED DECLARATION AND POWER OF ATTORNEY
FOR DIVISIONAL, CONTINUATION OR CONTINUATION-IN-PART (C-I-P)
APPLICATION.

**ALL FOREIGN APPLICATION(S), IF ANY, FILED MORE THAN 12 MONTHS
(6 MONTHS FOR DESIGN) PRIOR TO THIS U.S. APPLICATION**

NOTE: If the application filed more than 12 months from the filing date of this application is a PCT filing forming the basis for this application entering the United States as (1) the national stage, or (2) a continuation, divisional, or continuation-in-part, then also complete **ADDED PAGES TO COMBINED DECLARATION AND POWER OF ATTORNEY FOR DIVISIONAL, CONTINUATION OR C-I-P APPLICATION** for benefit of the prior U.S. or PCT application(s) under 35 U.S.C. Section 120.

POWER OF ATTORNEY

I hereby appoint the following practitioner(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

(list name and registration number)

JOSEPH H. HANDELMAN, 26179

JULIAN H. COHEN, 20302

JOHN RICHARDS, 31053

WILLIAM R. EVANS 25858

RICHARD J. STREIT, 25765

JANET I. CORD, 33778

PETER D. GALLOWAY, 27885

CLIFFORD J. MASS, 30086

IAN C. BAILLIE, 24090

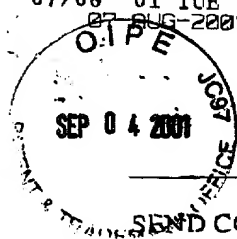
CYNTHIA R. MILLER, 34678

RICHARD P. BERG, 28145

(Check the following item, if applicable)

- ☐ I hereby appoint the practitioner(s) associated with the Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.
- ☐ Attached, as part of this declaration and power of attorney, is the authorization of the above-named practitioner(s) to accept and follow instructions from my representative(s).

NOTE: "Special care should be taken in continuation or divisional applications to ensure that any change of correspondence address in a prior application is reflected in the continuation or divisional application. For example, where a copy of the oath or declaration from the prior application is submitted for a continuation or divisional application filed under 37 CFR 1.53(b) and the copy of the oath or declaration from the prior application designates an old correspondence address, the Office may not recognize, in the continuation or divisional application, the change of correspondence address made during the prosecution of the prior application. Applicant is required to identify the change of correspondence address in the continuation or divisional application to ensure that communications from the Office are mailed to the current correspondence address. 37 CFR 1.63(d)(4)." Section 601.03, M.P.E.P., 7th Ed



SEND CORRESPONDENCE TO

Ladas & Parry
26 West 61st Street
New York, N.Y. 10023

DIRECT TELEPHONE CALLS TO:
(Name and telephone number)

Julian H. Cohen
(212) 708-1887

(complete the following if applicable)

Since this filing is a [] continuation [] divisional there is attached hereto a Change of Correspondence Address so that there will be no question as to where the PTO should direct all correspondence.

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

(check proper box(es) for any of the following added page(s)
that form a part of this declaration)

☒ **Signature** for fourth and subsequent joint inventors. *Number of pages added* 1

* * *

☐ **Signature** by administrator(trix), executor(trix) or legal representative for deceased or incapacitated inventor. *Number of pages added* _____

* * *

☐ **Signature** for inventor who refuses to sign or cannot be reached by person authorized under 37 C.F.R. Section 1.47. *Number of pages added* _____

* * *

☐ Added page for **signature** by one joint inventor on behalf of deceased inventor(s) where legal representative cannot be appointed in time. (37 C.F.R. Section 1.47)

* * *

☐ Added pages to combined declaration and power of attorney for divisional, continuation, or continuation-in-part (C-I-P) application.

☐ Number of pages added _____

* * *

☐ Authorization of practitioner(s) to accept and follow instructions from representative.

(If no further pages form a part of this Declaration,
then end this Declaration with this page and check the following item)

☐ This declaration ends with this page.

Optional Customer No. Bar Code



00140

PATENT TRADEMARK OFFICE

COMBINED DECLARATION AND POWER OF ATTORNEY

(ORIGINAL, DESIGN, NATIONAL STAGE OF PCT, SUPPLEMENTAL, DIVISIONAL,
CONTINUATION, OR C-I-P)

As a below named inventor, I hereby declare that:

TYPE OF DECLARATION

This declaration is of the following type:

(check one applicable item below)

- ☐ original.
☐ design.

NOTE: With the exception of a supplemental oath or declaration submitted in a reissue, a supplemental oath or declaration is not treated as an amendment under 37 CFR 1.312 (Amendments after allowance). M.P.E.P. Section 714.16, 7th Ed.

- ☐ supplemental.

NOTE: If the declaration is for an International Application being filed as a divisional, continuation or continuation-in-part application, do not check next item; check appropriate one of last three items.

- ☒ national stage of PCT.

NOTE: If one of the following 3 items apply, then complete and also attach **ADDED PAGES FOR DIVISIONAL, CONTINUATION OR C-I-P**.

NOTE: See 37 C.F.R. Section 1.63(d) (continued prosecution application) for use of a prior nonprovisional application declaration in the continuation or divisional application being filed on behalf of the same or fewer of the inventors named in the prior application.

- ☐ divisional.
☐ continuation.

NOTE: Where an application discloses and claims subject matter not disclosed in the prior application, or a continuation or divisional application names an inventor not named in the prior application, a continuation-in-part application must be filed under 37 C.F.R. Section 1.53(b) (application filing requirements-nonprovisional application)

- ☐ continuation-in-part (C-I-P).

INVENTORSHIP IDENTIFICATION

WARNING: *If the inventors are each not the inventors of all the claims, an explanation of the facts, including the ownership of all the claims at the time the last claimed invention was made, should be submitted.*

My residence, post office address and citizenship are as stated below, next to my name. I believe that I am the original, first and sole inventor (*if only one name is listed below*) or an original, first and joint inventor (*if plural names are listed below*) of the subject matter that is claimed, and for which a patent is sought on the invention entitled:

TITLE OF INVENTION

APPARATUS AND METHOD FOR FABRICATING FLAT WORKPIECES

SPECIFICATION IDENTIFICATION

The specification of which:

(complete (a), (b), or (c))

(a) ☐ is attached hereto.

NOTE: *"The following combinations of information supplied in an oath or declaration filed on the application filing date with a specification are acceptable as minimums for identifying a specification and compliance with any one of the items below will be accepted as complying with the identification requirement of 37 C.F.R. Section 1.63:*

"(1) name of inventor(s), and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration on filing,

"(2) name of inventor(s), and attorney docket number which was on the specification as filed; or

"(3) name of inventor(s), and title which was on the specification as filed."

Notice of July 13, 1995 (1177 O.G. 60).

(b) ☐ was filed on _____, ☐ as Application No. _____
☐ and was amended on _____ (if applicable).

NOTE: *Amendments filed after the original papers are deposited with the PTO that contain new matter are not accorded a filing date by being referred to in the declaration. Accordingly, the amendments involved are those filed with the application papers or, in the case of a supplemental declaration, are those amendments claiming matter not encompassed in the original statement of invention or claims. See 37 C.F.R. Section 1.67.*

NOTE: *"The following combinations of information supplied in an oath or declaration filed after the filing date are acceptable as minimums for identifying a specification and compliance with any one of the items below will be accepted as complying with the identification requirement of 37 C.F.R. Section 1.63:*

(A) application number (consisting of the series code and the serial number, e.g., 08/123,456);

(B) serial number and filing date;

(C) attorney docket number which was on the specification as filed;

(D) title which was on the specification as filed and reference to an attached specification which is both attached to the oath or declaration at the time of execution and submitted with the oath or declaration; or

(E) title which was on the specification as filed and accompanied by a cover letter accurately identifying the application for which it was intended by either the application number (consisting of the series code and the serial number, e.g., 08/123,456), or serial number and filing date. Absent any statement(s) to the contrary, it will be presumed that the application filed in the PTO is the application which the inventor(s) executed by signing the oath or declaration.

M.P.E.P. Section 601.01(a), 7th ed.

- (c) ☒ was described and claimed in PCT International Application No. PCT/IL99/00583 filed on November 2, 1999 and as amended under PCT Article 19 on _____ (if any).

SUPPLEMENTAL DECLARATION (37 C.F.R. Section 1.67(b))

(complete the following where a supplemental declaration is being submitted)

☐ I hereby declare that the subject matter of the

☐ attached amendment

☐ amendment filed on _____.

was part of my/our invention and was invented before the filing date of the original application, above identified, for such invention.

ACKNOWLEDGMENT OF REVIEW OF PAPERS AND DUTY OF CANDOR

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information, which is material to patentability as defined in 37, Code of Federal Regulations, Section 1.56,

(also check the following items, if desired)

☐ and which is material to the examination of this application, namely, information where there is a substantial likelihood that a reasonable Examiner would consider it important in deciding whether to allow the application to issue as a patent, and

☐ in compliance with this duty, there is attached an information disclosure statement, in accordance with 37 C.F.R. Section 1.98.

PRIORITY CLAIM (35 U.S.C. Section 119(a)-(d))

NOTE: *"The claim to priority need be in no special form and may be made by the attorney or agent if the foreign application is referred to in the oath or declaration as required by Section 1.63. The claim for priority and the certified copy of the foreign application specified in 35 U.S.C. Section 119(b) must be filed in the case of an interference (Section 1.630), when necessary to overcome the date of a reference relied upon by the examiner, when specifically required by the examiner, and in all other situations, before the patent is granted. If the claim for priority or the certified copy of the foreign application is filed after the date the issue fee is paid, it must be accompanied by a petition requesting entry and by the fee set forth in Section 1.17(i). If the certified copy is not in the English language, a translation need not be filed except in the case of interference; or when necessary to overcome the date of a reference relied upon by the examiner; or when specifically required by the examiner, in which event an English language translation must be filed together with a statement that the translation of the certified copy is accurate." 37 C.F.R. Section 1.55(a).*

I hereby claim foreign priority benefits under Title 35, United States Code, Section 119(a)-(d) of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application(s) for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed.

(complete (d) or (e))

- (d) ☐ no such applications have been filed.
(e) ☒ such applications have been filed as follows.

NOTE: Where item (c) is entered above and the International Application which designated the U.S. itself claimed priority check item (e), enter the details below and make the priority claim

**PRIOR FOREIGN/PCT APPLICATION(S) FILED WITHIN 12 MONTHS
(6 MONTHS FOR DESIGN) PRIOR TO THIS APPLICATION
AND ANY PRIORITY CLAIMS UNDER 35 U.S.C. SECTION 119(a)-(d)**

COUNTRY (OR INDICATE IF PCT)	APPLICATION NUMBER	DATE OF FILING DAY, MONTH, YEAR	PRIORITY CLAIMED UNDER 35 USC 119
IL	126866	2 November 1998	<input checked="" type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO
			<input type="checkbox"/> YES <input type="checkbox"/> NO

**CLAIM FOR BENEFIT OF PRIOR U.S. PROVISIONAL APPLICATION(S)
(35 U.S.C. Section 119(e))**

I hereby claim the benefit under Title 35, United States Code, Section 119(e) of any United States provisional application(s) listed below:

PROVISIONAL APPLICATION NUMBER
_____/_____
_____/_____
_____/_____

FILING DATE

**CLAIM FOR BENEFIT OF EARLIER U.S./PCT APPLICATION(S)
UNDER 35 U.S.C. SECTION 120**

- ☐ The claim for the benefit of any such applications are set forth in the attached
ADDED PAGES TO COMBINED DECLARATION AND POWER OF ATTORNEY
FOR DIVISIONAL, CONTINUATION OR CONTINUATION-IN-PART (C-I-P)
APPLICATION.

**ALL FOREIGN APPLICATION(S), IF ANY, FILED MORE THAN 12 MONTHS
(6 MONTHS FOR DESIGN) PRIOR TO THIS U.S. APPLICATION**

NOTE: If the application filed more than 12 months from the filing date of this application is a PCT filing forming the basis for this application entering the United States as (1) the national stage, or (2) a continuation, divisional, or continuation-in-part, then also complete ADDED PAGES TO COMBINED DECLARATION AND POWER OF ATTORNEY FOR DIVISIONAL, CONTINUATION OR C-I-P APPLICATION for benefit of the prior U.S. or PCT application(s) under 35 U.S.C. Section 120

POWER OF ATTORNEY

I hereby appoint the following practitioner(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

(list name and registration number)

JOSEPH H. HANDELMAN, 26179

JULIAN H. COHEN, 20302

JOHN RICHARDS, 31053

WILLIAM R. EVANS 25858

RICHARD J. STREIT, 25765

JANET I. CORD, 33778

PETER D. GALLOWAY, 27885

CLIFFORD J. MASS, 30086

IAIN C. BAILLIE, 24090

CYNTHIA R. MILLER, 34678

RICHARD P. BERG, 28145

(Check the following item, if applicable)

- ☐ I hereby appoint the practitioner(s) associated with the Customer Number provided below to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.
- ☐ Attached, as part of this declaration and power of attorney, is the authorization of the above-named practitioner(s) to accept and follow instructions from my representative(s).

NOTE: "Special care should be taken in continuation or divisional applications to ensure that any change of correspondence address in a prior application is reflected in the continuation or divisional application. For example, where a copy of the oath or declaration from the prior application is submitted for a continuation or divisional application filed under 37 CFR 1.53(b) and the copy of the oath or declaration from the prior application designates an old correspondence address, the Office may not recognize, in the continuation or divisional application, the change of correspondence address made during the prosecution of the prior application. Applicant is required to identify the change of correspondence address in the continuation or divisional application to ensure that communications from the Office are mailed to the current correspondence address 37 CFR 1.63(d)(4)." Section 601.03, M.P.E.P., 7th Ed

SEND CORRESPONDENCE TO

Ladas & Parry
26 West 61st Street
New York, N.Y. 10023

DIRECT TELEPHONE CALLS TO:
(Name and telephone number)

Julian H. Cohen
(212) 708-1887

(complete the following if applicable)

Since this filing is a [] continuation [] divisional there is attached hereto a Change of Correspondence Address so that there will be no question as to where the PTO should direct all correspondence.

DECLARATION

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

SIGNATURE(S)

NOTE: Carefully indicate the family (or last) name, as it should appear on the filing receipt and all other document.

NOTE: Each inventor must be identified by full name, including the family name, and at least one given name without abbreviation together with any other given name or initial, and by his/her residence, post office address and country of citizenship. 37 C.F.R. Section 1.63(a)(3).

NOTE: Inventors may execute separate declarations/oaths provided each declaration/oath sets forth all the inventors. Section 1.63(a)(3) requires that a declaration/oath, inter alia, identify each inventor and prohibits the execution of separate declarations/oaths which each sets forth only the name of the executing inventor. 62 Fed. Reg. 53,131, 53,142, October 10, 1997.

Full name of sole or first inventor

Doron Eidelman
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) [Signature]Date (x) 08/07/2001 Country of Citizenship Israel ✓Residence 22 Amon Street, 47202 Ramat Hasharon Israel ILXPost Office Address Same as above

Full name of second joint inventor, if any

David Fisch
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) _____

Date (x) _____ Country of Citizenship IsraelResidence 71940 Paduel IsraelPost Office Address Same as above

Full name of third joint inventor, if any

Amir Nov
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) _____

Date (x) _____ Country of Citizenship IsraelResidence Shikun Banim (6 Gedarot), 76854 Kfar Mordechai IsraelPost Office Address Same as above

SIGNATURE(S)

NOTE: Carefully indicate the family (or last) name, as it should appear on the filing receipt and all other document

NOTE: Each inventor must be identified by full name, including the family name, and at least one given name without abbreviation together with any other given name or initial, and by his/her residence, post office address and country of citizenship. 37 C.F.R. Section 1.63(a)(3).

NOTE: Inventors may execute separate declarations/oaths provided each declaration/oath sets forth all the inventors. Section 1.63(a)(3) requires that a declaration/oath, inter alia, identify each inventor and prohibits the execution of separate declarations/oaths which each sets forth only the name of the executing inventor. 62 Fed. Reg. 53,131, 53,142, October 10, 1997.

Full name of sole or first inventor

Doron Eidelman
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) _____

Date (x) _____ Country of Citizenship Israel

Residence 22 Amon Street, 47202 Ramat Hasharon Israel

Post Office Address Same as above

Full name of second joint inventor, if any

2-00 David Fisch
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) David Fisch

Date (x) August-9-2001 Country of Citizenship Israel

Residence 71940 Paduel Israel ILX

Post Office Address Same as above

Full name of third joint inventor, if any

3-00 Amir Noy
(Given Name) (Middle Initial or Name) Family (Or Last Name)

Inventor's signature (x) Amir Noy

Date (x) 08/08/2001 Country of Citizenship Israel

Residence Shikun Banim (6 Gedarot), 76854 Kfar Mordechai Israel ILX

Post Office Address Same as above

ADDED PAGE TO COMBINED DECLARATION AND POWER OF ATTORNEY FOR SIGNATURE BY FOURTH AND SUBSEQUENT INVENTORS

Full name of fourth joint inventor, if any

Avi
(Given Name) _____ (Middle Initial or Name) _____ Gross
Family (Or Last Name) _____

Inventor's signature (x) Avi Gross

Date (x) 2/12/2001 Country of Citizenship Israel ✓

Residence 26 Ben Yosef Street, Ramat Aviv, 69125, Israel TLX

Post Office Address Same as above

Full name of fifth joint inventor, if any

(Given Name) _____ (Middle Initial or Name) _____ Family (Or Last Name) _____

Inventor's signature _____

Date _____ **Country of Citizenship** _____

Residence _____

Post Office Address _____

Full name of sixth joint inventor, if any

(Given Name) *(Middle Initial or Name)* *Family (Or Last Name)*
Inventor's signature _____
Date _____ **Country of Citizenship** _____
Residence _____
Post Office Address _____

*(check proper box(es) for any of the following added page(s)
that form a part of this declaration)*

☒ Signature for fourth and subsequent joint inventors. *Number of pages added* 1

* * *

☐ Signature by administrator(trix), executor(trix) or legal representative for deceased or incapacitated inventor. *Number of pages added* _____

* * *

☐ Signature for inventor who refuses to sign or cannot be reached by person authorized under 37 C.F.R. Section 1.47. *Number of pages added* _____

* * *

☐ Added page for signature by one joint inventor on behalf of deceased inventor(s) where legal representative cannot be appointed in time. (37 C.F.R. Section 1.47)

* * *

☐ Added pages to combined declaration and power of attorney for divisional, continuation, or continuation-in-part (C-I-P) application.

☐ Number of pages added _____

* * *

☐ Authorization of practitioner(s) to accept and follow instructions from representative.

*(If no further pages form a part of this Declaration,
then end this Declaration with this page and check the following item)*

☐ This declaration ends with this page.

